

UG0574
User Guide
RTG4 FPGA Fabric



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1 Revision History

The revision history describes the changes that were implemented in the document. The changes are listed by revision, starting with the most current publication.

1.1 Revision 6.0

The following is a summary of changes in this revision.

- Updated the information about the SB_CORRECT and DB_DETECT flags in [LSRAM ECC](#), page 21.
- Removed the note about LSRAMs not being inferred in the ECC mode by the Synthesis tool ([RTL Inference during Synthesis](#), page 63).
- Updated the LSRAM timing diagrams, see [Figure 13](#), page 18 and [Functional Timing Waveforms](#), page 42.
- LSRAM endianness information was added, see [LSRAM](#), page 12.
- Added a note to describe the ECC behavior for uncorrectable errors, see [LSRAM ECC](#), page 21.
- Updated [Two-Port Data Width Configuration](#), page 17.
- Added all supported memory file formats for μ PROM client, see [Add Clients to System](#), page 71.

1.2 Revision 5.0

The following is a summary of changes in this revision.

- Added information about the LSRAM hold time violation after read during pipelined-ECC mode, see [LSRAM Hold Time Violation](#), page 31.
- Updated the data widths supported by LSRAM in Two-Port Mode, see [Table 11](#), page 17.
- Add [Collision Behavior](#), page 67.
- Added the x36 data flow of the two port LSRAM, see [Figure 12](#), page 16.
- Added [Debugging LSRAMs Using SmartDebug](#), page 51.
- Added [LSRAM Configurator Component Timing and Ports](#), page 34.
- Added [Simulating ECC Errors in LSRAM](#), page 47.
- Removed x36 and x9 read port and write data width support respectively from [Table 11](#), page 17 as it is not supported now. For more information, see [Customer Advisory Notice \(CAN18002.3\)](#).
- Added [Two-Port Block Select Operation](#), page 17.

1.3 Revision 4.0

The following is a summary of changes in this revision.

- When clock is at negative edge, the inversion will be absorb into the SLE with out effecting output polarity.
- During ECC pipeline mode, back to back read, write operations are not allowed.
- During accumulation, any error caused by a radiation-induced event (SEU/SET) stays in the accumulator until it is reset or purged.
- Read-before Write and Write-feed through modes are not supported.
- Updated [Figure 14](#), page 19 and [Table 14](#), page 21.
- The following register names are updated:
 - A_IN_BYPASS changed to A_ADD_BYPASS
 - B_IN_BYPASS changed to B_ADD_BYPASS

1.4 Revision 3.0

The following is a summary of changes in this revision.

- The I/O section is removed from this user guide and published as a separate user guide. See [UG0741: RTG4 FPGA I/O User Guide](#).
- Removed BUSY signal reference from [\$\mu\$ PROM](#), page 68.
- Removed LSRAM write feed-through information.
- Updated [Table 5](#), page 11 with μ PROM data bus width details.
- Updated [LSRAM ECC](#), page 21.

- Updated [Figure 94](#), page 109.
- Added [Using LSRAM in a Design](#), page 22.
- Added [Using \$\mu\$ SRAM in a Design](#), page 63.
- Added [\$\mu\$ PROM Configurator](#), page 70.
- Updated [LSRAM Read Operation](#), page 18.
- Added [Use Model: LSRAM Write-Feed-Through using Fabric Logic](#), page 49.
- Updated Read Enable information in [RTG4 Dual-Port LSRAM Configurator](#), page 23.
- Removed RT4G075 device reference from the document.

1.5 Revision 2.0

The following is a summary of changes in this revision.

- Updated the document with FTC inputs.
- Updated Features section and Table 5-3.
- Updated [\$\mu\$ SRAM ECC](#), page 62.
- Updated Table 6-3.
- Updated Table 6-10.
- Updated Low Voltage CMOS (LVCMOS) section.
- Added Cold Sparing and Dedicated Global I/Os sections.
- Updated Programmable Slew Rate Control section.
- Added [\$\mu\$ PROM](#), page 68.
- Replaced GSR_N signal with ARST_N.

1.6 Revision 1.0

The first publication of this document.

2 Fabric Overview

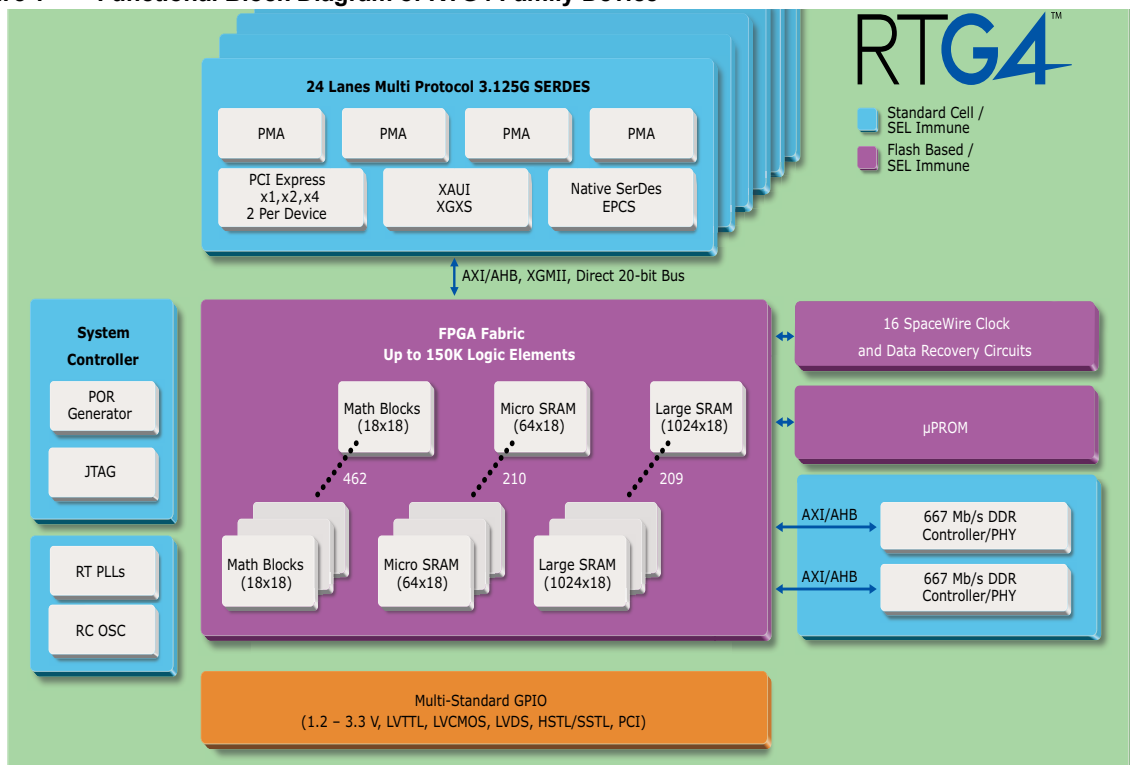
RTG4™ FPGAs feature a fourth-generation FPGA fabric with radiation tolerance. Fabric is the programmable logic section of the RTG4 FPGA, which the user configures with VHDL or Verilog. The RTG4 FPGA fabric consists of the following resources:

- **Logic element:** These are basic building blocks in the RTG4 FPGA.
- **Embedded memory blocks:** These include large SRAM (LSRAM), microSRAM (μSRAM), and microPROM (μPROM).
- **Math blocks:** These have a built-in multiplier and adder.

The Libero® System-on-Chip (SoC) software (or third-party synthesis tools) automatically infers these logic elements, embedded memories, and math blocks from the user's register transfer level (RTL) code. For more information about the Libero SoC Classic and Enhanced Constraint design flow, see the [Libero SoC Classic Constraint Flow User Guide](#) and [Libero SoC for Enhanced Constraint Flow \(ECF\) User Guide](#).

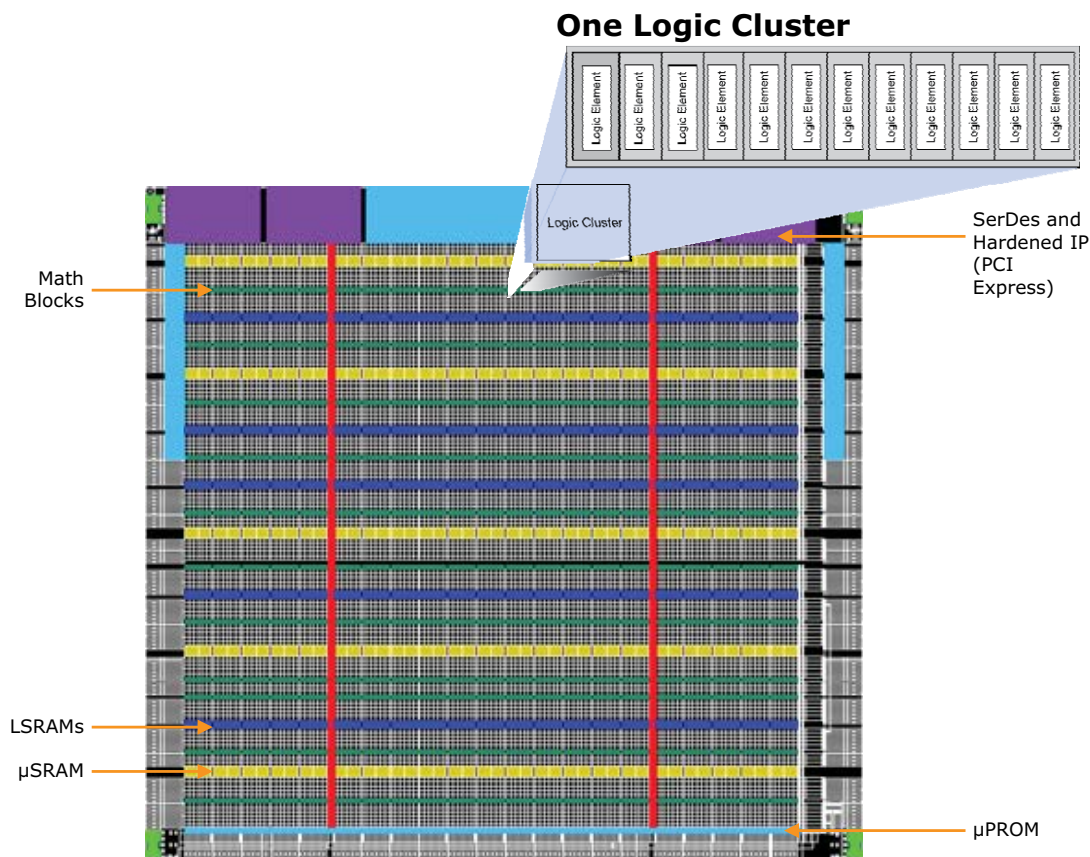
The following figure is a top-level functional block diagram of the RTG4 FPGA family. The highlighted fabric block is described in this document.

Figure 1 • Functional Block Diagram of RTG4 Family Device



The following figure shows the fabric layout. The FPGA logic resources are displayed as logic clusters (LC). Each LC consists of 12 logic elements (LE). The embedded memory blocks and math blocks are arranged in rows.

Figure 2 • Fabric Layout



The following table lists the available fabric resources in the RTG4 family devices.

Table 1 • Fabric Resources for RTG4 FPGA Devices¹

Resources	RT4G150
Logic elements	120,108
Interface logic	31,716
Total logic elements	151,824
LSRAM blocks (24.5-Kb each)	209
Total LSRAM bits (Mb)	5
μSRAM blocks (1.5-Kb each)	210
Total μSRAM bits (Kb)	315
Total RAM (Mb)	5.3
Math blocks (18 × 18 MACC)	462
μPROM (Bits)	374,400

1. 1 Kb = 1024 bits, 1 Mb = 1024 Kb.

3 Logic Elements and Routing

The RTG4 FPGA fabric has an array of logic elements grouped in clusters connected via hierarchical routing structures. These clusters are arranged in rows and are used to implement sequential and combinational logic. The following table lists the available logic elements in RTG4 devices.

Table 2 • Number of Logic Elements

Devices	RT4G150
Logic elements	120,108
Interface logic ¹	31,716
Total logic elements	151,824

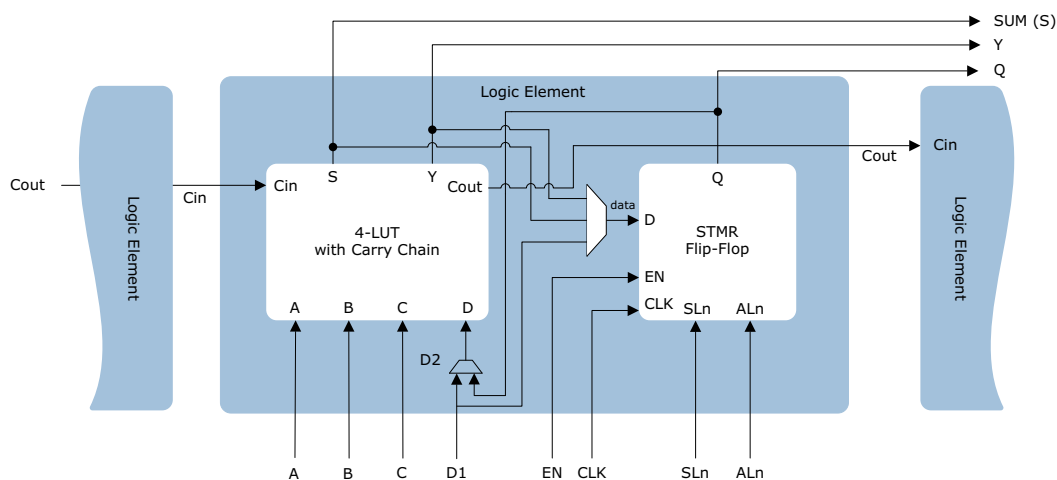
1. See [Interface Logic](#), page 7 for more information.

3.1 Logic Element

The logic element (LE) is the basic building block of the RTG4 FPGA. The logic element is fracturable – the LUT can be independently used without flip-flop or flip-flop can be used without LUT. The logic element consists of:

- 4-LUT with carry chain
- STMR-D flip-flop

Figure 3 • Functional Block Diagram of Logic Element



3.1.1 4-Input LUT with Carry Chain

The 4-input LUT with carry chain can be configured to implement any 4-input combinational logical function or arithmetic function. The 4-input LUT generates the output (Y) depending on the four inputs—A, B, C, and D. The carry chain is implemented using a 3-bit carry-look-ahead circuit. This circuit is connected between various logic elements by carry chain input (Cin) signal and carry chain output (Cout) signal. When the LUT is used to implement arithmetic functions, the carry chain input (Cin) is used with LUT output to generate the sum (S) output. However, for non-arithmetic functions, the sum (S) output can still be used as an output along with the other output (Y).

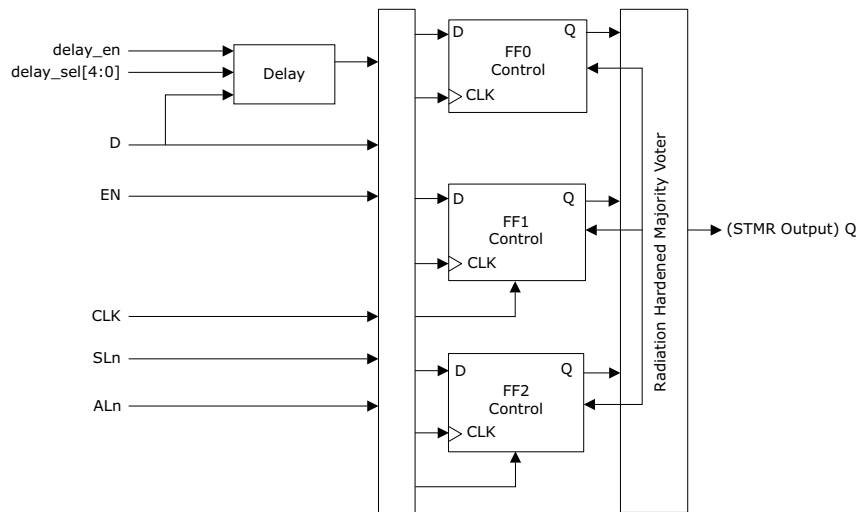
3.1.2 STMR-D Flip-Flop

Each logic element has a Single-event Transient (SET)-mitigated asynchronous Self-corrected Triple Module Redundancy (STMR)-D flip-flop, which can be used as a sequential logic element. The STMR-D flip-flop can be configured as a register. The following figure shows the functional block diagram of STMR-D flip-flop. Each STMR-D flip-flop has Asynchronous majority voter logic that ensures Single-event Upset (SEU) immunity within the timeline of an SET pulse width. Its TMR mitigates the SEU errors.

The STMR-D flip-flop has the following ports:

- Asynchronous load (ALn)
- Synchronous load (SLn)
- Data input (D)
- Enable (EN)
- Clock input (CLK)
- Data Output (Q)
- delay_en
- delay_sel[4:0]

Figure 4 • Functional Block Diagram of STMR-D Flip-Flop



ALn can be used as single global asynchronous set or reset signal of each fabric STMR-D flip-flops. It sets or resets the register depending on configuration. SLn can be used as synchronous set or reset signal of each fabric STMR-D flip-flop. It sets or resets the register depending on configuration. The data input (D) of the STMR-D flip-flop can be provided from the direct input or from the outputs of the 4-input LUT inside the logic element. When the design uses falling edge clocking, the Libero SoC Compile step optimizes the design netlist using a technique called "bubble pushing". As a result a discrete inverter instance can be removed from the netlist and the inversion property is pushed onto the CLK input pin of the SLE macro. D has a programmable delay circuit to derive a delayed data for SET mitigation. This delay circuit can be enabled or disabled using the delay_en signal. The delay_sel[4:0] signal decides the delay value for maximum SET glitch width, which can be filtered out. The radiation majority voter logic outputs the final output (Q) from the three flip-flops.

STMR-D flip-flops support Mitigated SET and Non-mitigated SET modes. These modes can be set by using the Libero SoC tool. For more information about how to set mitigation modes, see the [Libero SoC Classic Constraint Flow User Guide](#) and [Libero SoC for Enhanced Constraint Flow \(ECF\) User Guide](#). Non-mitigated timing mode is significantly faster than the mitigated timing mode. Setting the fabric flip-flops in critical timing paths to Non-mitigated mode improves the application speed significantly and reduces the radiation tolerance nominally.

3.1.3 Interface Logic

The RTG4 embedded hard IP blocks (LSRAM, μ SRAM, and math blocks) are connected to the fabric through interface logic (ILs). This interface logic element is structurally similar to a logic element with 4-input LUT, STMR-D flip-flop, and without a dedicated carry chain. Interface logic elements are also TMR-D and have same SET mitigation as Logic Elements. Each embedded hard IP block is associated with 36 interface logic elements. The following table lists the total number of ILs associated with each embedded hard IP block.

Table 3 • ILs for Embedded Hard IP Blocks

RT4G150		
Resources	Number of Blocks	Number of LEs
LSRAM	209	7,524
μ SRAM	210	7,560
Math block	462	16,632
Total interface logic	881	31,716

Figure 5 • Functional Block Diagram of Interface Logic

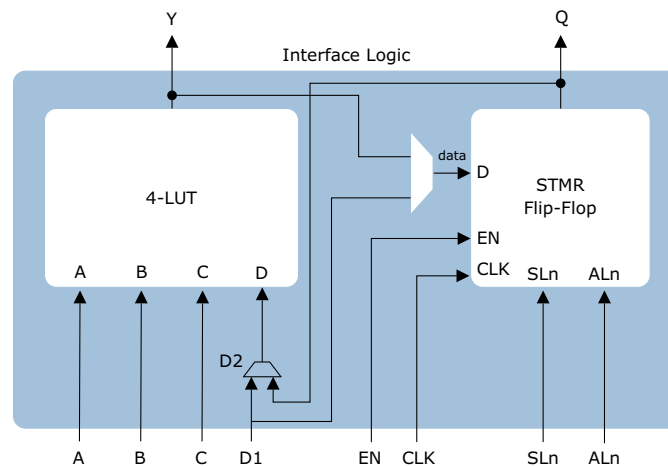
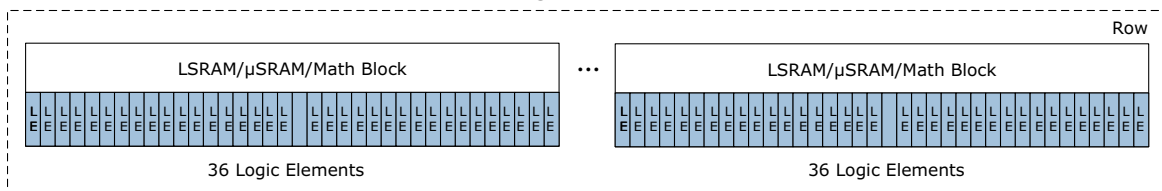


Figure 6 • LSRAM/ μ SRAM/Math Block Interfacing with ILs in a Row



If an embedded hard block is used by the target design, the interface logic element is used to connect the I/Os of the embedded hard IP block to the fabric routing. If an embedded hard IP block is not used by the design, the interface logic can be used as normal logic elements to implement combinational and sequential circuits. The preceding figure shows the interface logic connected to the embedded hard block.

3.1.4 I/O Element

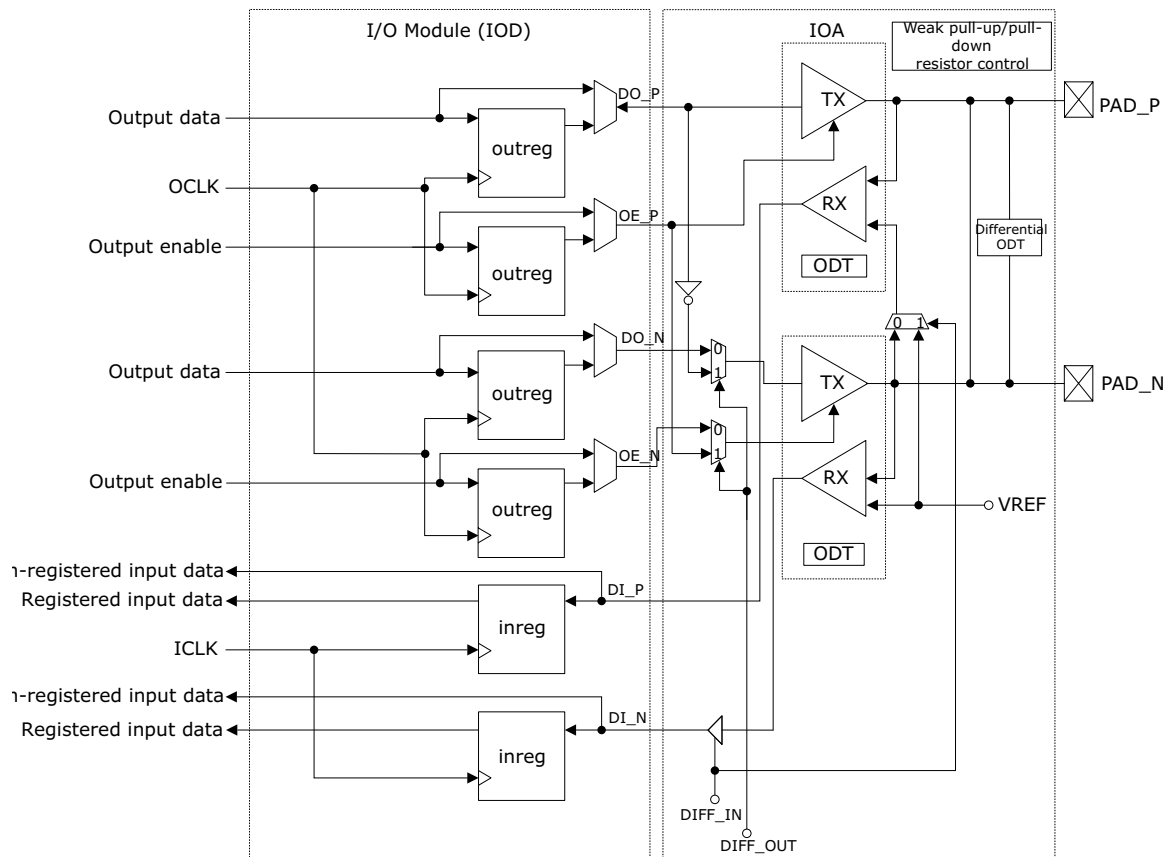
The I/O element includes the I/O Digital (IOD) circuitry and the associated routing interface. Each user I/O pad is connected to its own dedicated I/O element. The I/O element interfaces the user I/Os with the fabric routing and enables the routing of external signals coming in through the I/Os to reach all the logic elements. The I/O element also enables the internal signals to reach the I/Os.

The following figure shows the functional diagram of the complete I/O element with the IOD and I/O Analog (IOA). The IOD circuitry consists of the following:

- **Input registers:** Used to register the inputs received from the I/Os. These registers allow capturing the input signals and synchronizing them to the design clock.
- **Output registers:** Used in the I/O element for registering the output signals at I/Os for better design performance. These registers provide the registered version of the output signals to the I/Os.
- **Output Enable registers:** Act as a control signal for the output, if the I/O is configured as a tristate or bi-directional I/O.
- **Routing multiplexers (MUXes):** These routing MUXes are used to connect logic elements.

All these registers in the I/O modules are similar to the STMR-D-flip-flop available in the logic element. For a signal bus, these registers ensure that all the signal bus bits are synchronized to the clock signal when sent out through I/Os. For more information on IOA, see [UG0741: RTG4 FPGA I/Os User Guide](#).

Figure 7 • Functional Block Diagram of I/O Element

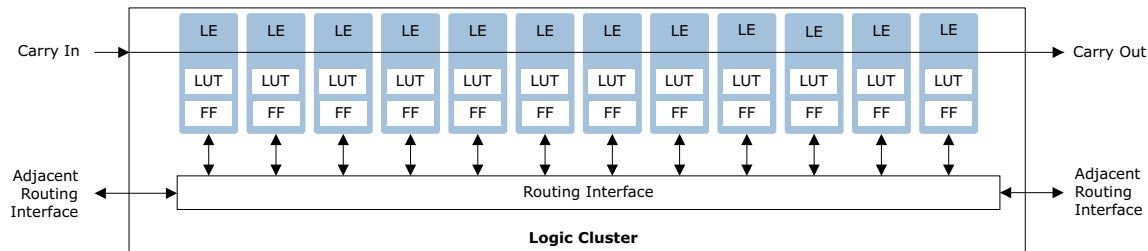


3.2 Logic Cluster

The logic elements in the RTG4 FPGA are organized in clusters. The logic cluster is a group of 12 LEs or 12 ILs. Each logic cluster is connected by a routing interface comprising MUXes and buffers. This routing interface connects to its associated LEs and the adjacent routing interfaces. Each routed signal is driven by a unique logic element output or by a routing MUX. All the logic elements are interconnected with feedback from outputs to inputs.

The following figure shows the logic cluster with routing interface.

Figure 8 • Logic Cluster



3.3 Routing Architecture

The RTG4 FPGA fabric routing architecture is a hierarchical grouping of fabric resources arranged in clusters. Each logic cluster has one routing interface that connects the LEs within a cluster and also to the routing interfaces of adjacent clusters.

The RTG4 device routing interface has two types of routings—intra cluster routing and inter cluster routing. The intra-cluster routing connects the LEs inside a cluster and inter-cluster routing connects multiple clusters. The intra-cluster routing has lower propagation delay compared to inter-cluster routing. When connecting the adjacent clusters, inter-cluster routing also has additional short routing connections for faster routing.

RTG4 FPGAs have vertical and horizontal routing stripes for global network. This global network is designed to route clocks and reset signals across the fabric with low skew, and is designed to support multiple clock domains. This global network can also be used for other high fan-out signals, such as enables and resets. See [UG0586: RTG4 FPGA Clocking Resources User Guide](#) for more information about global network.

Each 4-input LUT, D-type flip-flop, carry chain, LSRAM, μ SRAM, and math block has individual X-Y coordinates. If the user design requires manual placement of these blocks, it is possible to set region constraints using these coordinates. The coordinates are measured from the lower left (0, 0) to the top right corner (X, Y), where X, Y values vary as per the device.

For more information about using coordinates for region/placement constraints, see the [Chip Planner User's Guide](#) or Libero SoC Online Help.

The array coordinates are measured from the bottom left corner to the top right corner of the FPGA fabric. The following table provides the array coordinates of logical blocks and embedded hard blocks of the RTG4 devices. For more information about how to use array coordinates for region or placement constraints, see [Libero SoC Classic Constraint Flow User Guide](#) and [Libero SoC for Enhanced Constraint Flow \(ECF\) User Guide](#) or online help (available in the software).

Table 4 • Fabric Array Coordinate Systems

Device	Logic Elements		μ SRAM	LSRAM	Math Blocks
	Minimum (X, Y)	Maximum (X, Y)	(X, Y)	(X, Y)	(X, Y)
RT4G150	0, 0	1535, 311	(0, 56), (0, 125), (0, 182), (0, 212), (0, 266)	(0, 32), (0, 95), (0, 158), (0, 236), (0, 296)	(0, 17), (0, 41), (0, 71), (0, 80), (0, 110), (0, 140), (0, 167), (0, 197), (0, 221), (0, 251), (0, 281)

3.4 Libero Compile Report - Fabric Resources

The compile report contains fabric resource utilization and the total number of resources available. See the following figure for a sample compile report for RT4G150. This report provides the number of 4LUTs, DFFs, μ SRAMs, LSRAMs, math blocks, I/O, DLLs, PLLs, transceivers, and globals used in a design. It also contains the detail logic resource usage that contains the additional 4LUTs and DFFs required for RAMs and MACC interface logic.

Figure 9 • Sample Compile Report for RT4G150

Resource Usage

Type	Used	Total	Percentage
4LUT	8100	151824	5.34
DFF	8267	151824	5.45
I/O Register	0	2154	0.00
User I/O	43	718	5.99
-- Single-ended I/O	39	718	5.43
-- Differential I/O Pairs	2	359	0.56
RAM64x18	4	210	1.90
RAM1K18	3	209	1.44
MACC	32	462	6.93
H-Chip Globals	9	48	18.75
CCC	1	8	12.50
RCOSC_50MHZ	1	1	100.00
SERDESIF Blocks	2	6	33.33
FDDR	0	2	0.00
GRESET	1	1	100.00

4 Embedded Memory Blocks

The RTG4 FPGA fabric has the following memory blocks:

- **LSRAM:** The embedded 24-Kb SRAM blocks are arranged in multiple rows within the fabric and can be accessed through the fabric routing architecture. The LSRAMs can be operated in dual-port or two-port modes. The following table lists the number of available LSRAM blocks depending on the specific RTG4 device. LSRAM blocks are used for storing large data with Error-correcting Code (ECC) and Single-event Transient (SET) mitigation options.
- **μSRAM:** The embedded 1.5-Kb SRAM blocks are arranged in multiple rows within the fabric and can be accessed through the fabric routing architecture. The following table lists the number of available μSRAM blocks depending on the specific RTG4 device. Embedded μSRAM blocks are used for storing small data with ECC and SET mitigation options.
- **μPROM:** The embedded non-volatile PROM is arranged in a single row at the bottom of the fabric and is read only through the fabric interface. The μPROM can be loaded only during device programming.

The following table lists the LSRAM, μSRAM, and μPROM features.

Table 5 • RTG4 LSRAM, μSRAM, and μPROM Features

Feature	LSRAM	μSRAM	μPROM
Memory size	24,576 bits/block	1,536 bits/block	374,400 bits (total memory size)
Data bus width	512 × 36, 1K × 18, 2K × 12, 2K × 9 ¹	64 × 18, 128 × 12, 128 × 9 ²	16K × 36
Number of ports	2 read/write ports in dual port mode	2 read ports, 1 write port	1 read port
Memory modes	True dual-port ³ and two-port	Three-port	Single-port
Read operation	Synchronous	Synchronous/Asynchronous	Synchronous
Write operation	Simple write	Simple write	Only during device programming
ECC	Available for ×18 data widths in dual-port mode and for ×18, ×36 data widths in two-port mode.	Available for ×18 data widths	

1. Only the ×12 port width accesses the entire address space of the 24,576 bits. The ×9, ×18, and ×36 address space is limited to 18,432 bits.
2. Only the ×12 port width accesses the entire address space of the 1536 bits. The ×9 and ×18 address space is limited to 1152 bits.
3. True dual-port is not available for 2K × 12 and 2K × 9.

Note: In specific configurations, x9 and x12 dual-port LSRAMs undergo compile transformations by Libero SoC. See, [Customer Advisory Notice \(CAN\) 18002.3](#). Compile transformations occur when opening a design created by an older version of Libero or when compiling a design that contains manually instantiated LSRAM primitive macros.

The following table lists the embedded memory resources available in RTG4 devices.

Table 6 • RTG4 Embedded Memory Resources

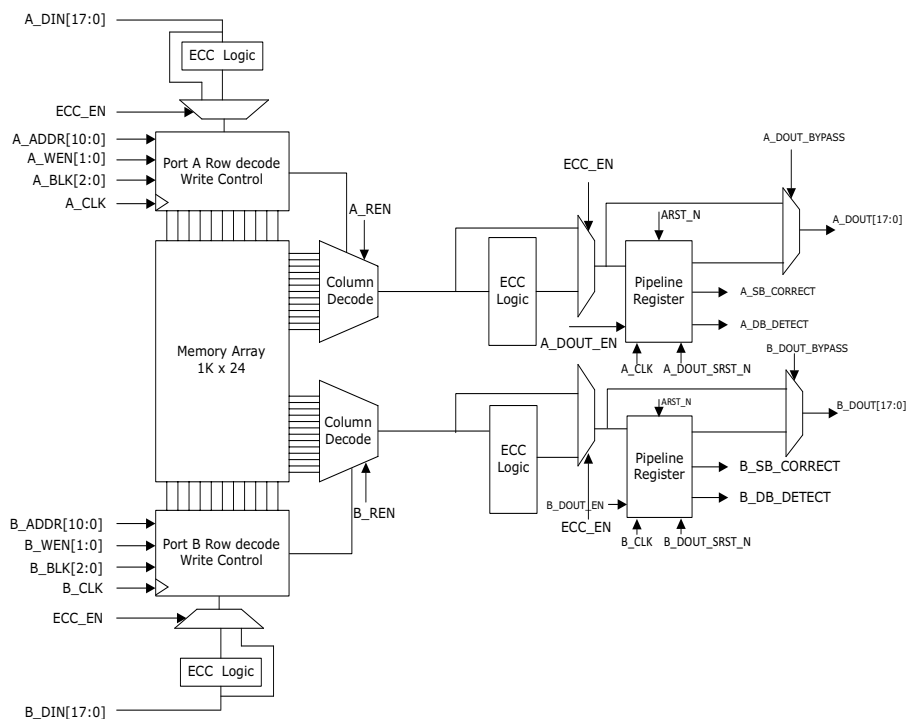
Resources	RT4G150
24.5-Kb LSRAM blocks	209
LSRAM (Mb) ¹	5
μSRAM blocks (1.5-Kb each)	210
μSRAM (Kb) ¹	315
Total RAM (Mb) ¹	5.3
μPROM (Bits)	374,400

1. 1 Kb = 1024 bits, 1 Mb = 1024 Kb.

4.1 LSRAM

Each LSRAM has two independent ports—port A and port B, as shown in the following figure. Both these ports support write and read operations and can be configured in dual-port mode or two-port mode depending on the data width and access pattern requirement. LSRAMs follow the little-endian system.

Figure 10 • Functional Block Diagram of LSRAM



The following table lists the port list for LSRAM.

Table 7 • Port List for LSRAM

Port Name	Direction	Type ¹	Polarity	Description
Port A				
A_ADDR[10:0]	Input	Dynamic		Port A address
A_BLK[2:0]	Input	Dynamic	Active high	Port A block selects
A_CLK	Input	Dynamic	Rising edge	Port A clock
A_DIN[17:0]	Input	Dynamic		Port A write-data
A_DOUT[17:0]	Output	Dynamic		Port A read-data
A_WEN[1:0] ²	Input	Dynamic	Active high	Port A write-enables (per byte)
A_REN	Input	Dynamic	Active high	Port A read-enable
A_WIDTH[1:0]	Input	Static		Port A width/depth mode select
A_WMODE[1:0]	Input	Static	Active high	Port A write mode select. Must be 2'b00.
A_DOUT_BYPASS	Input	Static	Active low	Port A output pipeline bypass mode
A_DOUT_EN	Input	Dynamic	Active high	Port A read pipeline register enable
A_DOUT_SRST_N	Input	Dynamic	Active low	Port A read pipeline synchronous-reset
A_SB_CORRECT	Output	Dynamic	Active high	Port A 1-bit error correction flag
A_DB_DETECT	Output	Dynamic	Active high	Port A 2-bit error detection flag
Port B				
B_ADDR[10:0]	Input	Dynamic		Port B address
B_BLK[2:0]	Input	Dynamic	Active high	Port B block selects
B_CLK	Input	Dynamic	Rising edge	Port B clock
B_DIN[17:0]	Input	Dynamic		Port B write-data
B_DOUT[17:0]	Output	Dynamic		Port B read-data
B_WEN[1:0] ²	Input	Dynamic	Active high	Port B write-enables (per byte)
B_REN	Input	Dynamic	Active high	Port B read-enable
B_WIDTH[1:0]	Input	Static		Port B width/depth mode select
B_WMODE[1:0]	Input	Static	Active high	Port B write mode select. Must be 2'b00.
B_DOUT_BYPASS	Input	Static	Active low	Port B pipeline register select
B_DOUT_EN	Input	Dynamic	Active high	Port B pipeline register enable
B_DOUT_SRST_N	Input	Dynamic	Active low	Port B pipeline synchronous-reset
B_SB_CORRECT	Output	Dynamic	Active high	Port B 1-bit error correction flag
B_DB_DETECT	Output	Dynamic	Active high	Port B 2-bit error detection flag
Common Signals				
ARST_N	Input	Global	Active low	Pipeline registers asynchronous-reset
ECC_EN	Input	Static	Active high	ECC enable, turns on the ECC encoders, decoders, and registers.
ECC_DOUT_BYPASS	Input	Static	Active low	ECC pipeline bypass
DELEN	Input	Static	Active high	SET mitigation
SECURITY	Input	Static	Active high	Lock access to system controller ³

Table 7 • Port List for LSRAM (continued)

Port Name	Direction	Type ¹	Polarity	Description
BUSY	Output	Dynamic	Active high	Busy signal from the system controller. This is high while system controller accessing LSRAM. ³

1. Static inputs are defined during the design time and must be tied to logic 0 or 1.
2. If the LSRAM block is configured for data width of x9 or ECC, both the bits of A_WEN and B_WEN must be tied to logic 1 and must not be dynamically changed.
3. For more information about BUSY signal from system controller, see [UG0576: RTG4 FPGA System Controller User Guide](#).

4.1.1 Dual-Port Mode

The LSRAM block can be configured as a true dual-port SRAM with independent write and read ports. Write and read operations can be performed from both the ports (A and B) independently at any location as long as there is no write collision. The LSRAM block does not have built-in write collision detection circuit. Simultaneous read and write operations from both ports to the same address location results in correct data written into the memory, but does not guarantee correct read data. Each port has a unique address, data in, data out, clock, block select, write enable, pipeline registers.

4.1.1.1 Dual-Port Data Width Configuration

In dual-port mode, both ports A and B have maximum data width of x18. Each port can be configured in multiple data widths. The configuration of one port has a corresponding configuration for the other port, as shown in the following table. A_WIDTH indicates the read width and B_WIDTH indicates the write width.

Table 8 • Data Width Configurations For Dual-port Mode

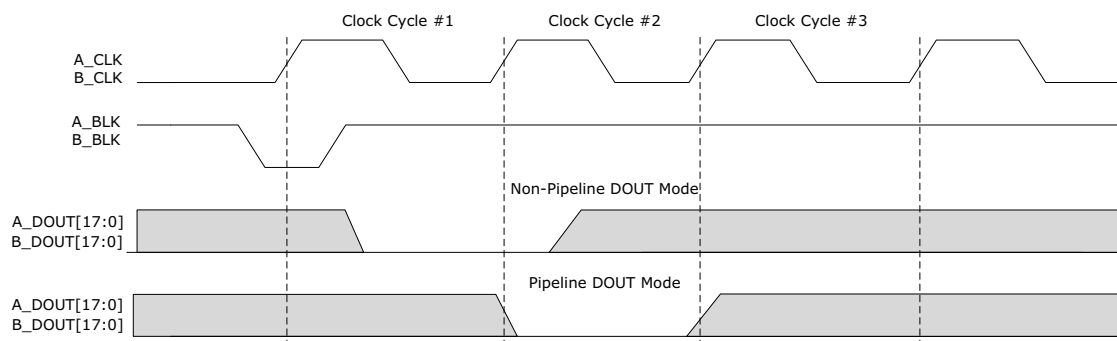
A_WIDTH	B_WIDTH
x9	x18
x18	x18

4.1.1.2 Dual-Port Block Select Operation

In dual-port mode, to perform two independent write and read operations (on port A or port B or both) the block select signal is required. The following table lists the block select operation for port A and port B. When the pipeline registers are enabled, the effect of the block select at the outputs is delayed by one clock cycle, see [Figure 11](#).

Table 9 • Block Select Operation

A_BLK[2:0]	B_BLK[2:0]	Operation
Any one bit = 0	Any one bit = 0	No operation on port A or B. The data output A_DOUT[17:0] and B_DOUT[17:0] will be forced zero.
Any one bit = 0	111	Read or write operation on port B. A_DOUT[17:0] will be forced zero.
111	Any one bit = 0	Read or write operation on port A. B_DOUT[17:0] will be forced zero.
111	111	Read or write operation on both ports A and B.

Figure 11 • Block Select Inputs for Dual-Port Mode

4.1.1.3 Dual-Port Byte Write Enables

The byte write enables (A_WEN[1:0] and B_WEN[1:0]) enable writing individual bytes of data (9 MSB or 9 LSB) for the $\times 18$ width. The byte write enables for port A (A_WEN[1:0]) enable A_DIN[17:9] and A_DIN[8:0] respectively. The byte write enables for port B (B_WEN[1:0]) enable B_DIN[17:9] and B_DIN[8:0] respectively. Writing one byte at a time to the LSRAM is not compatible with the built-in ECC logic, as per [Table 14](#), page 21. The complete data word must be written by setting both WEN bits high when using the built-in LSRAM ECC.

If all byte write enables are low, then port A or port B is considered to be in read mode and any read operations are controlled by the read enables (A_REN and B_REN).

The following table lists the byte write enable settings for port A and port B.

Table 10 • Dual-Port Byte Write Enables Settings

Depth x Width	A_WEN / B_WEN	Result
2K \times 9, 1K \times 18	00	Perform a read operation
2K \times 9	11	Perform a write operation
1K \times 18	01	Write [8:0]
	10	Write [17:9]
	11	Write [17:0]

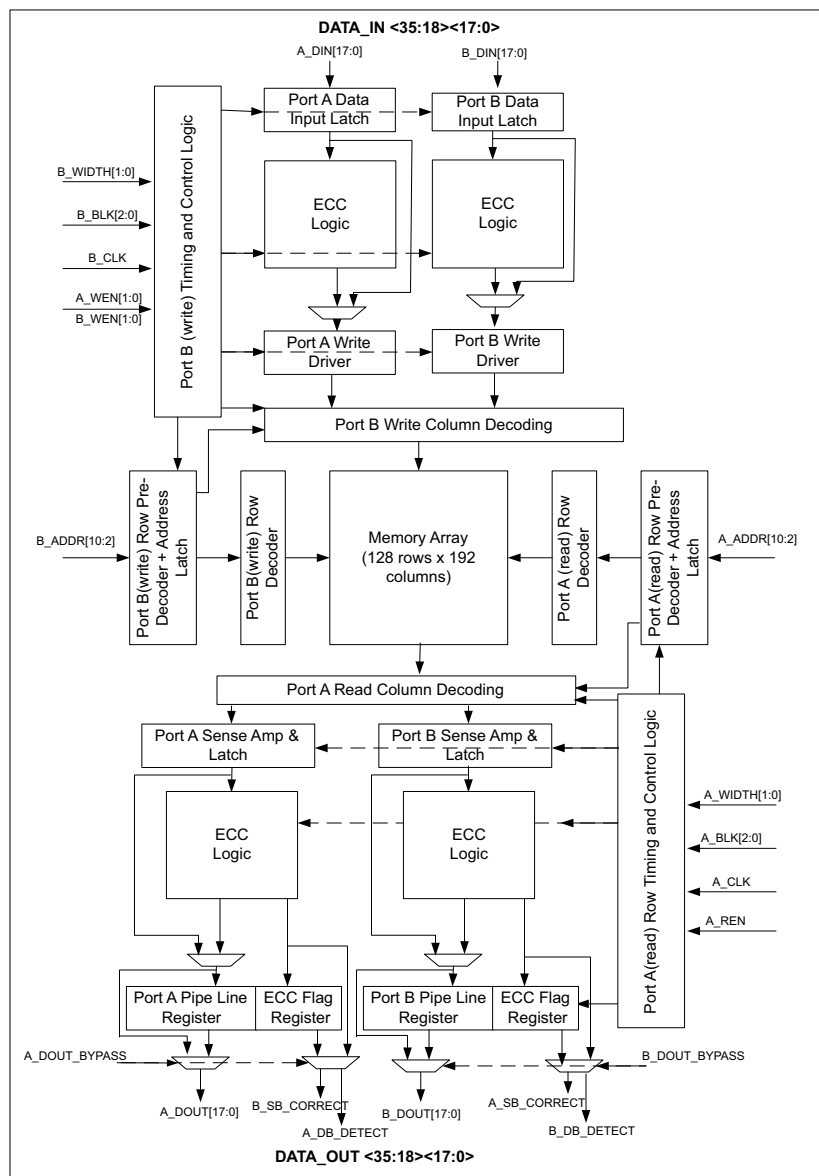
4.1.1.4 Dual-Port Read Enable

The read enable signals, A_REN and B_REN, perform the read operation on port A and port B, unless any one bit of that port's block select is low which forces the data outputs to low. When read enable is low, the data outputs retain their previous state and no dynamic read power is consumed on that port. When read enable is high, LSRAM performs read operation and consumes read power.

4.1.2 Two-Port Mode

The LSRAM block can be configured as a two-port SRAM with port A dedicated to read operations and port B dedicated to write operations. For data widths greater than $\times 18$, the read port borrows the port B data output signals, similarly write port borrows the port A data input signals.

[Figure 12](#) illustrates the two-port LSRAM data-flow in the $\times 36$ data width configuration.

Figure 12 • Two Port Mode x36 Data Flow

4.1.2.1 Two-Port Data Width Configuration

In two-port mode, the maximum data width is $\times 36$. Each port can be configured in multiple data widths. The configuration of read port has a corresponding configuration for the write port, as shown in the following table.

Table 11 • Data Width Configurations for Two-Port Mode

Read Port	Write Port
$\times 9$	$\times 9, \times 18, \times 36$
$\times 12$	$\times 12$
$\times 18$	$\times 9, \times 18, \times 36$
$\times 36$	$\times 18, \times 36$

Note: Libero SoC performs compile transformations on two-port LSRAMs configured for $\times 9$ and $\times 12$ write widths where the writes occur on port B. For more information, see [Customer Advisory Notice \(CAN18002.3\)](#). These configurations will have the read and write ports swapped so that writes occur on port A instead of port B.

4.1.2.2 Two-Port Block Select Operation

In the two-port mode Port A is the read port and Port B is the write port. [Table 12](#), page 17 lists the Block select values required to enable the read and write operation on Port A and Port B respectively.

Table 12 • Block Select Operation in Two-Port Mode

A_BLK[2:0] Setting	Read Operation	B_BLK[2:0] Setting	Write Operation
A_BLK[2:0]=111	Read operation from Port A.	B_BLK[2:0]=111	Write operation at the Port B.
Any bit of A_BLK[2:0] is 0	No read operation from Port A. The data outputs A_DOUT[17:0] and B_DOUT[17:0] are forced to zero.	Any bit of B_BLK[2:0] is 0	No write operation at the Port B.

4.1.2.3 Two-Port Byte Write Enables

The byte write enables (A_WEN and B_WEN) enable writing individual bytes of data (9 MSB or 9 LSB) for $\times 9$ width, $\times 18$, and $\times 36$ data widths. For $\times 36$ write-width, the byte write enables for the corresponding data is used to enable each of the four bytes, that is, byte write enables for port A enable A_DIN[17:9] and A_DIN[8:0] and byte write enables for port B enable B_DIN[17:9] and B_DIN[8:0]. Writing one byte at a time to the LSRAM is not compatible with the built-in ECC logic, as per [Table 14](#), page 21. The complete data word must be written by setting all WEN bits high when using the built-in LSRAM ECC.

The following table lists the byte write enable settings for port A and port B.

Table 13 • Two-Port Byte Write Enables For $\times 36$ Write Width

Depth x Width	A_WEN/B_WEN	Result
512 \times 36	B_WEN[0] = 1	Write B_DIN[8:0]
	B_WEN[1] = 1	Write B_DIN[17:9]
	A_WEN[0] = 1	Write A_DIN[8:0]
	A_WEN[1] = 1	Write A_DIN[17:9]

4.1.2.4 Two-Port Read Enable

The read enable signals, A_REN and B_REN, perform the read operation on port A and port B, unless any one bit of A_BLK is low which forces the data outputs to low. When read enable is low, the data outputs retain their previous state and no dynamic read power is consumed on that port. When read

enable is high, LSRAM performs read operation and consumes read power. When read width is x36, LSRAM port B read enable (B_REN) is tied to port A read enable (A_REN).

4.1.3 LSRAM Read Operation

LSRAM supports both pipelined and non-pipelined read operations. In pipelined read operation, the output data is registered at the pipeline registers; hence, the data is available on the corresponding data output on the next clock cycle. Figure 13 shows the pipelined and non-pipelined read timing.

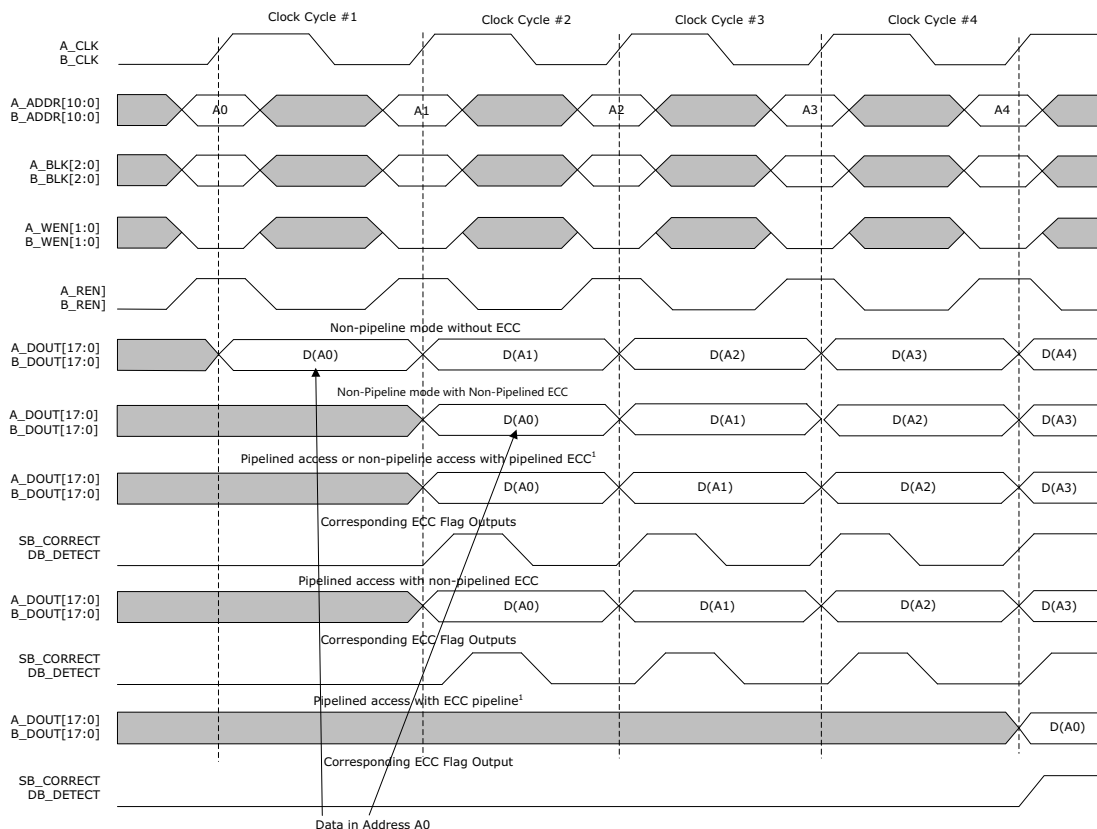
In non-pipelined read operation, the pipeline registers are bypassed with data available on the corresponding output in the same clock cycle. During this operation, LSRAM can generate glitches on the data output buses. Therefore, it is recommended to use LSRAM with pipeline registers to avoid glitches.

Note: Enable pipeline mode to achieve high performance. This will pipeline the output data bus before the data bus is delivered to the FPGA fabric.

Note: When using non-pipelined ECC mode, the SET filter must be enabled per the [Product Change Notification \(PCN 18009.1\)](#). If this filter is not enabled by the user, Libero SoC (v11.9 and above) automatically turns on SET mitigation for non-pipelined ECC LSRAMs.

Figure 13 shows both pipelined and non-pipelined read operations.

Figure 13 • LSRAM Read Operation



1. For cases where pipelined ECC mode is used, the first write cycle is used by the ECC encoder and the second clock cycle is used when the LSRAM memory array is actually written. Therefore, it is not legal to perform a write immediately followed by a read to the same address on the next clock cycle, because the LSRAM is being written with the newly encoded data. When pipelined ECC mode is used, after issuing a write to a given LSRAM address, a subsequent read to that address must wait until two clock cycles later to ensure the correct data is being read. Once the read command is issued, pipelined ECC mode requires one clock cycle to decode the data from LSRAM before it is presented on the data output port.

4.1.4 LSRAM Write Operation

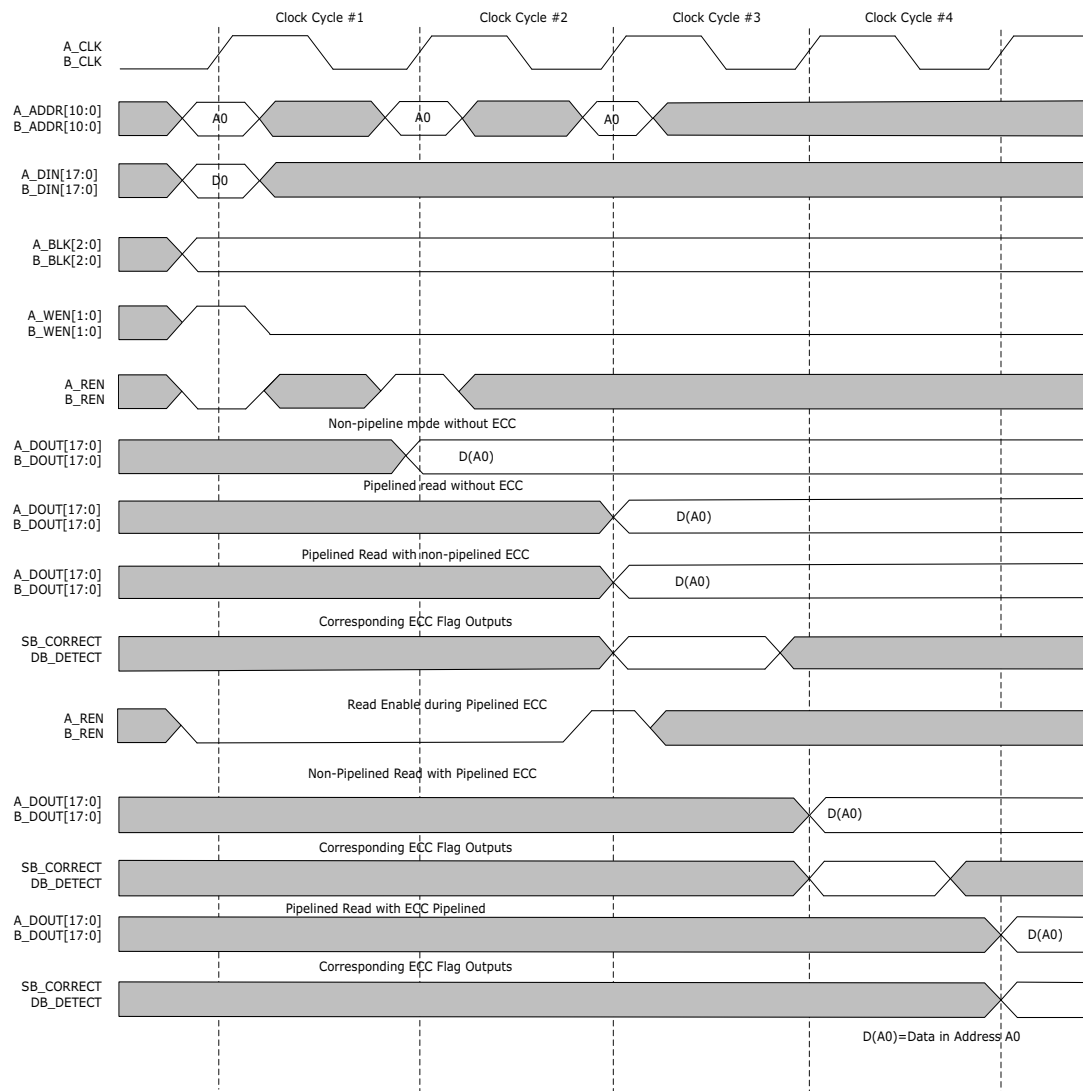
LSRAM supports Simple write operations:

In a simple-write operation, data input A_DIN and B_DIN are written to the corresponding address locations A_ADDR and B_ADDR. The data written to the memory is available at the output only after performing a read operation.

Note: Simultaneous write operations from both ports to the same address location are not prevented. Since simultaneous write operations can result in data uncertainty, it is recommended to use external logic in the fabric to avoid collisions.

The following figure shows the timing for write operations followed by the corresponding read to the same address, at the earliest possible time.

Figure 14 • LSRAM Write Operation— Followed by Earliest Read

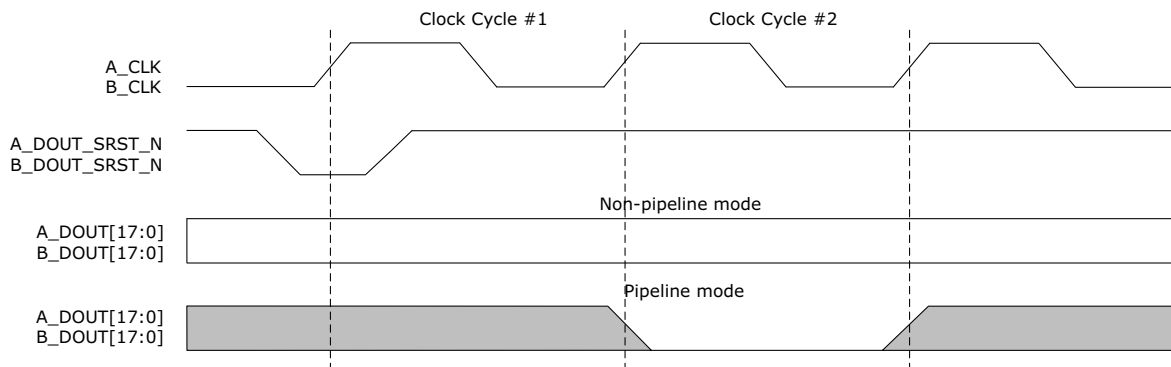


1. For cases where pipelined ECC mode is used, the first write cycle is used by the ECC encoder and the second clock cycle is used when the LSRAM memory array is actually written. Therefore, it is not legal to perform a write immediately followed by a read to the same address on the next clock cycle, because LSRAM is being written with the newly encoded data. When using pipelined ECC mode, after issuing a write to a given LSRAM address, a subsequent read to that address must wait until two clock cycles later to ensure the correct data is being read. Once the read command is issued, pipelined ECC mode requires one clock cycle to decode the data from LSRAM before it is presented on the data output port.

4.1.5 Pipelined Read Synchronous Reset Operation

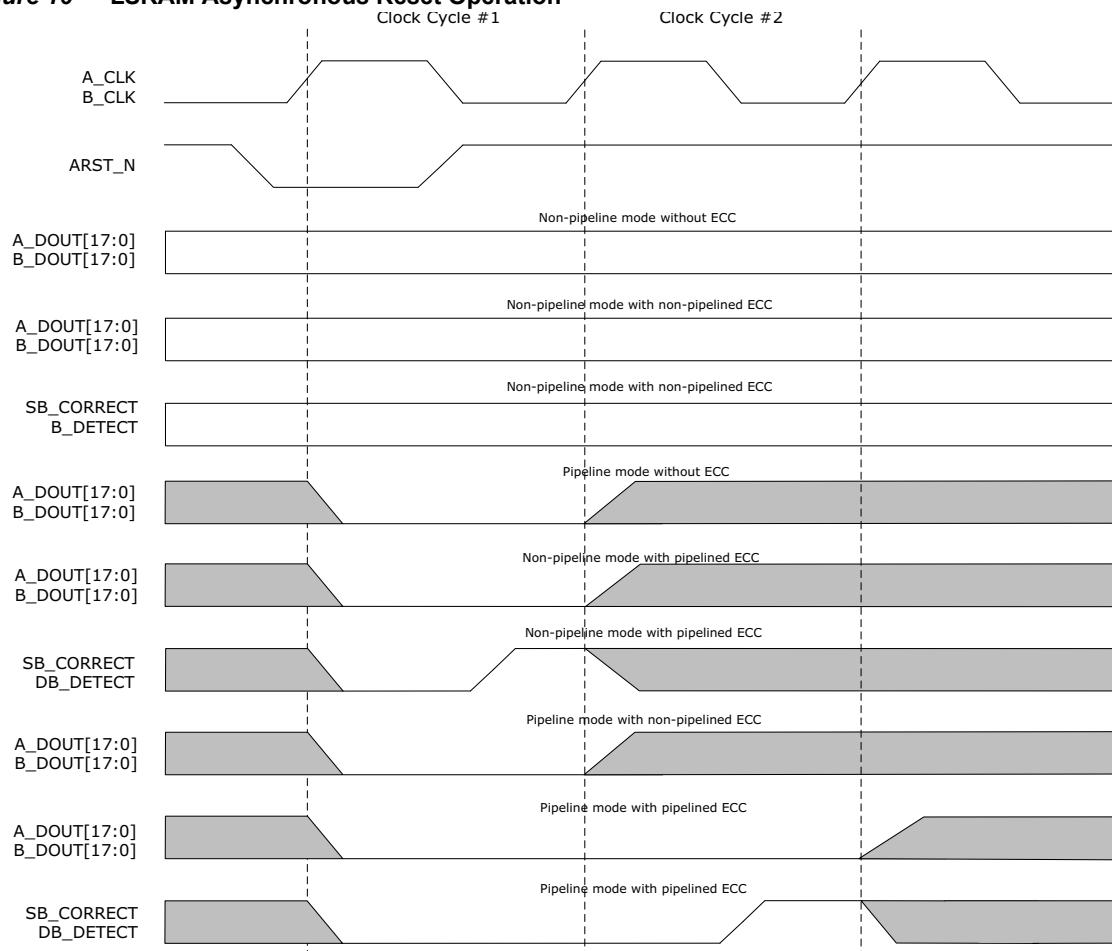
Each port's pipeline registers have a synchronous reset. A_DOUT_SRST_N and B_DOUT_SRST_N drive the synchronous reset of the data output pipeline registers: A_DOUT and B_DOUT. If the synchronous reset is low, the pipeline data output registers are reset to zero on the next valid clock edge, as shown in the following figure.

Figure 15 • LSRAM Synchronous Reset Operation



4.1.6 Pipelined Read Asynchronous Reset Operation

Each LSRAM has an asynchronous reset (ARST_N), which connects the read-data pipeline registers to the global asynchronous-reset signal. If the asynchronous reset is driven low, the pipeline data registers are immediately reset to zero as shown in the following figure.

Figure 16 • LSRAM Asynchronous Reset Operation

4.1.7 LSRAM ECC

The LSRAM block has ECC logic circuitry (1-bit error correction, 2 bits error detection) for the $\times 18$ and $\times 36$ modes; but not for the $\times 9$ and $\times 12$ modes. The error correction code (ECC) encoder provides 24 bits of data for $\times 18$ mode or 48 bits of data for $\times 36$ mode. The ECC decoder reads the same amount of bits (24 or 48) from the array and provides the expected number of corrected bits (18 or 36) on the outputs. The ECC encoder contains an optional pipeline register which is enabled during pipelined ECC mode. The ECC encoder pipeline register delays the actual data write to the LSRAM by 1 clock cycle.

Table 14 • ECC Available Mode

Port Widths A/B	Write Enables (byte write)	Output Pipeline	Pipeline Bypass
$\times 9/\times 9$	No ECC	No ECC	No ECC
$\times 9/\times 18$	No ECC	No ECC	No ECC
$\times 9/\times 36$	No ECC	No ECC	No ECC
$\times 12/\times 12$	No ECC	No ECC	No ECC
$\times 18/\times 9$	No ECC	No ECC	No ECC
$\times 18/\times 18$	No ECC	ECC available	ECC available
$\times 18/\times 36$	No ECC	ECC available	ECC available
$\times 36/\times 9$	No ECC	No ECC	No ECC

Table 14 • ECC Available Mode (continued)

Port Widths A/B	Write Enables (byte write)	Output Pipeline	Pipeline Bypass
×36/×18	No ECC	ECC available	ECC available
×36/×36	No ECC	ECC available	ECC available

For cases where pipelined ECC mode is used, the ECC encoder, used during writes, and the ECC decoder, used during reads, will each add a clock cycle to the memory operations. During a write to a pipelined ECC LSRAM, the first write cycle is used by the ECC encoder and the second clock cycle is where the LSRAM memory array is actually written. Therefore, it is not legal to perform a write immediately followed by a read to the same address on the next clock cycle, because that is the same cycle where the LSRAM is being written with the newly encoded data. When using pipelined ECC mode, after issuing a write to a given LSRAM address, a subsequent read to that address must wait at least two clock cycles to ensure the correct data is being read. Once the read command is issued, pipelined ECC mode requires one clock cycle to decode the data from LSRAM before it is presented on the data output port. The following are the possible scenarios, since the output data can also be pipelined.

- Pipeline mode with non-pipelined ECC
- Pipeline mode with pipelined ECC
- Non-pipeline mode with non-pipelined ECC
- Non-pipeline mode with pipelined ECC

The timing diagrams for the above possible scenarios are shown in [Figure 14](#).

The ECC logic generates two flags:

- **SB_CORRECT**: Asserted when a single-bit error is detected. If **SB_CORRECT** is set without the dual-bit error flag being asserted, the corrupted bit is corrected in read data output. Even though the corrupted bit is corrected in the read data output, the data in the RAM location is not corrected. The user logic must correct the contents of the RAM.
- **DB_DETECT**: Asserted when a dual-bit error is detected, but not corrected. Multi-bit errors (more than two bits) produce unknown results on the flags and data outputs. If **DB_DETECT** is set, correction is not performed on read data output. Correction must be performed by user logic.

In pipeline mode, these flags are valid only in read data output clock cycle. In non-pipeline mode, the ECC flags are valid only in the same clock cycle as the corresponding read data output, because they are reset in the next clock cycle.

The following table lists the ECC errors and corresponding flag status.

Table 15 • LSRAM Error Flag Status

ECC Errors	SB_CORRECT	DB_DETECT
No error	0	0
Single-bit error	1	0
Double-bit error	1	1

During an x36 read with LSRAM ECC enabled, all the A and B port ECC flags are used to represent the ECC status for the complete x36 read data out word.

Note: The ECC decoder generates two flags (**DB_DETECT** and **SB_CORRECT**). If a single-bit error occurs in a 24-bit word (18 data bits and 6 ECC bits), the error correction flag (**SB_CORRECT**) is set high and the 18-bit data is corrected. If two or multiple-bit errors occur in the 24-bit word, **DB_DETECT** and **SB_CORRECT** flags are set high and the 18-bit data from the LSRAM is not corrected or modified. If multiple-bit errors occur in the 6 ECC bits, both ECC flags are asserted and no correction is performed on the 18-bit data.

4.1.8 Using LSRAM in a Design

An LSRAM block can be implemented in a design by the following methods:

- RTL Inference during Synthesis
- Inserting an LSRAM Configurator Component

4.1.8.1 RTL Inference during Synthesis

Synplify Pro can infer an LSRAM and automatically set the configuration for various modes, if the RTL design contains an array of at least 12 bits. Synplify also supports inferring memories according to the user attribute `syn_ramstyle`. Synthesis ensures that the signals of the LSRAM are properly connected to the rest of the design and sets the correct values for the static signals required to configure the appropriate operational mode. The tool ties unused dynamic input signals to low.

Note:

Synplify Pro can cascade multiple LSRAM blocks if the required memory size exceeds the limit of a single LSRAM block. It can also absorb any registers at the LSRAM interface if they are driven by the same clock. If the registers have different clocks, then the clock that drives the output register has priority, and all registers driven by that clock are absorbed into the LSRAM block. If the outputs are unregistered and the inputs are registered with different clocks, the input registers with the larger input have priority and are absorbed into the LSRAM block. For more information about LSRAM inference by Synplify Pro, see [Inferring Microsemi RTG4 RAM Blocks Application Note](#).

4.1.8.2 Inserting an LSRAM Configurator Component

The Libero SoC software catalog provides separate configuration tools for dual-port and two-port modes. Using these configurators, the user can configure LSRAM in the required operating modes. These configuration tools generate the HDL wrapper files for LSRAM with the appropriate values assigned to the static signals. The generated HDL wrapper files can be used in the design hierarchy by connecting the ports to the rest of the design.

4.1.8.2.1 RTG4 Dual-Port LSRAM Configurator

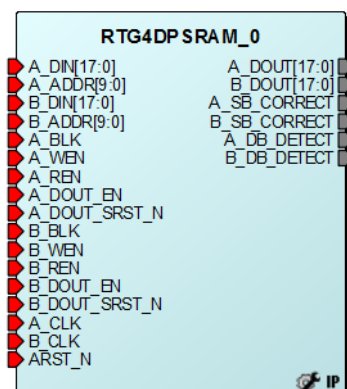
The RTG4 DPSRAM configurator is available in the Libero SoC IP catalog under **Memory & Controllers**, see [Figure 17](#). The RTG4 DPSRAM IP configurator enables write and read access on both ports: port A and port B.

The DPSRAM configurator automatically cascades LSRAM blocks to create wider and deeper memories by selecting the most efficient aspect ratio. It also handles the grounding of unused bits. The core configurator supports the generation of memories that have different aspect ratios on each port. The configurator uses one or more memory blocks to generate a RAM component to match the configuration. The configurator also creates the external logic required for the cascading.

The configurator cascades RAM blocks in three different methods:

- Cascaded deep. For example, two blocks of 1024x18 to create a 2048x18.
- Cascaded wide. For example, two blocks of 1024x18 to create a 1024x36.
- Cascaded wide and deep. For example, four blocks of 1024x18 to create a 2048x36, in two blocks width-wise by two blocks depth-wise configuration.

Dual-port LSRAM is synchronous for memory write and read operations, setting up the addresses, and writing and reading the data. The memory write and read operations will be triggered at the rising edge of the clock. Optional pipeline registers are available at both read data ports to improve the clock-to-output delay.

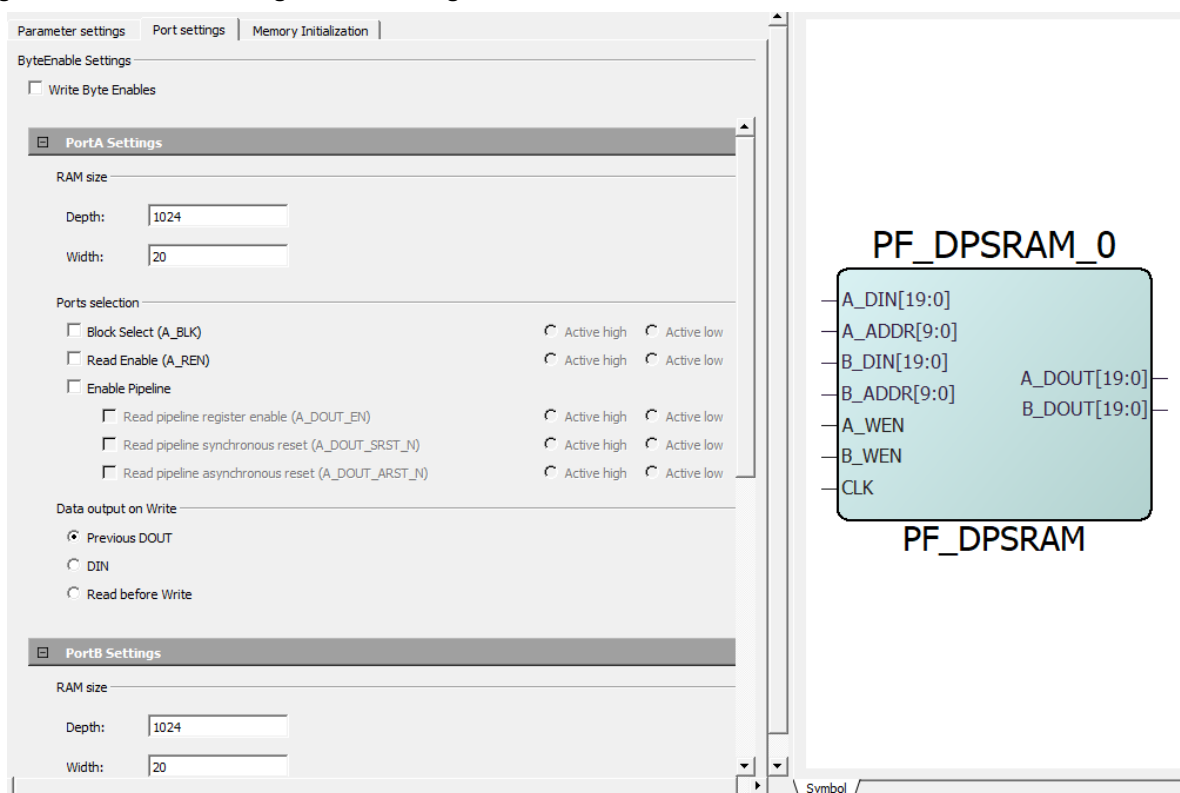
Figure 17 • LSRAM Ports Configured as Dual-Port SRAM - DPSRAM Macro in Libero SoC**Table 16 • Port List for the DPSRAM Configurator**

Port Name	Direction	Description
Port A		
A_CLK	Input	Input clocks for port A. The same clock also acts as clock inputs for the output pipeline registers if configured as registers. All inputs must be set up before the rising edge of the clock. The read or write operation begins with the rising edge.
A_ADDR	Input	Address inputs for port A.
A_BLK	Input	Block-select for port A.
A_DIN	Input	Data inputs for port A.
A_WEN	Input	Write enable for port A. Low = Read, High = Write.
A_REN	Input	Read enable for port A (exposed only if there is no depth cascading).
A_WBYTE_EN	Input	Port A Write Byte Enables (per byte).
A_DOUT	Output	Data outputs for port A.
A_DOUT_EN	Input	Read pipeline register enable for port A.
A_DOUT_SRST_N	Input	Read pipeline register synchronous reset for port A.
ARST_N	Input	Read pipeline register asynchronous reset for Port.
A_SB_CORRECT	Output	Single-bit error correction flag for port A.
A_DB_DETECT	Output	Double-bit error detection flag for port A.
Port B		
B_CLK	Input	Input clocks for port B. The same clock also acts as clock inputs for the output pipeline registers if configured as registers. All inputs must be set up before the rising edge of the clock. The read or write operation begins with the rising edge.
B_ADDR	Input	Address inputs for port B.
B_BLK	Input	Block-select for port B.
B_DIN	Input	Data input for port B
B_WEN	Input	Write enable for port B. Low = Read; High = Write
B_REN	Input	Read enable for port B (exposed only if there is no depth cascading).
B_WBYTE_EN	Input	Port B Write Byte Enables (per byte).

Table 16 • Port List for the DPSRAM Configurator (continued)

Port Name	Direction	Description
B_DOUT	Output	Data outputs for port B.
B_DOUT_EN	Input	Read pipeline register enable for port B.
B_DOUT_SRST_N	Input	Read pipeline register synchronous reset for port B.
B_SB_CORRECT	Output	Single-bit error correction flag for port B.
B_DB_DETECT	Output	Double-bit error detection flag for port B.
Common Signals		
ARST_N	Input	Pipeline registers asynchronous reset.

In this section, it is described how to configure a dual-port LSRAM instance and define how the signals are connected.

Figure 18 • Dual-Port Large SRAM Configurator

Optimization for High Speed or Low Power

The user can optimize the LSRAM macro with one of the following options:

- **High Speed** - To optimize the LSRAM macro for speed and area by using width cascading.
- **Low Power** - To optimize the LSRAM macro for low power, but it uses additional logic at the input and output by using depth cascading. Performance for a low power optimized macro may be inferior to that of a macro optimized for speed.

Port A Depth/Width and Port B Depth/Width

The user can set depth and width of a port.

- **Depth** - To set depth range. The depth range for each port is 1 to 32768
- **Width** - To set width range. The width range for each port is 1 to 3762.

Note: The two ports can be configured independently for any depth and width. Port A depth × port A width must be equal to port B depth × port B width.

Single Clock (CLK) or Independent Clocks (A_CLK and B_CLK)

The user can set the clock signals:

- Check **Single Clock** to drive both A and B ports with the same clock. This is the default configuration for dual-port LSRAM. Uncheck **Single Clock** to enable independent clock for each port: port A - A_CLK and port B - B_CLK.
- Click the waveform next to any of the clock signals to toggle its active edge.

Block Select (A_BLK and B_BLK) and Read/Write Control (A_WEN and B_WEN)

De-asserting A_BLK forces A_DOUT to zero. De-asserting B_BLK forces B_DOUT to zero.

- Asserting A_BLK when A_WEN is low reads the RAM at the A_ADDR onto the input of the A_DOUT register, on the next rising edge of A_CLK.
- Asserting A_BLK when A_WEN is high writes the data A_DIN into the RAM at the A_ADDR, on the next rising edge of A_CLK.
- Asserting B_BLK when B_WEN is low, reads the RAM at the B_ADDR onto the input of the B_DOUT register, on the next rising edge of B_CLK.
- Asserting B_BLK when B_WEN is high, writes the data B_DIN into the RAM at the B_ADDR, on the next edge of B_CLK.

The default configuration for A_BLK and B_BLK is unchecked, which ties the signal to the active state and removes it from the generated macro. Click the respective checkbox to insert that signal on the generated macro. Click the signal arrow (when available) to toggle its polarity.

Pipeline for Read Data Output of Port A and B

Check the **A_DOUT Pipeline** or **B_DOUT Pipeline** checkbox to enable pipelining of read data (A_DOUT or B_DOUT). If the checkbox is not checked, the user cannot configure the A_DOUT_EN/B_DOUT_EN, A_DOUT_SRST_N/B_DOUT_SRST_N signals.

DOUT on Write

- **Previous DOUT** - The default data on the read data output (A_DOUT or B_DOUT) during a write cycle is the DOUT data from the previous cycle (Previous DOUT).

Note: DOUT on Write selection is ignored during read operation. Writing different data to the same address using both ports is undefined and must be avoided. Writing to and reading from the same address is undefined and must be avoided.

Register Enable (A_DOUT_EN and B_DOUT_EN)

The pipeline registers for ports A and B have active high, enable inputs. The default configuration is to tie these signals to the active state and remove them from the generated macro. Use the signal arrow (when available) to toggle its polarity.

Synchronous Reset (A_DOUT_SRST_N and B_DOUT_SRST_N)

The pipeline registers for ports A and B have active low, synchronous reset inputs. The default configuration is to tie these signals to the inactive state and remove them from the generated macro. Use the signal arrow (when available) to toggle its polarity.

Read Enable (A_REN and B_REN)

De-asserting A_REN holds the previous read data on port A and de-asserting B_REN holds the previous read data on port B. For DOUT hold behavior when using pipelined-ECC mode and REN inputs, see [LSRAM Hold Time Violation](#), page 31. Asserting the A_REN reads the RAM at the A_ADDR onto port A's Read Data register on the next rising edge of the clock. Similarly, asserting the B_REN reads the RAM at the B_ADDR onto port B's Read Data register on the next rising edge of the clock.

The default configuration for the A_REN or B_REN checkbox is unchecked, which ties the signal to the active state and removes it from the generated macro. Check A_REN or B_REN checkbox (when available) to insert that signal on the generated macro; click the signal arrow (when available) to toggle its polarity.

The A_REN option for Port A and the B_REN option for Port B are disabled (greyed-out) in the Configurator if the Depth x Width of the port and the Optimization mode of the macro requires depth cascading and the address space is fractured.

For example, consider a 2048×18 dual-port LSRAM macro without ECC. If it is optimized for high speed, the Configurator generates two RAM1K18_RT blocks, each configured for 1024×9 (width-wise cascading). Since depth-wise cascading is not used, the Configurator enables the A_REN and B_REN options. When any of the check boxes is selected, the respective signal is exposed as an input port.

When the same 2048×18 dual-port LSRAM macro is optimized for low power, the Configurator generates two RAM1K18_RT blocks, each configured for 512×18 (depth-wise cascading). The Configurator disables the A_REN and B_REN options and these signals cannot be generated.

For a 4096×n dual-port SRAM macro, regardless of low power or high speed optimization, depth-wise cascading is required, and it fractures the address space. The Configurator disables the A_REN and B_REN options, and these signals cannot be generated.

Note: Read from both ports at the same location is allowed.

Write Byte Enables (A_WBYTE_EN and B_WBYTE_EN)

When enabled, write byte enables (A_WBYTE_EN and B_WBYTE_EN) are available as top-level buses. Each bit of A_WBYTE_EN gated by the A_WEN signal, enables writing to an individual byte of A_DIN. Each bit of B_WBYTE_EN gated by the B_WEN signal, enables writing to an individual byte of B_DIN.

Asynchronous Reset (ARST_N)

The pipeline registers for ports A and B have an active low, asynchronous reset input. The default configuration is to tie this signal to the inactive state and remove it from the generated macro. Use the signal arrow (when available) to toggle its polarity.

Note: ARST_N does not reset the memory contents. It resets only the pipeline registers for read data.

ECC

The following three ECC options are available:

- Disabled
- Pipelined
- Non-Pipelined

Note: When ECC is enabled (pipelined or non-pipelined), both ports have data widths equal to 18 bits. The SB_CORRECT and DB_DETECT output ports are exposed when ECC is enabled. When ECC is disabled, each port can be configured to either 18 bits or 9 bits width.

Initialize RAM for Simulation

The user can initialize RAM for simulation by setting the following:

- **Initialize RAM for Simulation** - To load the RAM content during simulation.
- **RAM Configuration** - Both write and read depths and widths are displayed as specified in configurator window.
- **Initialize RAM Contents From File** - The RAM Content can be initialized by importing the memory file. It avoids the simulation cycles required for initializing the memory and reduces the simulation runtime. The configurator partitions the memory file appropriately so that the right content goes to the right block RAM when multiple blocks are cascaded.
- **Import File** - To select and import a memory content file (Intel-Hex) from the Import Memory Content dialog box. File extensions are set to *.hex for Intel-Hex files during import. See [Appendix: Supported Memory File Formats](#), page 98. The imported memory content is displayed in the **RAM Content Editor**.
- **Reset All Values** - Resets all the data values.

RAM Configuration

The RAM Content Manager enables the user to specify the contents of RAM memory manually for both port A and port B. It avoids the simulation cycles required for initializing the memory and reduces the simulation runtime. It also allows the user to modify the imported data.

Port A View/Port B View

- **Go To Address** - Enables to go to a specific address in the editor. User can select the number display format (HEX, BIN, DEC) from the drop-down menu.
- **Default Value Data** - User can change the default data value by setting this with new data. When the data value is changed, all default values in the manager are updated to match the new value. User can select the number display format (HEX, BIN, DEC) from the drop-down menu.
- **Address** - The Address column lists the address of a memory location. The drop-down menu specifies the number format of the address list (hexadecimal, binary, or decimal).
- **Data** - To control the data format and data value in the manager.

Note: The dialogs show all data with the MSB down to LSB. For example, if the row showed 0xAABB for a 16-bit word size, the AA is MSB and BB is LSB.

- Click **OK** to close the manager and save all the changes made to the memory and its contents.
- Click **Cancel** to close the manager by canceling all the changes.

4.1.8.2.2 RTG4 Two-Port LSRAM Configurator

The RTG4 TPSRAM IP configurator is available in the Libero SoC software under Memory & Controllers. The following figure shows the TPSRAM IP block available in the Libero SoC software. The RTG4 TPSRAM configurator enables write access on one port and read access on the other port. The RAM configurator automatically cascades LSRAM blocks to create wider and deeper memories by selecting the most efficient aspect ratio. It also handles the grounding of unused bits. The core configurator supports the generation of memories that have different write and read aspect ratios. The configurator uses one or more memory blocks to generate a RAM matching the configuration. In addition, it also creates the surrounding cascading logic.

The configurator cascades RAM blocks in three different methods:

- Cascaded deep. For example, two blocks of 1024x18 to create a 2048x18.
- Cascaded wide. For example, two blocks of 1024x18 to create a 1024x36.
- Cascaded wide and deep. For example, four blocks of 1024x18 to create a 2048x36, in two blocks width-wise by two blocks depth-wise configuration.

Two-port LSRAM is synchronous for write and read operations, setting up the addresses, and writing and reading the data. The memory write and read operations will be triggered at the rising edge of the clock. An optional pipeline register is available at the read data ports to improve the clock-to-out delay.

Figure 19 • LSRAM Ports Configured as Two-Port SRAM - TPSRAM Macro in Libero SoC

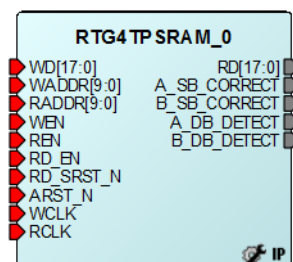


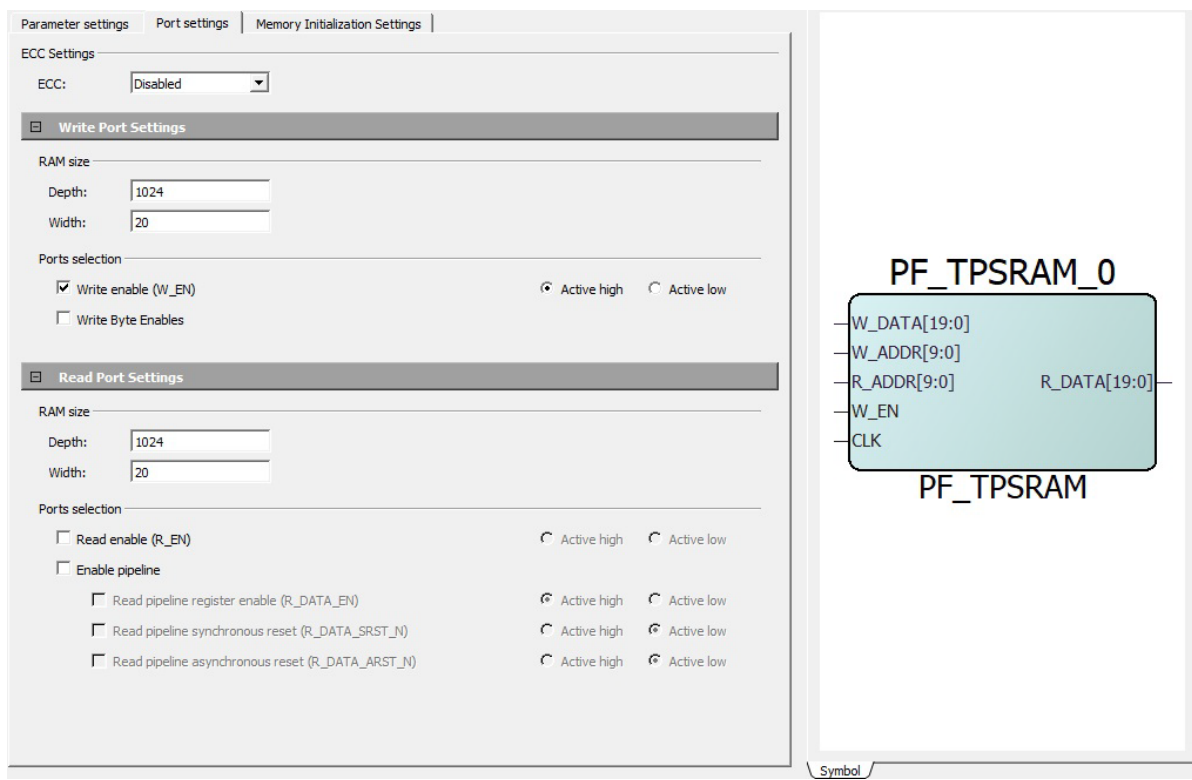
Table 17 • Port List for the TPSRAM Configurator

Port Name	Direction	Description
CLK	Input	Single clock to drive both WCLK and RCLK
WD	Input	Write data
WADDR	Input	Write address
WEN	Input	Write port enable
WCLK	Input	Write clock
RCLK	Input	Read clock

Table 17 • Port List for the TPSRAM Configurator (continued)

Port Name	Direction	Description
REN	Input	Read port enable
RADDR	Input	Read address
RD	Output	Read data
RD_EN	Input	Read data register enable
RD_SRST_N	Input	Read data register Synchronous reset
ARST_N	Input	Read data register Asynchronous reset
SB_CORRECT	Output	Single-bit correct flag
DB_DETECT	Output	Double-bit detect flag
WBYTE_EN	Input	Write Byte Enables (per byte)

In this section, it is described how to configure a two-port LSRAM instance and define how the signals are connected.

Figure 20 • Two-Port Large SRAM Configurator

Optimization of High Speed or Low Power

The user can optimize the LSRAM macro with one of the following options:

- **High Speed** - To optimize the LSRAM macro for speed and area by using width cascading.
- **Low Power** - To optimize the LSRAM macro for low power, but it uses additional logic at the input and output by using depth cascading. Performance for a low power optimized macro may be inferior to that of a macro optimized for speed.

Write Depth/Width and Read Depth/Width

The user can set depth and width of a port.

- **Depth** - To set depth range. The depth range for each port is 1 to 65536. The maximum value depends on the die.
- **Width** - To set width range. The width range for each port is 1 to 7524.

Note: The two ports can be configured independently for any depth and width. Write depth × write width must be equal to read depth × read width.

Single Clock (CLK) or Independent Write and Read Clocks (WCLK and RCLK)

The user can set the clock signals:

- Check **Single Clock** to drive both A and B ports with the same clock. This is the default configuration for dual-port LSRAM. Uncheck **Single Clock** to enable independent clock for each port: write and read.
- Click the waveform next to any of the clock signals to toggle its active edge.

Write Enable (WEN)

The following list describes the result of asserting and de-asserting the WEN signal:

- The default configuration for WEN is check state. Asserting WEN writes the data WD into the RAM at the address WADDR on the next rising edge of WCLK.
- Unchecking the WEN option ties the signal to the active state and removes it from the generated macro. Click the signal arrow (when available) to toggle its polarity.

Read Enable (R_{EN})

- When there is no depth cascading, de-asserting REN holds the previous Read data (RD). When there is depth cascading, de-asserting REN will generate zeros on RD. The different behavior in these two scenarios stems from the fact that the component's REN input is used to either drive the LSRAM block's A_REN input or the read-port block select input (A_BLK) depending on the cascading configuration.
- Asserting the REN reads the RAM at the read address RADDR onto the input of the RD register on the next rising edge of RCLK.
- The default configuration for REN is unchecked, which ties the signal to the active state and removes it from the generated macro.

Note: The user can insert the signal on the generated macro by checking the respective check boxes. Click the signal arrow (when available) to toggle its polarity.

Pipeline for Read Data Output

Click the Pipeline checkbox to enable pipelining for Read data (RD).

Turning off pipelining of Read data also disables the configuration options of the RD_EN, RD_SRST_N, and ARST_N signals.

Register Enable (RD_EN)

The pipeline register for RD has an active high, enable input. The default configuration is to tie this signal to the active state and remove it from the generated macro. Click the signal's checkbox to insert on the generated macro; click the signal arrow (when available) to toggle its polarity.

Synchronous Reset (RD_SRST_N)

The pipeline register for RD has an active low, synchronous reset input. The default configuration is to tie this signal to the inactive state and remove it from the generated macro. Click the signal's checkbox to insert on the generated macro; click the signal arrow (when available) to toggle its polarity.

Asynchronous Reset (ARST_N)

The pipeline register for RD has an active low, asynchronous reset input. The default configuration is to tie this signal to the inactive state and remove it from the generated macro. Click the signal's checkbox to insert on the generated macro; click the signal arrow (when available) to toggle its polarity.

Write Byte Enables (WBYTE_EN)

When enabled, write byte enables (WBYTE_EN) are available as a top-level bus. Each bit of WBYTE_EN enables writing to an individual byte of data. When ECC is enabled, the state of the WBYTE_EN bits should be identical for each LSRAM block.

Error Correction Code (ECC)

The following three error correction code (ECC) options are available:

- Disabled
- Pipelined
- Non-Pipelined

Note: When ECC is enabled (pipelined or non-pipelined), both ports have data widths equal to either 36 bits or 18 bits. The SB_CORRECT and DB_DETECT output ports are exposed when ECC is enabled. The SB_CORRECT and DB_DETECT flags from both ports A and B are used to report ECC errors for two-port RAMs configured for x36 data width. When ECC is disabled, each port can be configured to 36 bits, 18 bits or 9 bits width.

Initialize RAM for Simulation

The user can initialize RAM for simulation by setting the following:

- **Initialize RAM for Simulation** - To load the RAM content during simulation.
- **RAM Configuration** - Both write and read depths and widths are displayed as specified in the Port setting tab.
- **Initialize RAM Contents From File** - The RAM Content can be initialized by importing the memory file. It avoids the simulation cycles required for initializing the memory and reduces the simulation runtime. The configurator partitions the memory file appropriately so that the right content goes to the right block RAM when multiple blocks are cascaded.
- **Import File** - To select and import a memory content file (Intel-Hex) from the Import Memory Content dialog box. File extensions are set to *.hex for Intel-Hex files during import. See [Appendix: Supported Memory File Formats](#), page 98. The imported memory content is displayed in the RAM Content Editor.
- **Reset All Values** - Resets all the data values.

RAM Configuration

The RAM Content Manager enables the user to specify the contents of RAM memory manually for both port A and port B. It avoids the simulation cycles required for initializing the memory and reduces the simulation runtime. It also allows the user to modify the imported data.

Port A View/Port B View

- **Go To Address** - Enables to go to a specific address in the editor. User can select the number display format (HEX, BIN, DEC) from the Address drop-down menu.
- **Default Value Data** - User can change the default data value by setting this with new data. When the data value is changed, all default values in the manager are updated to match the new value. User can select the number display format (HEX, BIN, DEC) from the Data drop-down menu.
- **Address** - The Address column lists the address of a memory location. The drop-down menu specifies the number format of the address list (hexadecimal, binary, or decimal).
- **Data** - To control the data format and data value in the manager.

Note: The dialogs show all data with the MSB down to LSB. For example, if the row showed 0xAABB for a 16-bit word size, the AA is MSB and BB is LSB.

- Click **OK** to close the manager and save all the changes made to the memory and its contents.
- Click **Cancel** to close the manager by canceling all the changes.

4.1.8.3 LSRAM Hold Time Violation

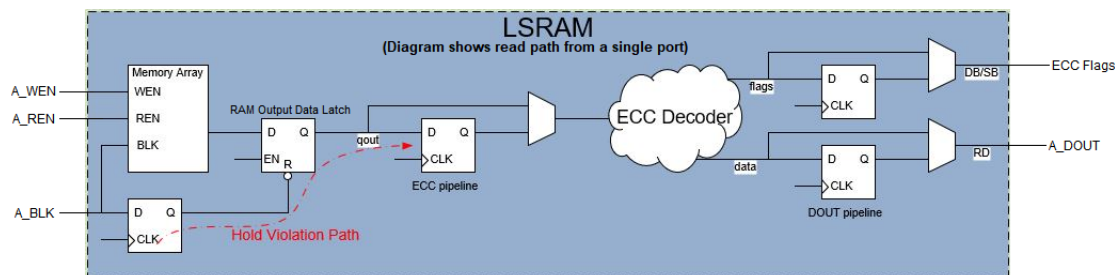
As described in the previous sections, the RTG4 LSRAM supports pipelined-ECC operation where there is an ECC encoder pipeline stage during LSRAM writes and an ECC decoder pipeline stage during LSRAM reads. Furthermore, the LSRAM primitive macro includes A_BLK and B_BLK block select inputs to enable the LSRAM block for reading and writing depending on the RAM port configuration. In certain cases, it is beneficial, or even required, to de-assert the block select inputs. In some configurations, de-asserting BLK select can save power after completing a read versus having the RAM continually read from the last address used. As another example, when performing depth-cascading of the LSRAM primitive to form deeper RAM blocks, the BLK select input provides a means to extend the address space by disabling non-addressed RAM blocks in the depth-cascade to ensure the correct read and write operations.

Designs which combine pipelined-ECC LSRAM mode with application use-models that could de-assert the BLK select inputs on a port used for LSRAM reads are recommended to use the LSRAM configurator cores described in the previous sections to create the LSRAM component instance. As described in [RTG4 Customer Advisory Notice, CAN19011.1](#), the LSRAM primitive has an internal hold-time issue affecting the ECC decoder pipeline register during an LSRAM read, whenever the BLK select input for the port being read is de-asserted immediately after issuing the read operation.

When the BLK select input is de-asserted after issuing an LSRAM read, the LSRAM read DOUT port should go to zero after the appropriate number of clock cycles, depending on the number of LSRAM pipeline registers enabled (ECC pipeline and DOUT pipeline). Inside the LSRAM, de-asserting the BLK select clears the RAM data output latch which feeds the ECC decoder register and DOUT pipeline register, when enabled, or directly feeds the DOUT port when pipeline options are disabled.

In the case of pipelined-ECC mode, the BLK select de-assertion clears the RAM output data latch too quickly, violating the ECC decoder pipeline register's data hold time, preventing of the capture of the valid read data from the previously issued RAM read. The ECC decoder register captures the zeroed-out data, which causes all-zero data to shoot-through to the LSRAM DOUT port. Since the data is all-zero, the ECC is no longer correct, and the ECC output flags also assert. The issue is depicted in the figure below:

Figure 21 • LSRAM Pipelined-ECC BLK Select De-assertion Hold Time Violation After Read



This issue only impacts RTG4 two-port and dual-port LSRAM in pipelined-ECC mode.

This issue does NOT impact the following LSRAM configurations:

- Any configuration where the BLK select inputs are tied high
- Non-pipelined-ECC mode (with or without DOUT pipeline)
- Non-ECC mode (with or without DOUT pipeline)
- Two-port LSRAM configurator component without depth-cascading
- Dual-port LSRAM configurator component without depth cascading, and without exposing BLK select input on any port used for reading
- LSRAM port used exclusively for writes (There is no issue if BLK select input is de-asserted on that port after a write command is issued)
- Synplify-inferred LSRAM (Synplify Pro does not infer pipelined-ECC mode)

The RTG4 two-port and dual-port LSRAM configurator cores in Libero SoC generate an additional fabric logic circuit for pipelined-ECC mode. The additional circuit avoids the hold time issue by delaying BLK select de-assertion to each LSRAM block.

The additional fabric logic generated by the configurator is shown in the following figure:

Figure 22 • LSRAM Configurator Fabric Wrapper Logic Mitigating BLK De-assertion Hold Time Issue on Depth Cascaded LSRAM Component

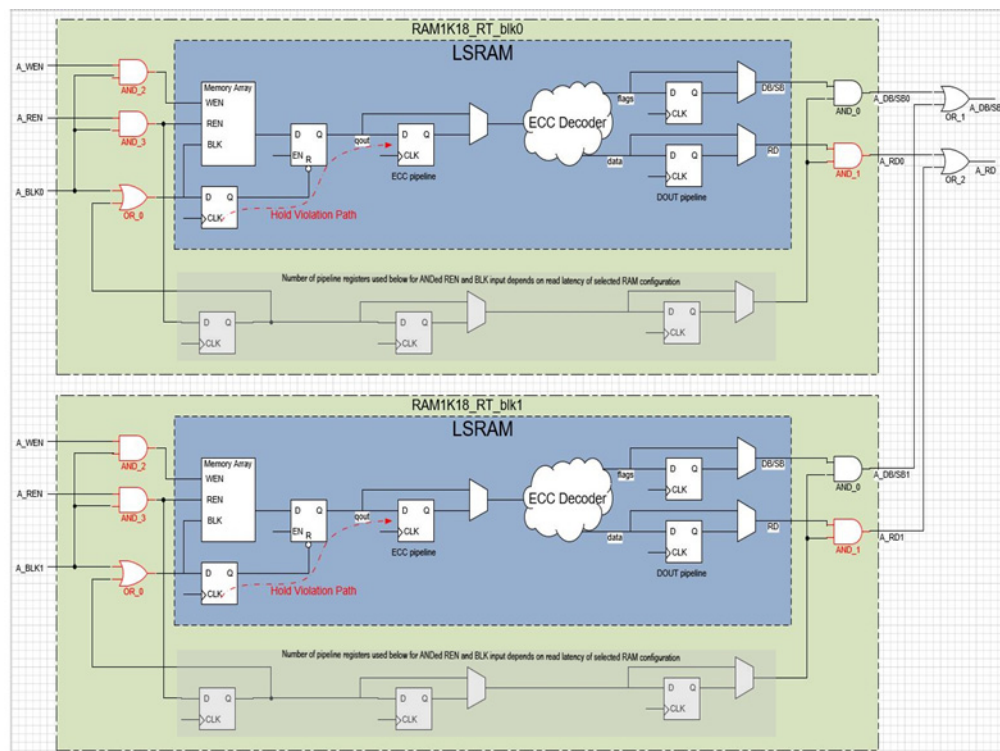


Figure 22 shows an added AND (x3) and OR (x1) gates for depth cascaded RAMs working together with a pipelined version of the BLK select input. To prevent zeros from shooting through to read DOUT port, a pipelined version of the BLK select input + OR_0 keeps the BLK select input to the LSRAM primitive asserted 1 cycle longer, to delay BLK de-assertion during read. Furthermore, AND_2/AND_3 gate WEN/REN, respectively, with the non-registered BLK select input to prevent extra write/read commands due to the delayed BLK de-assertion at the LSRAM primitive BLK input port. Finally, AND_1, and similarly AND_0, ensures outputs and ECC flags are gated-off when not in the active read output cycle with correct pipeline latency depending on the number of pipeline stages active.

Note: With this LSRAM configurator update, single-depth dual-port LSRAM components which enable the use of the BLK select input will no longer hold the most recent read data after de-asserting REN. Read data output is gated by the pipelined BLK select input, and thus the RAM component will output zero an appropriate number of cycles after outputting the valid read data.

Therefore, it is recommended that designers generate pipelined-ECC LSRAM components using the Libero SoC configurator cores in Libero SoC v11.9 SP3 or above. Designers who manually instantiate pipelined-ECC LSRAM primitive macros would need to carefully consider whether the issue above applies to their application use-model, and manually add mitigation logic.

Lastly, designers are reminded to re-run static timing analysis in SmartTime using the appropriate timing constraints to ensure the additional fabric logic added to mitigate the issue works with the application's target clock frequency.

4.1.8.4 LSRAM Configurator Component Timing and Ports

The LSRAM configurator component timing will vary based on the configuration created.

Note: Component <Port> Name is used to identify top-level port on generated configurator component. LSRAM <Port> Name is used to identify pin on LSRAM primitive.

Note: Comb delay is used to refer to Combinatorial Gate delay.

Table 18 • LSRAM Configurator Component Timing and Ports

Config #	Configuration Name	Additional Fabric Wrapper Logic?	Notes about input port mapping	Impact to Timing Waveform
1	DPSRAM_DOUTnpipe_1Kx18_ECCnpipe	ECC Flags (SB_CORRECT, DB_DETECT) are gated by registered signal derived from BLK ANDed with REN.	None For schematic, see Figure 23 .	Write: None Read: ECC Flag outputs only valid during active read data out cycle after accounting for comb gate delay.
2	DPSRAM_DOUTnpipe_1Kx18_ECCpipe	Component level BLK ANDed with component REN and WEN inputs respectively. Component level BLK ORed with pipelined version of component BLK. Component BLK is pipelined twice and used to gate LSRAM DOUT. Component (BLK&REN) is pipelined twice and used to gate LSRAM ECC Flag outputs.	LSRAM REN and WEN are driven by component level BLK ANDed with component REN and WEN inputs respectively. LSRAM BLK driven by component level BLK ORed with pipelined version of component BLK which extends BLK assertion by 1 cycle. For schematic, see Figure 24 .	Write: Comb delay for WEN reaching LSRAM macro. Read: Comb delay for REN reaching LSRAM macro. BLK select assertion extended by 1 cycle. LSRAM DOUT and ECC Flag outputs are only active during read data out cycle with 1 cycle added latency and comb delay.
3	DPSRAM_DOUTpipe_1Kx18_ECCnpipe	ECC Flags (SB_CORRECT, DB_DETECT) are gated by registered signal derived from BLK ANDed with REN. Two levels of BLK pipeline to ensure ECC flags are output on the correct read data out cycle.	None For schematic, see Figure 25 .	Write: None Read: ECC Flag outputs only valid during active read data out cycle after accounting for comb gate delay.
4	DPSRAM_DOUTpipe_1Kx18_ECCpipe	Component level BLK ANDed with component REN and WEN inputs respectively. Component level BLK ORed with pipelined version of component BLK. Component BLK is pipelined thrice and used to gate LSRAM DOUT. Component (BLK&REN) is pipelined thrice and used to gate ECC Flag outputs.	LSRAM REN and WEN are driven by component level BLK ANDed with component REN and WEN inputs respectively. LSRAM BLK driven by component level BLK ORed with pipelined version of component BLK which extends BLK assertion by 1 cycle. For schematic, see Figure 26 .	Write: Comb delay for WEN reaching LSRAM macro. Read: Comb delay for REN reaching LSRAM macro. BLK select assertion extended by 1 cycle. LSRAM DOUT and ECC Flag outputs are only active during read data out cycle with 2 cycles added latency and comb delay.
5	DPSRAM_DOUTpipe_HS_1Kx36_noECC	No additional fabric logic. Width cascading. DIN splits across multiple LSRAMs. DOUT assembled from multiple LSRAM outputs.	Component ports mapped to respective LSRAM ports, but there is a 1 to 2 mapping to multiple LSRAMs in the width cascade. There is bus slicing (on DIN) and bus concatenation (on DOUT). For schematic, see Figure 27 .	No change to LSRAM primitive macro timing waveform for pipelined DOUT.
6	DPSRAM_DOUTpipe_LP_2Kx18_noECC	Depth Cascade. Decoder of RADDR MSB selects a particular RAM block in the depth cascade. Component DOUT uses OR gate to output selected LSRAM macro's data	Component RADDR MSB drives LSRAM BLK select and Component BLK drives another bit of LSRAM BLK select. When REN is not exposed at top-level, it is tied HIGH. When exposed, it is ANDed with Component RADDR MSB to drive LSRAM BLK. For schematic, see Figure 28 .	Comb delay on component RADDR feeding LSRAM BLK select. Comb delay on component DOUT. Minimal change to LSRAM primitive macro timing waveform for pipelined DOUT.

Table 18 • LSRAM Configurator Component Timing and Ports

Config #	Configuration Name	Additional Fabric Wrapper Logic?	Notes about input port mapping	Impact to Timing Waveform
7	TPSRAM_DOUTnpipe_512x36_ECCnpipe	Component REN is pipelined and used to gate off each port's ECC flag outputs which are OR'd together to make one DB_DETECT and one SB_CORRECT output.	Component level WEN drives LSRAM Write Port BLK select input. LSRAM WEN tied HIGH. For schematic, see Figure 29 .	Minimal change from LSRAM primitive timing for non-pipelined ECC. Comb delay on ECC flag outputs (AND + OR delay) ECC Flag outputs only valid during active read data out cycle.
8	TPSRAM_DOUTnpipe_512x36_ECCpipe	Component REN is pipelined twice and used to gate off each port's ECC flag outputs which are OR'd together to make one DB_DETECT and one SB_CORRECT output.	Component REN drives LSRAM read port REN. LSRAM Read Port BLK is tied HIGH. Component level WEN drives LSRAM Write Port BLK select input. LSRAM WEN tied HIGH. For schematic, see Figure 30 .	Minimal change from LSRAM primitive timing with pipelined ECC. Comb delay on ECC flag outputs (AND + OR delay). ECC Flag outputs only valid during active read data out cycle.
9	TPSRAM_DOUTpipe_512x36_ECCnpipe	Component REN is pipelined twice and used to gate off each port's ECC flag outputs which are OR'd together to make one DB_DETECT and one SB_CORRECT output.	Component REN drives LSRAM read port REN. LSRAM Read Port BLK is tied HIGH. Component level WEN drives LSRAM Write Port BLK select input. LSRAM WEN tied HIGH. For schematic, see Figure 31 .	Minimal change from LSRAM primitive timing with only DOUT pipeline. Comb delay on ECC flag outputs (AND + OR delay). ECC Flag outputs only valid during active read data out cycle.
10	TPSRAM_DOUTpipe_512x36_ECCpipe	Component REN is pipelined three times and used to gate off each port's ECC flag outputs which are OR'd together to make one DB_DETECT and one SB_CORRECT output.	Component REN drives LSRAM read port REN. LSRAM Read Port BLK is tied HIGH. Component level WEN drives LSRAM Write Port BLK select input. LSRAM WEN tied HIGH. For schematic, see Figure 32 .	Minimal change from LSRAM primitive timing for pipelined-ECC with DOUT pipeline. Comb delay on ECC flag outputs (AND + OR delay). ECC Flag outputs only valid during active read data out cycle.
11	TPSRAM_DOUTpipe_HS_512x72_noECC	No additional fabric logic. Width cascading. DIN splits across multiple ports and multiple LSRAMs. DOUT assembled from all DOUT ports of multiple LSRAMs macros.	Component ports mapped to respective LSRAM. There is bus slicing on component DIN across both LSRAM ports and both LSRAM macros. There is bus concatenation from both DOUT ports of both LSRAM macros. For schematic, see Figure 33 .	No change to LSRAM primitive macro timing waveform for pipelined DOUT.
12	TPSRAM_DOUTpipe_LP_1Kx36_noECC	Depth Cascade. Decoder of RADDR MSB selects a particular RAM block in the depth cascade. Component DOUT uses OR gate to output selected LSRAM macro's data.	Component RADDR and WADDR MSB each drives a bit of LSRAM read and write port's BLK select, respectively. Component REN drives another bit of LSRAM read port BLK select. Component WEN drives another bit of LSRAM write port BLK select. LSRAM REN inputs tied HIGH. LSRAM WEN inputs tied HIGH. For schematic, see Figure 34 .	Comb delay on component RADDR/WADDR feeding LSRAM BLK select. Comb delay on component DOUT. Minimal change to LSRAM primitive macro timing waveform for pipelined DOUT.

The following schematic diagrams depict 12 configurations supported by the LSRAM which are mentioned in the preceding table:

Figure 23 • DPSRAM_DOUTnpipe_1Kx18_ECCnpipe

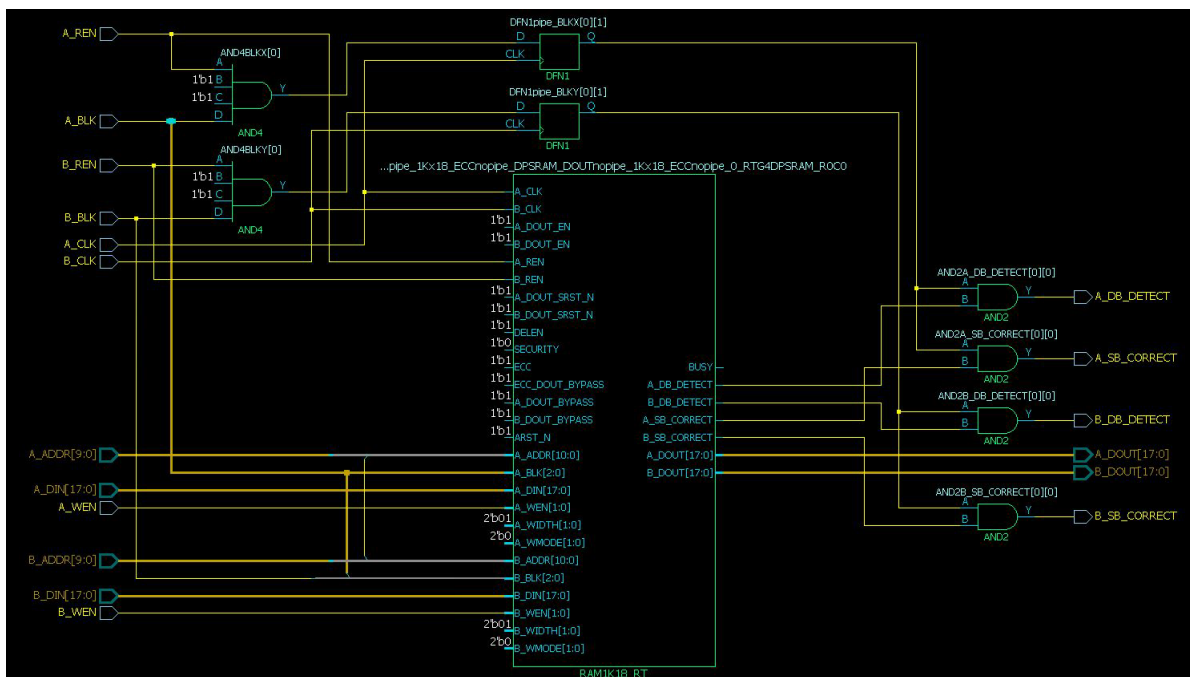


Figure 24 • DPSRAM_DOUTnpipe_1Kx18_ECCpipe

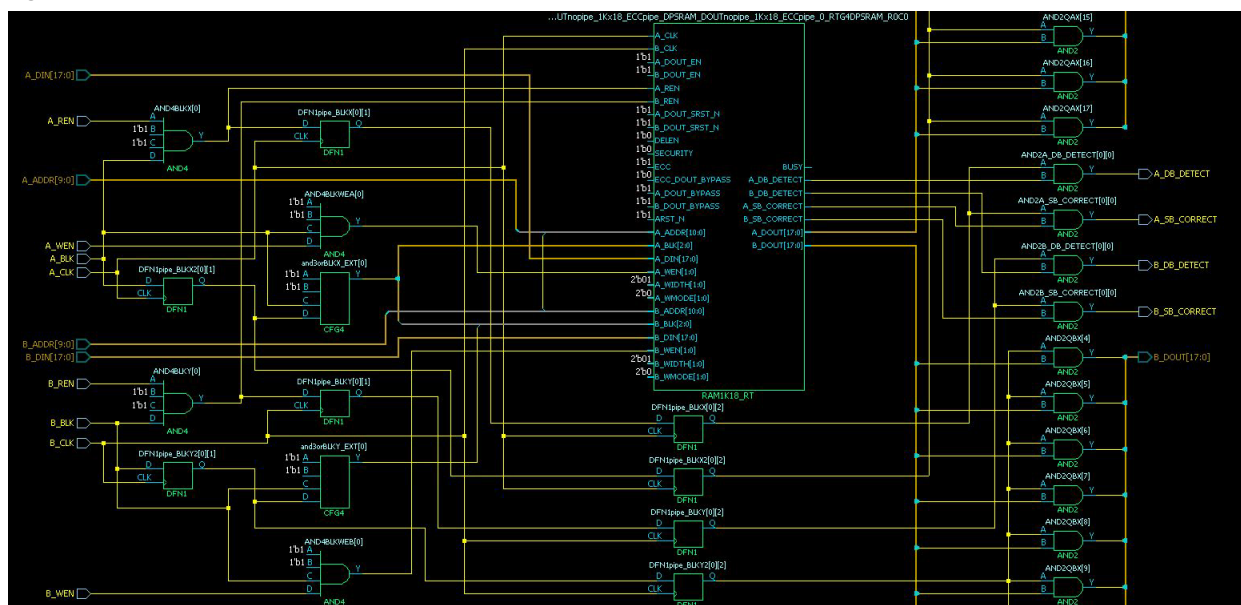


Figure 25 • DPSRAM_DOUTpipe_1Kx18_ECCnopipe

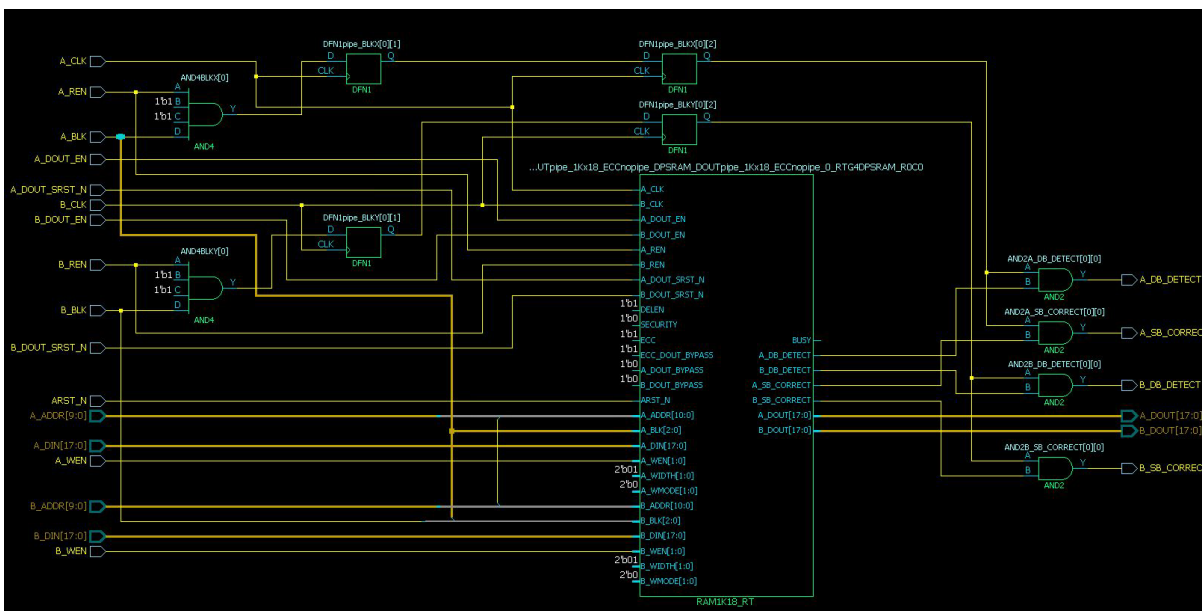


Figure 26 • DPSRAM_DOUTpipe_1Kx18_ECCpipe

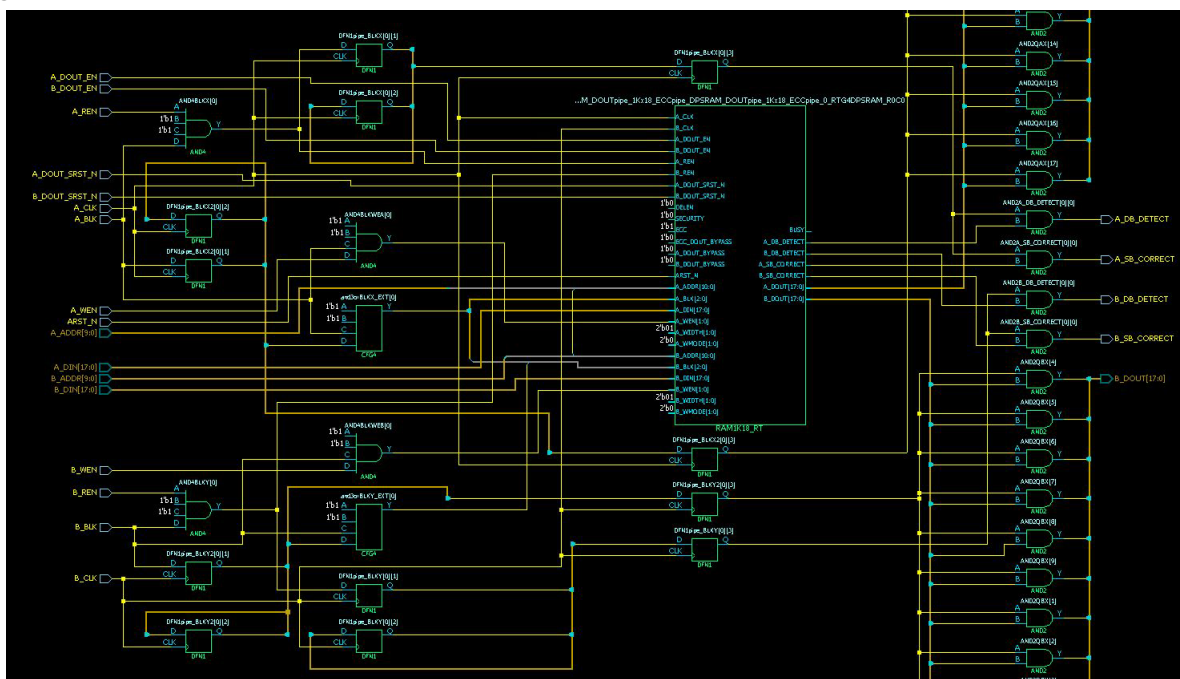


Figure 27 • DPSRAM_DOUTpipe_HS_1Kx36_noECC

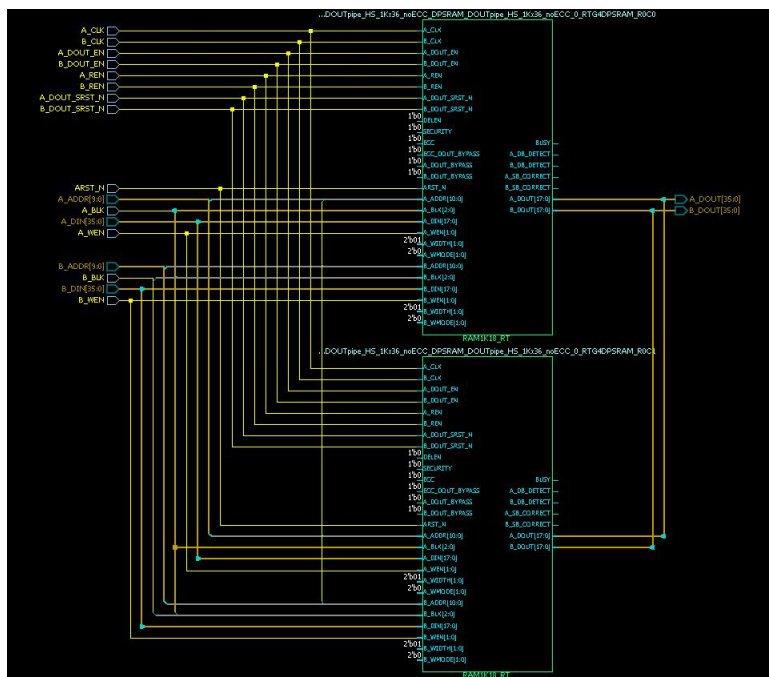
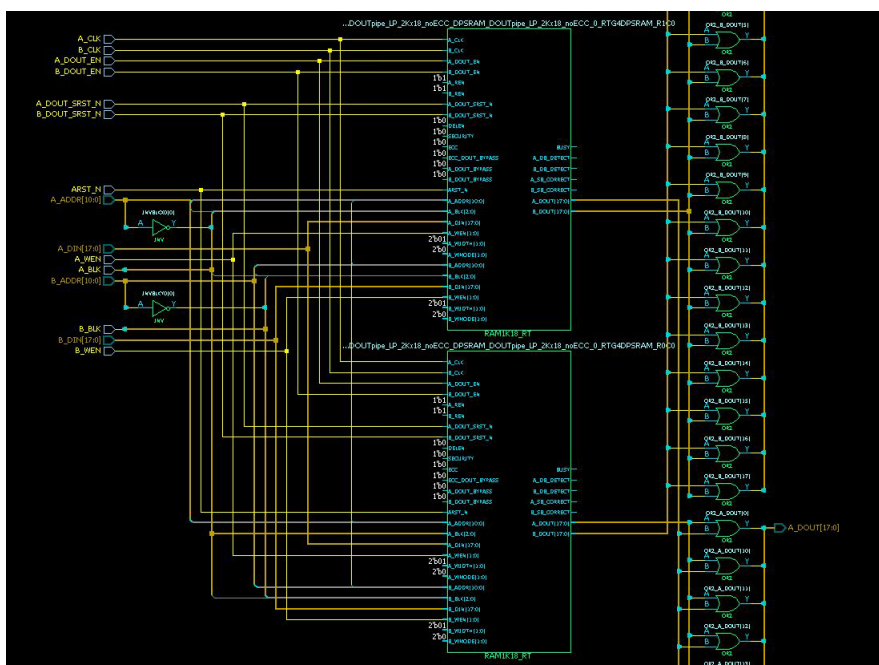


Figure 28 • DPSRAM_DOUTpipe_LP_2Kx18_noECC



[illegible]

The diagram illustrates the internal logic of the RAM1K13B RT component. It features several input registers: REN, RCLK, WCLK, RADDR[8:0], WADDR[8:0], and WEN. The logic is implemented using D flip-flops (DFN1, DFN2) and combinational logic blocks (AND2, OR2). The output is RD[35:0]. The diagram is labeled 'RAM1K13B RT' at the bottom.

Figure 31 • TPSRAM_DOUTpipe_512x36_ECCnopipe

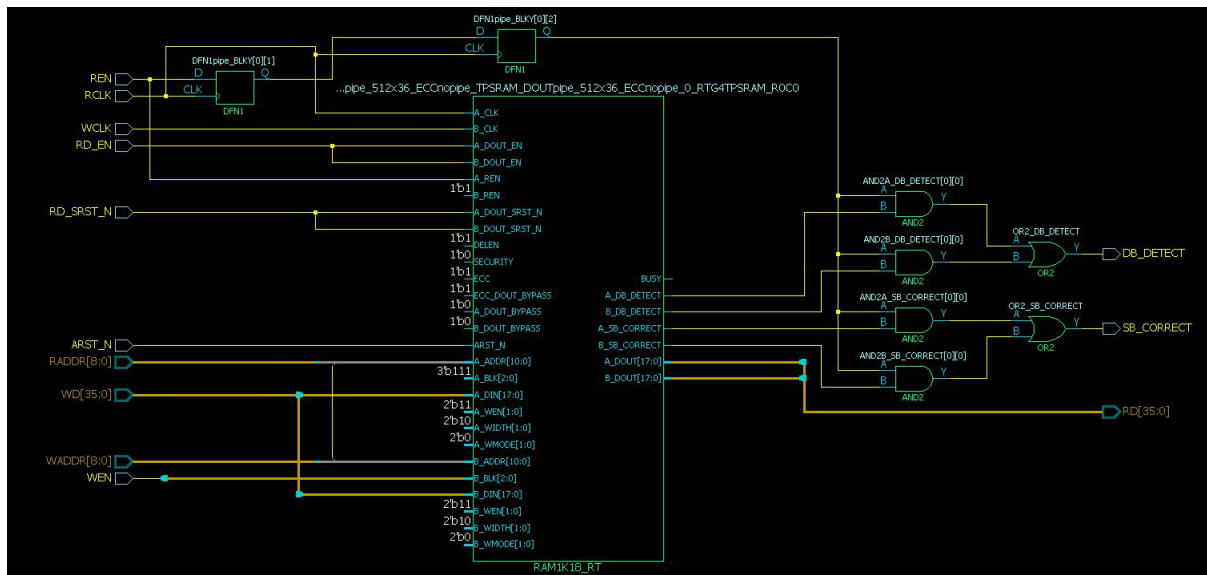


Figure 32 • TPSRAM_DOUTpipe_512x36_ECCpipe

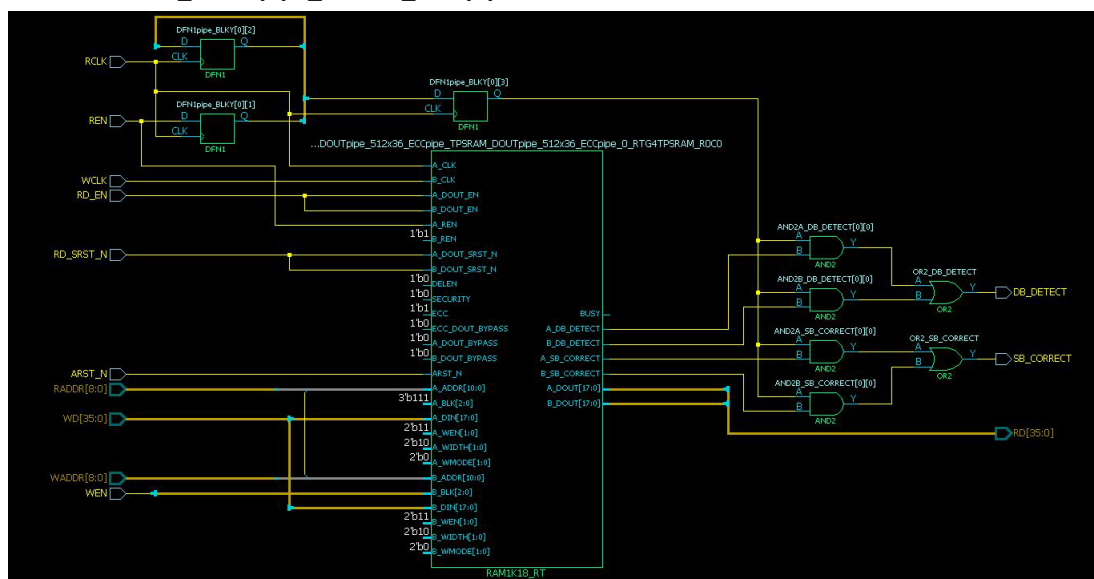


Figure 33 • TPSRAM_DOUTpipe_HS_512x72_noECC

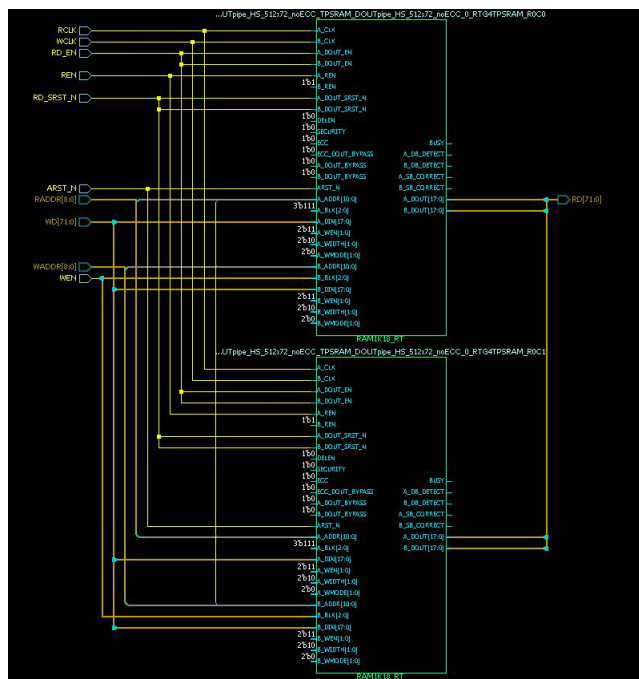
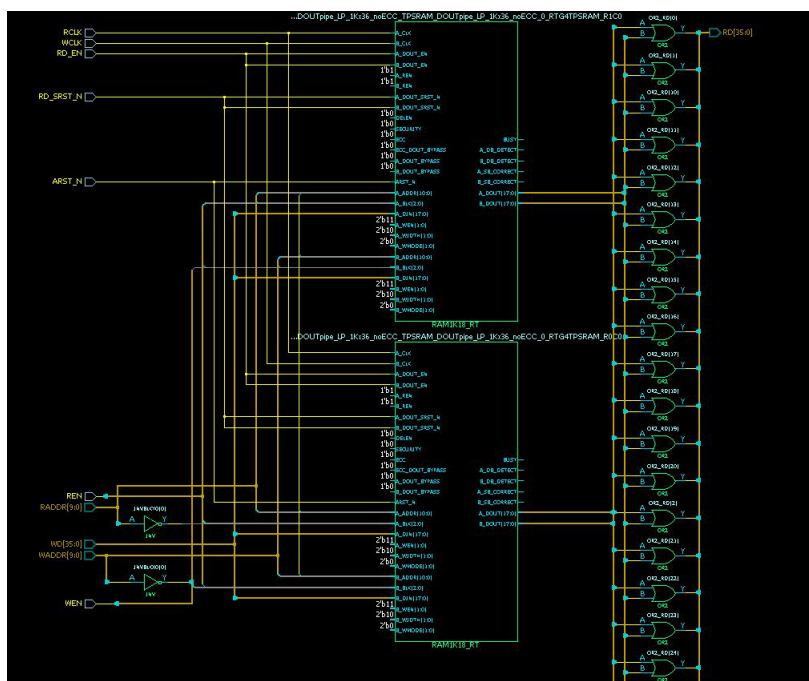


Figure 34 • TPSRAM_DOUTpipe_LP_1Kx36_noECC



4.1.8.4.1 Functional Timing Waveforms

The following table maps each timing waveform to all the applicable configuration options.

Table 19 • Functional Timing Waveforms

Figure	LSRAM Configurator Use-Case Depicted	Difference vs LSRAM Primitive Timing
Case A: LSRAM Configurator with Comb Delay. Gating ECC Flag Outputs, non-Pipelined ECC. For functional timing waveform, see Figure 35 .	Config #1, Config #3, Config #7, Config #9	Combinatorial Delay on ECC Flag Outputs. ECC Flag Outputs are Gated Off when not in valid read data out cycle.
Case B: LSRAM Read Operation, Pipelined Read without ECC. For functional timing waveform, see Figure 36 .	Config #5 and Config #11	No change to LSRAM primitive macro timing waveform for pipelined DOUT, no ECC.
Case C: Depth Cascaded Dual Port LSRAM Component, Pipelined Read without ECC. For functional timing waveform, see Figure 37 .	Config #6	Combinatorial Delay on BLK Select @ LSRAM Block, Combinatorial Delay on DOUT.
Case D: Depth Cascaded Two Port LSRAM Component, Pipelined Read without ECC. For functional timing waveform, see Figure 38 .	Config #12	Combinatorial Delay on BLK Select @ LSRAM Block, Combinatorial Delay on DOUT.
Case E: Dual Port LSRAM with Pipelined ECC. For functional timing waveform, see Figure 39 .	Config #2 and Config #4	Write: Comb delay for WEN reaching LSRAM macro. Read: Comb delay for REN reaching LSRAM macro. BLK select assertion extended by 1 cycle. LSRAM DOUT and ECC Flag outputs are only active during respective read data out cycle.
Case F: Two Port LSRAM with Pipelined ECC. For functional timing waveform, see Figure 40 .	Config #8 and Config #10	Minimal change from LSRAM primitive timing for pipelined-ECC with and without DOUT pipeline. Some comb delay on ECC flag outputs (AND + OR delay). ECC Flag outputs only valid during active read data out cycle.

Figure 35 • Case A: LSRAM Configurator Component with Comb Delay Gating ECC Flag Outputs, non-Pipelined ECC

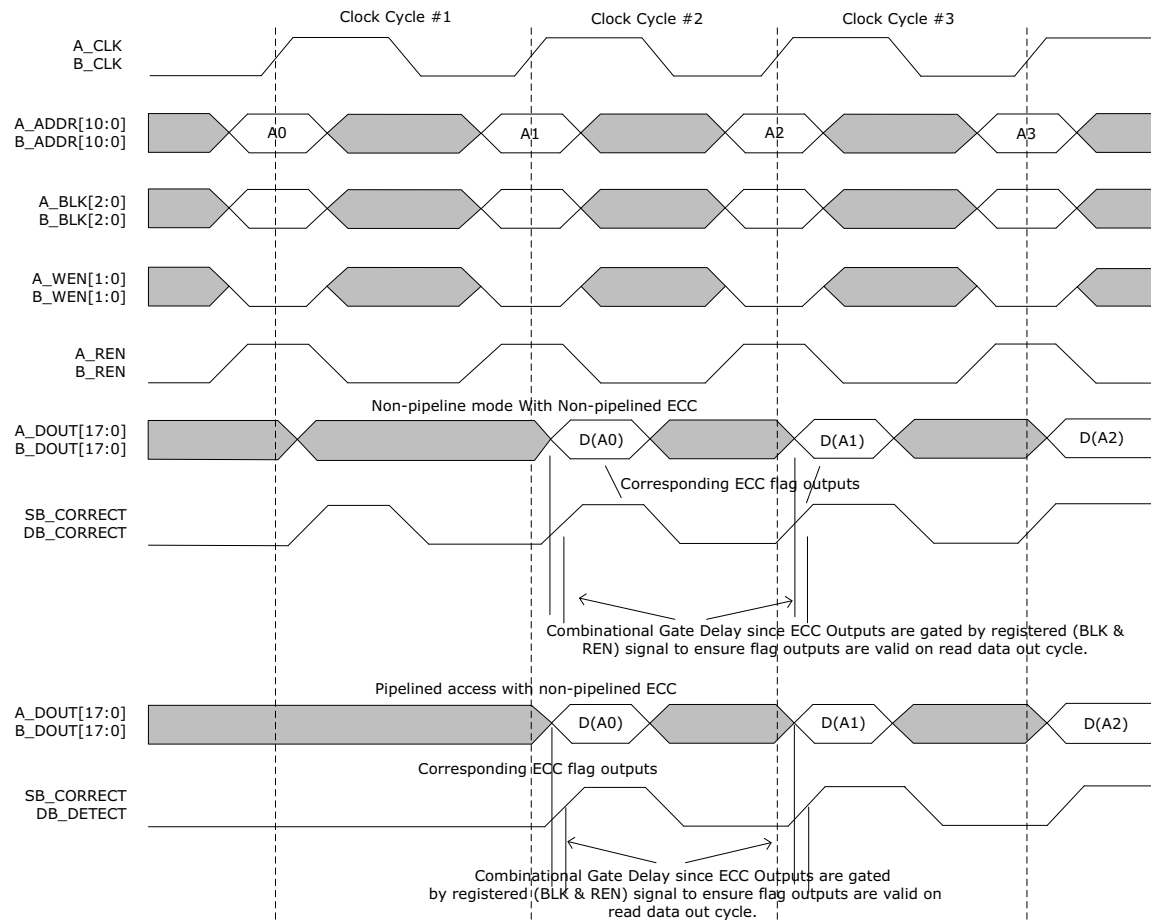


Figure 36 • Case B: LSRAM Read Operation, Pipelined Read without ECC

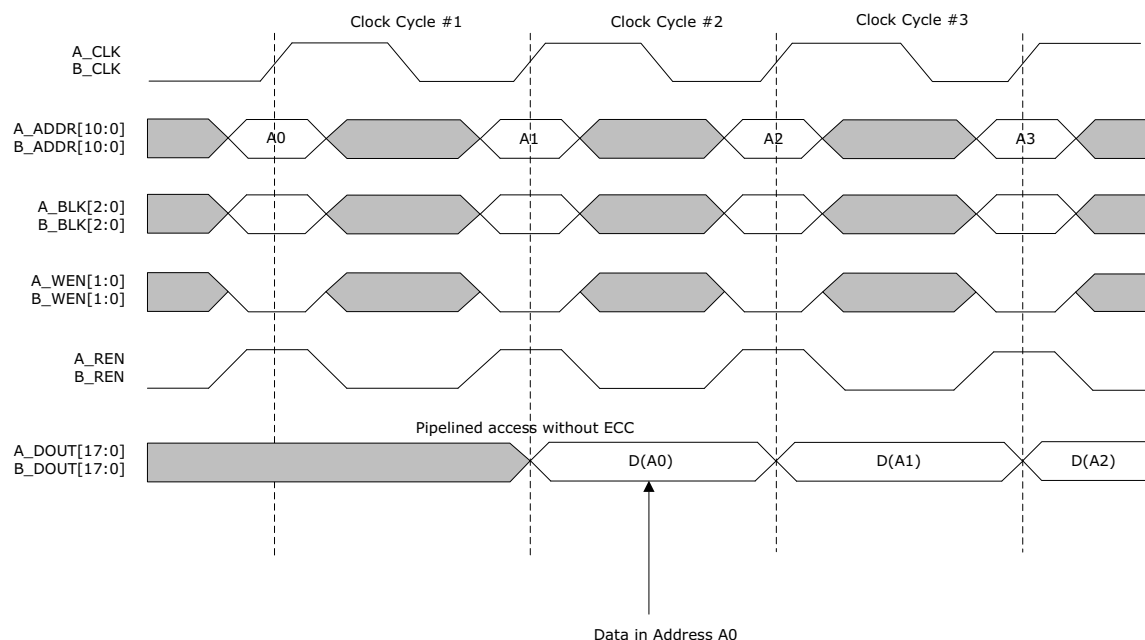


Figure 37 • Case C: Depth Cascaded Dual Port LSRAM Component, Pipelined Read without ECC

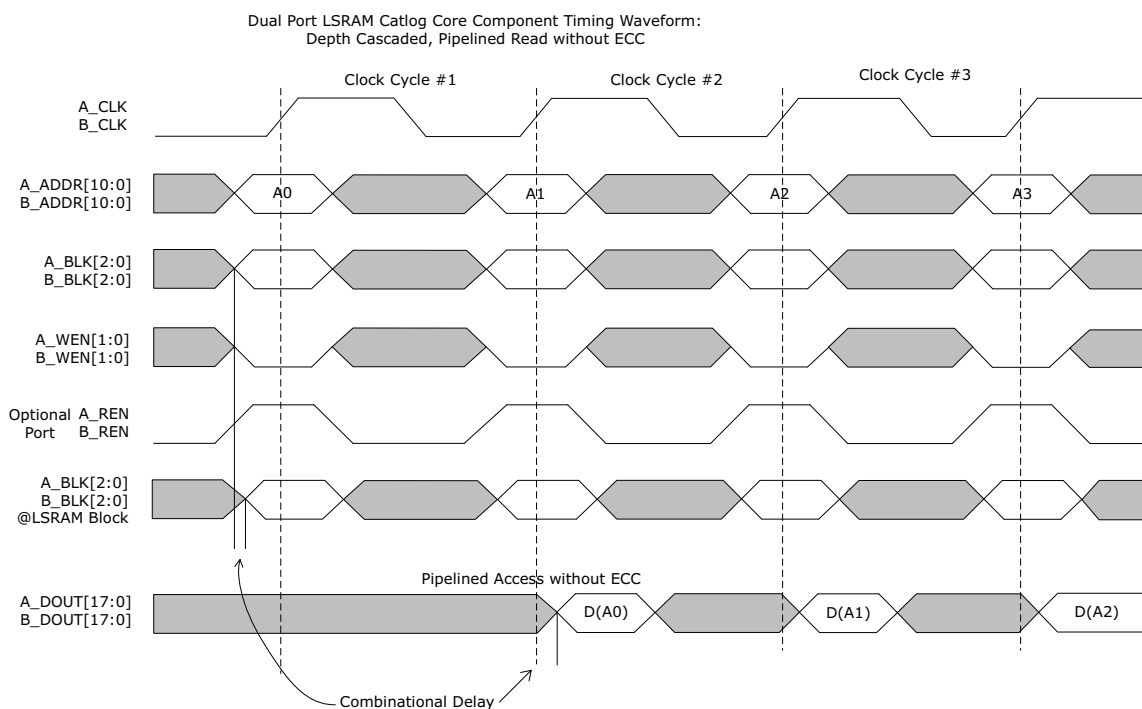


Figure 38 • Case D: Depth Cascaded Two Port LSRAM Component, Pipelined Read without ECC

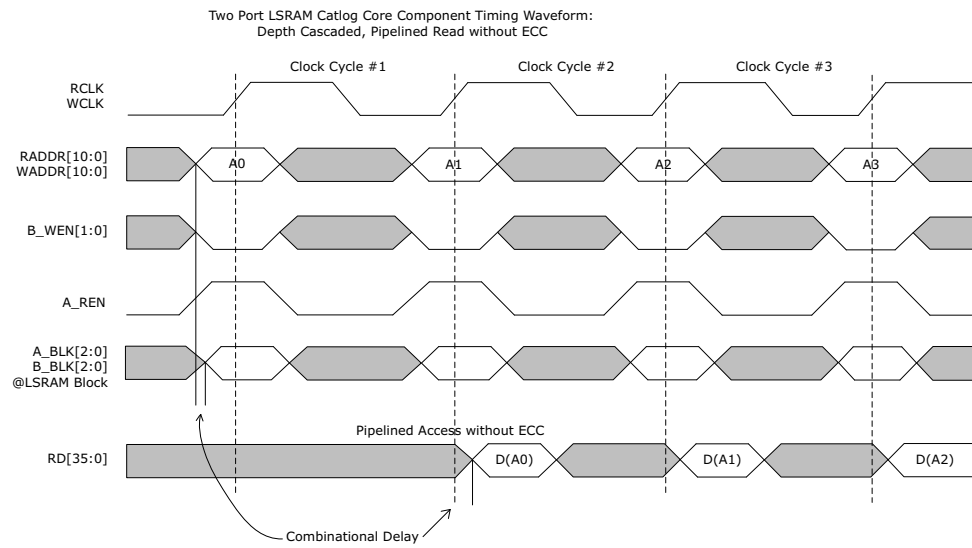
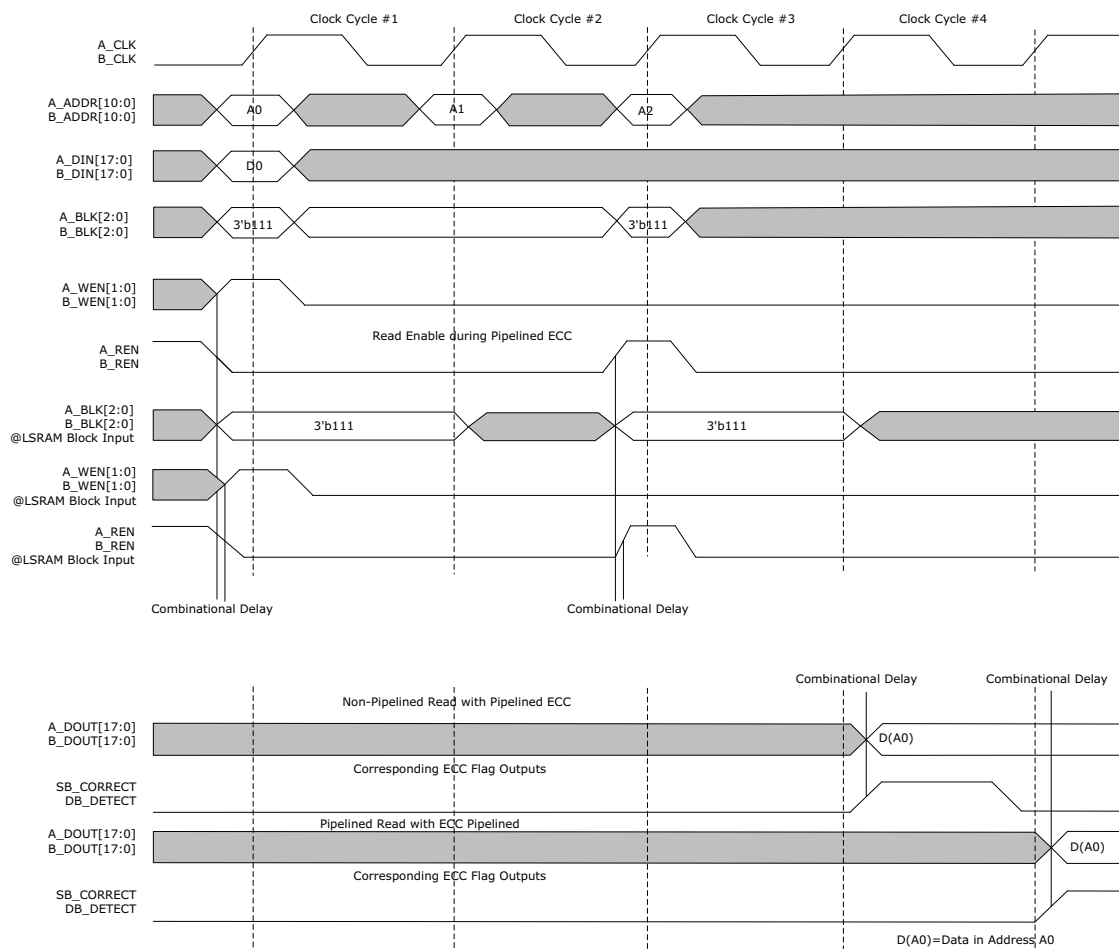
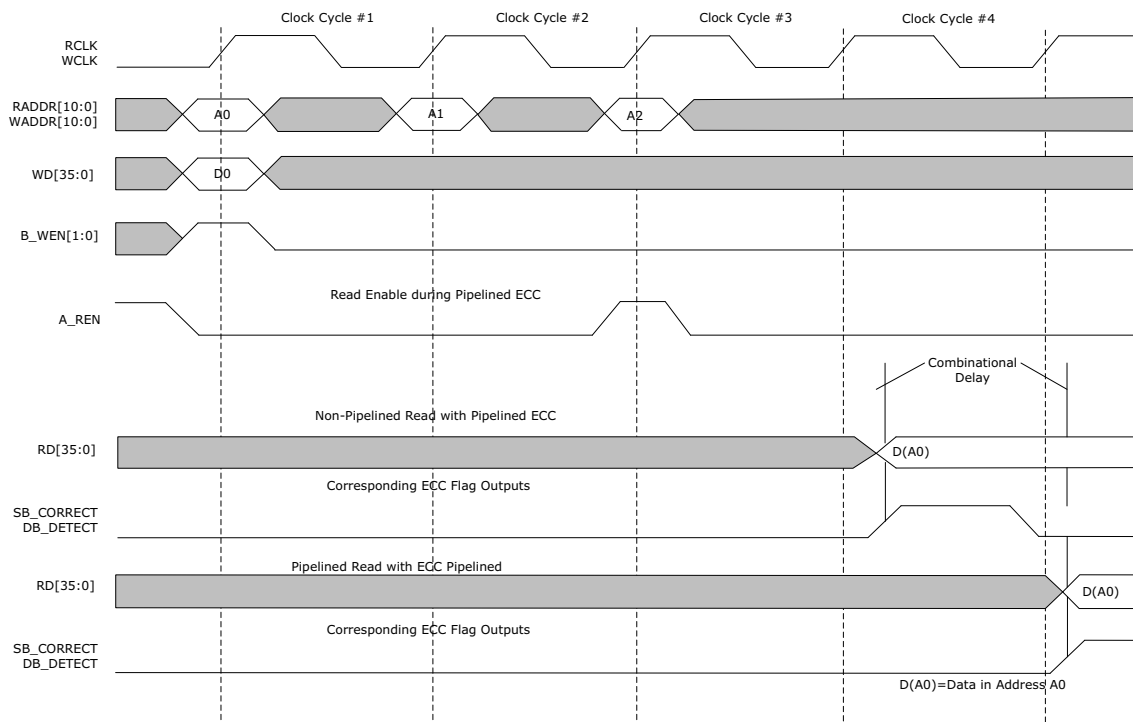


Figure 39 • Case E: Dual Port LSRAM with Pipelined ECC

1. For cases where pipelined ECC mode is used, the first write cycle is used by the ECC encoder and the second clock cycle is used when the LSRAM memory array is actually written. Therefore, it is not legal to perform a write immediately followed by a read to the same address on the next clock cycle, because LSRAM is being written with the newly encoded data. When using pipelined ECC mode, after issuing a write to a given LSRAM address, a subsequent read to that address must wait until two clock cycles later to ensure the correct data is being read. Once the read command is issued, pipelined ECC mode requires one clock cycle to decode the data from LSRAM before it is presented on the data output port.

Figure 40 • Case F: Two Port LSRAM with Pipelined ECC



1. For cases where pipelined ECC mode is used, the first write cycle is used by the ECC encoder and the second clock cycle is used when the LSRAM memory array is actually written. Therefore, it is not legal to perform a write immediately followed by a read to the same address on the next clock cycle, because LSRAM is being written with the newly encoded data. When using pipelined ECC mode, after issuing a write to a given LSRAM address, a subsequent read to that address must wait until two clock cycles later to ensure the correct data is being read. Once the read command is issued, pipelined ECC mode requires one clock cycle to decode the data from LSRAM before it is presented on the data output port.

4.1.8.5 Simulating ECC Errors in LSRAM

The simulation models for the LSRAM and μ SRAM support two signals, the SB_CORRECT signal to indicate a single-bit ECC error has occurred and the DB_DETECT signal to indicate that a double-bit, non-correctable error has occurred. The signals are asserted in conjunction with each other to pass this information. The read data is unaffected by the flag behavior and will always be correct in the simulation regardless of the flag state.

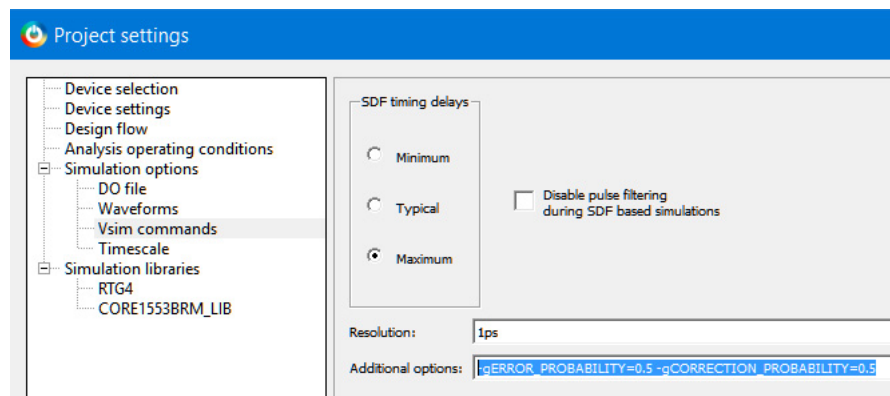
Table 20 • ECC Errors Flag

ECC Error Flag	SB_CORRECT	DB_DETECT
No Error	0	0
Single-bit Error Corrected	1	0
Double-bit Error	1	1

The added logic also ensures the flag outputs from the RAM block are always assigned a value and do not become unknown during periods when the read enable is not asserted high. For more information, see Libero SoC v11.9 SP2, v11.9 SP3, or Libero SoC v12.1 release notes.

The following figure shows the instantiations and connection of the memories along with the exposed ECC flag signals. The RTG4TPSRAM and RTG4URAM are configured for ECC in the non-pipelined mode.

Enable the simulation to report errors, the following options must be added to the vsim command. These are set on the command line when entering the vsim command or through the Libero Project settings as shown in the following figure.

Figure 41 • Libero Project Settings

-gERROR_PROBABILITY

Legal values are - 0 <= value <= 1

The simulation uses a random number generator and compares its value with the value assigned to ERROR_PROBABILITY

SB_CORRECT asserted = '1' indicates a single bit error has occurred.

The assertion rate of SB_CORRECT is directly related to the value of ERROR_PROBABILITY

Increasing the value results in SB_CORRECT being asserted more often.

Decreasing the value results in SB_CORRECT being asserted less often.

-gCORRECTION_PROBABILITY

Legal values are - 0 <= value <= 1

The simulation uses a random number generator and compares its value with the value assigned to

DB_DETECT asserted = '1' indicates more than one bit errors have occurred and could not be corrected.

ERROR_CORRECTION

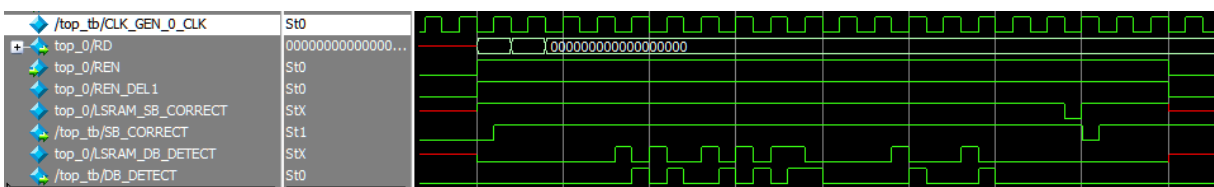
The assertion rate of DB_DETECT is inversely related to the value of CORRECTION_PROBABILITY

Increasing the value results in DB_DETECT being asserted less often.

Decreasing the value results in DB_DETECT being asserted more often.

4.1.8.5.1 TPSRAM Waveforms

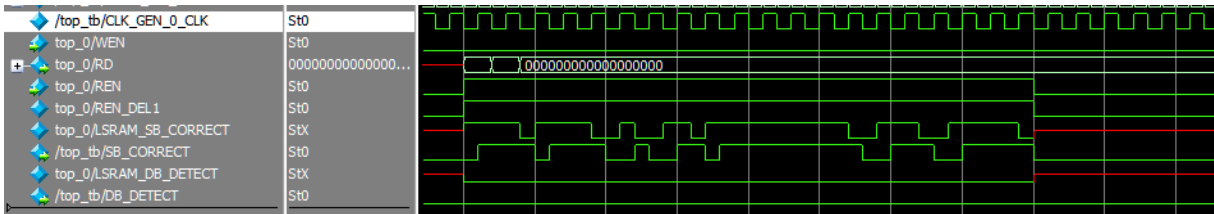
The following waveform was captured with the settings of 0.5 for both ERROR_PROBABILITY and CORRECTION_PROBABILITY. It can be seen that SB_CORRECT signal is high except for one clock during the read period indicating single bit errors were occurring during this time period. The state of DB_DETECT during the same period indicates if these were single bit errors (DB_DETECT = '0') or double bit errors (DB_DETECT = '1').

Figure 42 • TPSRAM: 0.5 Error Probability and 0.5 Correction Probability

The following waveform was captured with the settings of 0.25 for ERROR_PROBABILITY and 0.85 for CORRECTION_PROBABILITY. The new values should cause fewer errors to be asserted on SB_CORRECT and less double bit errors asserted on DB_DETECT. From the following waveform, it can

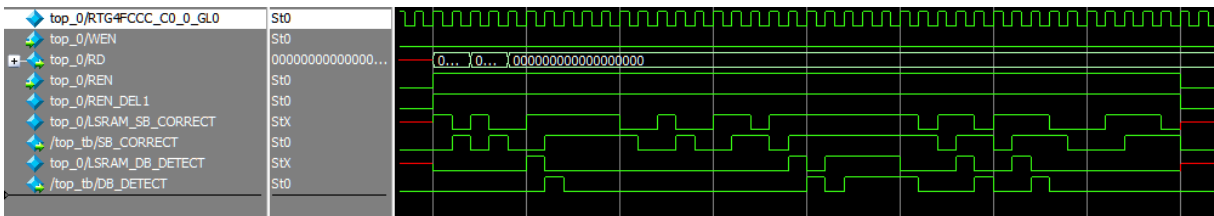
be seen there are fewer errors signaled by the SB_CORRECT signal and fewer (none) signaled by the DB_DETECT signal than in the previous waveform.

Figure 43 • TPSRAM: 0.25 Error Probability and 0.85 Correction Probability



The following waveform was captured with the settings of 0.15 for both ERROR_PROBABILITY and CORRECTION_PROBABILITY. The new values should cause fewer errors to be asserted on SB_CORRECT and more double bit errors asserted on DB_DETECT. From the following waveform, it can be seen there are fewer errors signaled by the SB_CORRECT signal and more signaled by the DB_DETECT signal than in the previous waveform.

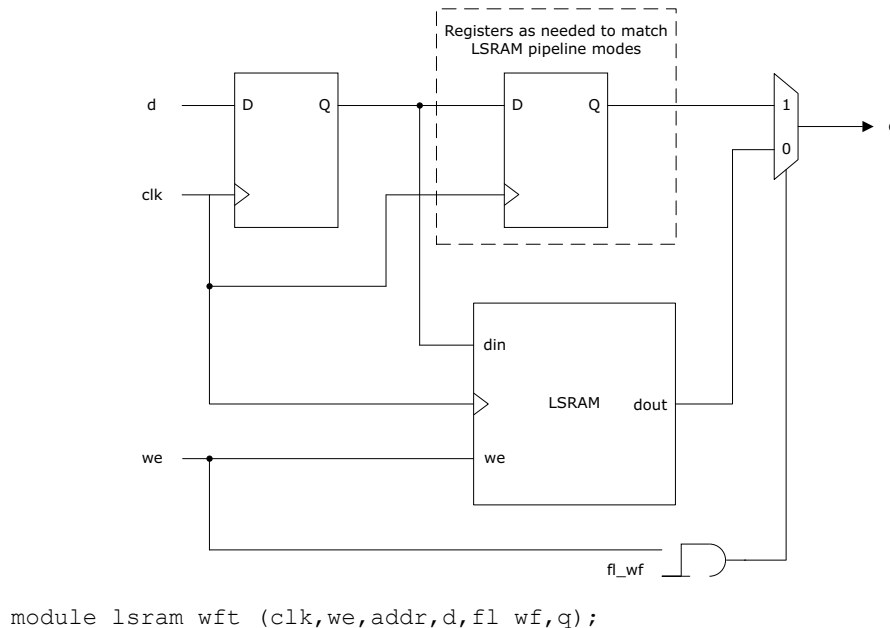
Figure 44 • TPSRAM: 0.15 Error Probability and 0.15 Correction Probability



4.1.9 Use Model: LSRAM Write-Feed-Through using Fabric Logic

The RTG4 LSRAM supports the write-feed-through operation using the fabric logic. The following figure shows the example implementation of write-feed-through fabric logic. The fabric logic consists of extra pipeline registers to match the LSRAM pipeline mode and MUX logic to select write-feed-through operation.

Figure 45 • Sample Write-Feed-Thorough Fabric Logic

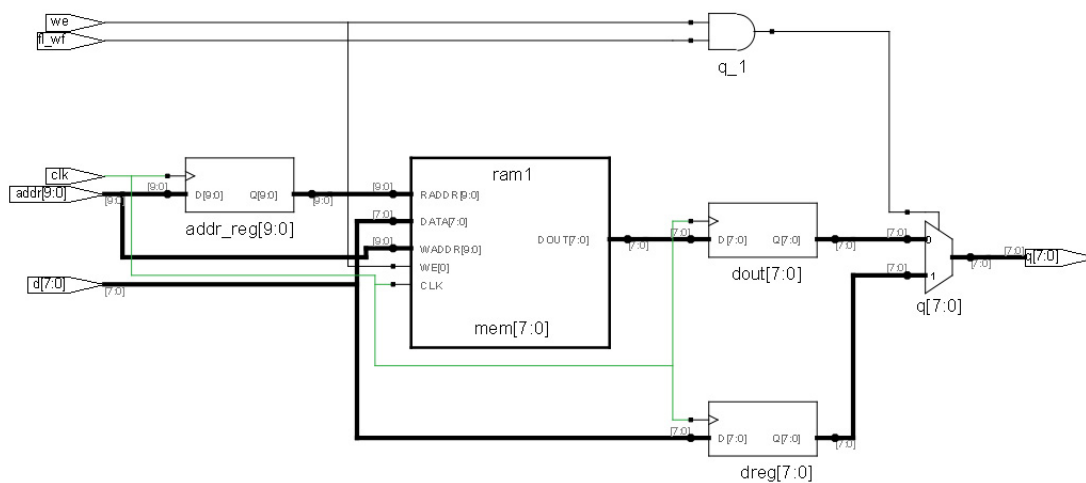


```

input [7:0] d;
input [9:0] addr;
input clk, we;
input fl_wf;
reg [9:0] addr_reg;
output [7:0] q;
reg [7:0] mem [1023:0] ;
reg [7:0] dout;
reg [7:0] dreg;
always @ (posedge clk )
begin
    dreg <= d;
end
always @(posedge clk)
begin
    addr_reg <= addr;
    if (we)
        mem[addr] <= d;
end
always @ (posedge clk )
begin
    dout <= mem[addr_reg];
end
assign q = (fl_wf && we) ? dreg : dout;
endmodule

```

Figure 46 • Write-Feed-Through using Fabric Logic - RTL Schematic View



4.1.10 Debugging LSRAMs Using SmartDebug

RTG4 LSRAM blocks support real-time memory debug using the SmartDebug software. However, depending on the design running in the RTG4 fabric, a debug session using SmartDebug memory debug can inadvertently write incorrect data into the LSRAM being debugged. For example, if the user design has the LSRAM block select (A_BLK[2:0], B_BLK[2:0]) and write enable (A_WEN[1:0], B_WEN[1:0]) inputs enabled when the SmartDebug memory access occurs, the instantaneous transition between user access and SmartDebug access to the LSRAM could result in unintentional writes to the LSRAM. To prevent this undesirable scenario, a manual handshake technique can be employed such that the user logic in the fabric can disable the block select and write enable inputs to the LSRAM before performing a SmartDebug memory debug access. Implementing the manual handshake described below to prevent SmartDebug corruption of the LSRAM being accessed requires HDL modifications to add a gate in the path of the block select and write enable control signals. Therefore, this can negatively impact the timing of the user block select and write enable inputs to the LSRAM. This timing impact must be analyzed during static timing analysis using SmartTime. Although the LSRAM primitive macro contains a BUSY output signal to indicate when an access is occurring, that signal asserts when a memory access starts. To prevent this unintentional write, a signal which transitions before the switch from user access to SmartDebug access must be created. Therefore, the BUSY output would transition too late to prevent this scenario in all cases.

Instead of using the BUSY output, the user can create a manual handshake signal by using a flip-flop whose value can be manually changed using SmartDebug active probe writes. This flip-flop output can be used to gate A_BLK, B_BLK, A_WEN, and B_WEN inputs to the LSRAM by modifying the user HDL. When the user is ready to perform a SmartDebug memory access, they must first use the Active Probe interface in SmartDebug, select the flip-flop which gates the control signals to the RAM they plan to debug, and write a logic-1 into the flip-flop. This disables the fabric block select and write enable to the LSRAM. Once fabric write access to the LSRAM is disabled the user can switch to the SmartDebug Memory Debug tab to perform the memory accesses. After the memory debug is complete, another active probe write is required to set the handshake flip-flop to logic-0, thus re-enabling fabric writes to the LSRAM. The example HDL below shows a module which can be added to the user design, and instantiated once per design or once per logical memory instance to create the handshake signal. Note that there are specific synthesis directives applied to prevent the active_probe_latch SLE from being optimized away during synthesis. The HDL below specifies that the active_probe_latch SLE must be reset to logic-0 during design reset to ensure that the LSRAM write ports are accessible to the user design by default. The RTG4 embedded power-on-reset signal distributed to the SLE ALn input automatically resets the active_probe_latch flip-flop because the code below maps the ADn input to a logic-1. For more information about the SLE_RT truth table, refer to the RTG4 Macro Library Guide (https://www.microsemi.com/document-portal/doc_download/1243102-rtg4-macro-library-guide-with-libero-soc-v11-9-release).

```
module probeWrite (
    RESET_N_IN,
    PRBWR_IN,
    ENABLE_HNDSHAKE,
    HNDSHAKE_OUT
)
    /* synthesis syn_hier = "hard" */;

    input RESET_N_IN;
    input PRBWR_IN;
    input ENABLE_HNDSHAKE;
    output HNDSHAKE_OUT;

    reg active_probe_latch /*synthesis syn_preserve = 1*/;
    wire dummyClk /*synthesis syn_keep=1*/;

    // This latch is to be driven asynchronously by Active Probe Write to 1 or 0
```

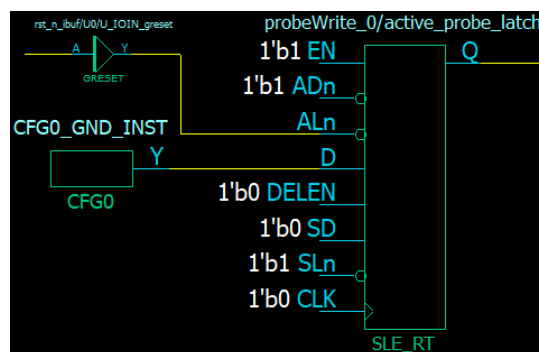
```

always @(posedge dummyClk or negedge RESET_N_IN)
begin
  if (!RESET_N_IN)
    active_probe_latch <= 1'b0;
  else
    active_probe_latch <= PRBWR_IN;
  end
assign HNDSHAKE_OUT = active_probe_latch & ENABLE_HNDSHAKE;
endmodule

```

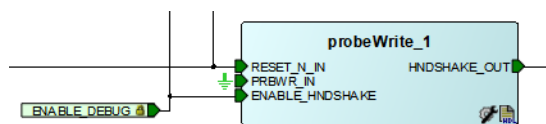
The post-compile netlist view of the active_probe_latch is shown in the following figure:

Figure 47 • Post-Compile Netlist View of active_probe_latch



When instantiating the probeWrite_1 module, the PRBWR_IN input to the active_probe_latch must be statically tied LOW since the writes to this SLE will be driven by SmartDebug Active Probe writes. The HNDSHAKE_OUT signal will only propagate to user logic if the ENABLE_HNDSHAKE input is HIGH. This provides control to enable or disable debug in the design, if required. For example, during design development, it would make sense to tie the ENABLE_HNDSHAKE input HIGH. Once the design is finalized, and debug is no longer required, the ENABLE_HNDSHAKE signal can be driven LOW to prevent the active_probe_latch output from gating-off user writes to the LSRAM. The following figure shows an example instantiation of this module.

Figure 48 • Instantiation of probeWrite_1 module with PRBWR_IN tied LOW



An instantiated LSRAM can be modified to use gated versions of A_BLK, B_BLK, A_WEN, and B_WEN:

```

wire A_BLK_gated, B_BLK_gated, A_WEN_gated, B_WEN_gated;

wire EN_DEBUG;
wire DEBUG_ACTIVE;

assign A_BLK_gated = DEBUG_ACTIVE ? 1'b0 : A_BLK;
assign B_BLK_gated = DEBUG_ACTIVE ? 1'b0 : B_BLK;
assign A_WEN_gated = DEBUG_ACTIVE ? 1'b0 : A_WEN;
assign B_WEN_gated = DEBUG_ACTIVE ? 1'b0 : B_WEN;

probeWrite probeWrite_0(
  // Inputs

```

```

.RESET_N_IN      ( RESET_N ),
.PRBWR_IN        ( 1'b0 ),
.ENABLE_HNDSHAKE ( EN_DEBUG ),
// Outputs
.HNDSHAKE_OUT     ( DEBUG_ACTIVE )
);

```

These gated versions of block select and write enable can then be mapped to the RAM macro block select and write enable ports:

```

RAM1K18_RT myDPRAM (

    .A_BLK({A_BLK_gated, 1'b1, 1'b1}),
    .B_BLK({B_BLK_gated, 1'b1, 1'b1}),
    .A_WEN({A_WEN_gated, A_WEN_gated}),
    .B_WEN({B_WEN_gated, B_WEN_gated}),
);

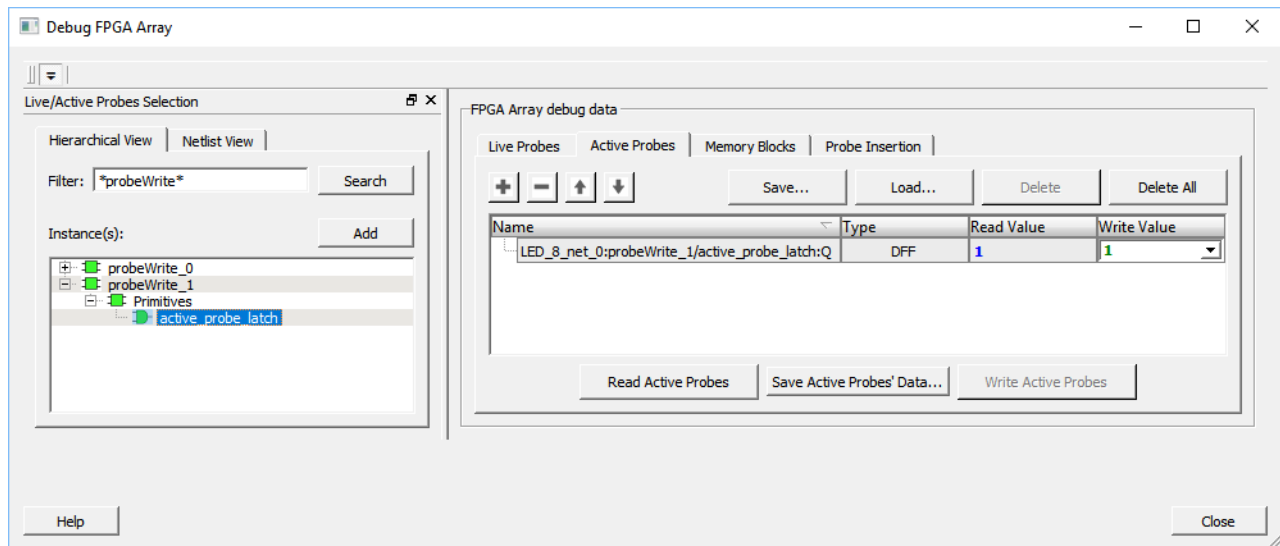
```

Note: Connect any 1 bit of A_BLK[2:0] and B_BLK[2:0] to a logic-0 to turn off that LSRAM port's block select input. The example above shows only 1 bit of the block select input driven by the gated version of A_BLK and B_BLK while the other 2 bits are tied to logic-1.

In contrast, the write enable input can be used on a per-byte basis in some RAM configurations, and thus both bits of A_WEN[1:0] and B_WEN[1:0] should be driven by the gated write enable signal.

The example above demonstrates how the manual handshake signal can be used to disable the write ports of an instantiated LSRAM. This concept can be directly applied to LSRAM blocks which have been manually instantiated in the user HDL. The Dual-port and Two-port Configurators can expose Write Byte Enables directly. In either case, the concept above can be used to disable the block select and write enable inputs to the individual RAM block instances during debug, while maintaining the generated component's port mapping to the individual block select and write enable inputs during normal user operation.

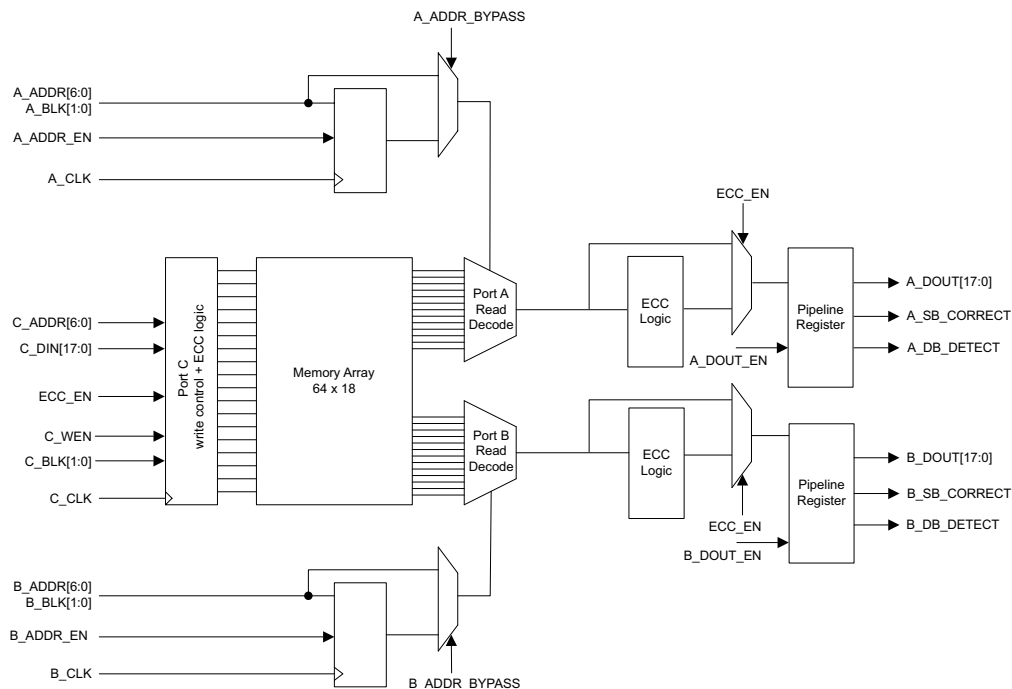
Once the LSRAM is setup to use the gated versions of block select and write enable, the user can employ the Active Probe write in SmartDebug to enable the handshake signal from the active_probe_latch and then perform Memory Debug on the LSRAM.

Figure 49 • Writing a Logic-1 to the active_probe_latch Handshake Signal

4.2 μ SRAM

Each μ SRAM has two read ports and one write port for two-port memory requirements. The following figure shows the μ SRAM diagram.

Figure 50 • Functional Block Diagram of μ SRAM



The following table lists the ports available in μ SRAM.

Table 21 • Port List for μ SRAM

Port Name	Pin Direction	Type ¹	Polarity	Description
Port A				
A_ADDR[6:0]	Input	Dynamic		Port A read address
A_BLK[1:0]	Input	Dynamic	Active high	Port A block selects
A_WIDTH	Input	Static		Port A depth × width mode selection
A_DOUT[17:0]	Output	Dynamic		Port A read-data
A_DOUT_EN	Input	Dynamic	Active high	Port A read-data pipeline register enable
A_DOUT_BYPASS	Input	Static	Active low	Port A pipeline register select
A_DOUT_SRST_N	Input	Dynamic	Active low	Port A read-data pipeline register synchronous-reset
A_CLK	Input	Dynamic	Rising edge	Port A register clock
A_ADDR_EN	Input	Dynamic	Active high	Port A read-address register enable
A_ADDR_BYPASS	Input	Static	Active low	Port A read-address pipeline register select
A_ADDR_SRST_N	Input	Dynamic	Active low	Port A read-address register synchronous-reset
A_SB_CORRECT	Output	Dynamic	Active high	Port A 1-bit error correction flag
A_DB_DETECT	Output	Dynamic	Active high	Port A 2-bit error detection flag

Table 21 • Port List for μ SRAM (continued)

Port Name	Pin Direction	Type ¹	Polarity	Description
Port B				
B_ADDR[6:0]	Input	Dynamic		Port B read-address
B_BLK[1:0]	Input	Dynamic	Active high	Port B block selects
B_WIDTH	Input	Static		Port B depth \times width mode
B_DOUT[17:0]	Output	Dynamic		Port B read-data
B_DOUT_EN	Input	Dynamic	Active high	Port B read-data pipeline register enable
B_DOUT_BYPASS	Input	Static	Active low	Port B read-data pipeline register select
B_DOUT_SRST_N	Input	Dynamic	Active low	Port B read-data pipeline register synchronous-reset
B_CLK	Input	Dynamic	Rising edge	Port B register clock
B_ADDR_EN	Input	Dynamic	Active high	Port B read-address register enable
B_ADDR_BYPASS	Input	Static	Active low	Port B read-address register select
B_ADDR_SRST_N	Input	Dynamic	Active low	Port B read-address register synchronous-reset
B_SB_CORRECT	Output	Dynamic	Active high	Port B 1-bit error correction flag
B_DB_DETECT	Output	Dynamic	Active high	Port B 2-bit error detection flag
Port C				
C_ADDR[6:0]	Input	Dynamic		Port C write address
C_CLK	Input	Dynamic	Rising edge	Port C clock input
C_DIN[17:0]	Input	Dynamic		Port C write-data
C_WEN	Input	Dynamic	Active high	Port C write-enable
C_BLK[1:0]	Input	Dynamic	Active high	Port C block selects
C_WIDTH	Input	Static		Port C depth \times width mode
Common Signals				
ARST_N	Input	Global	Active low	Read-address and read-data pipeline registers asynchronous-reset
ECC_EN	Input	Static	Active high	Enable ECC
ECC_DOUT_BYPASS	Input	Static	Active low	ECC pipeline register select
DELEN	Input	Static	Active high	Enable SET mitigation
SECURITY	Input	Static	Active high	Lock access to system controller
BUSY	Output	Dynamic	Active high	Busy signal from system controller

1. Static inputs are defined at design time and must be tied to 0 or 1.

4.2.1 μ SRAM Read Operation

Read operations are independent of write operations and are performed asynchronously. Synchronous read operations can be performed by using fabric flip-flops as pipeline registers. These flip-flops are located in the associated interface logic at the read address input and read data output.

When the input address (R_ADDR[]) is provided, the output data is available on the output data bus after a read delay. When BLK_EN is high, the read operations are enabled. R_DATA contains the contents of the memory location selected by R_ADDR. When block select is low, the R_DATA is driven to zero.

μSRAM blocks are read through two ports—port A and port B. There are four modes for read operations:

- Synchronous read mode without pipeline registers (Synchronous-Asynchronous mode)
- Synchronous read mode with pipeline registers (Synchronous-Synchronous mode)
- Asynchronous read mode without pipeline registers (Asynchronous-Asynchronous mode)
- Asynchronous read mode with pipeline registers (Asynchronous-Synchronous mode)

4.2.1.1 μSRAM Synchronous Read Operation

Synchronous read mode requires that the input registers for the address and block select inputs are configured in STMR-D flip-flop mode (A_ADDR_BYPASS or B_ADDR_BYPASS = 0). Similarly, on the output side, the pipeline registers can be configured as registered or asynchronous.

When the pipeline registers are enabled, the clock inputs of both the input and output registers must be synchronous to each other and fed with a single clock source. It is recommended to configure the registers as pipeline registers during read operation to avoid glitches on the read output data lines.

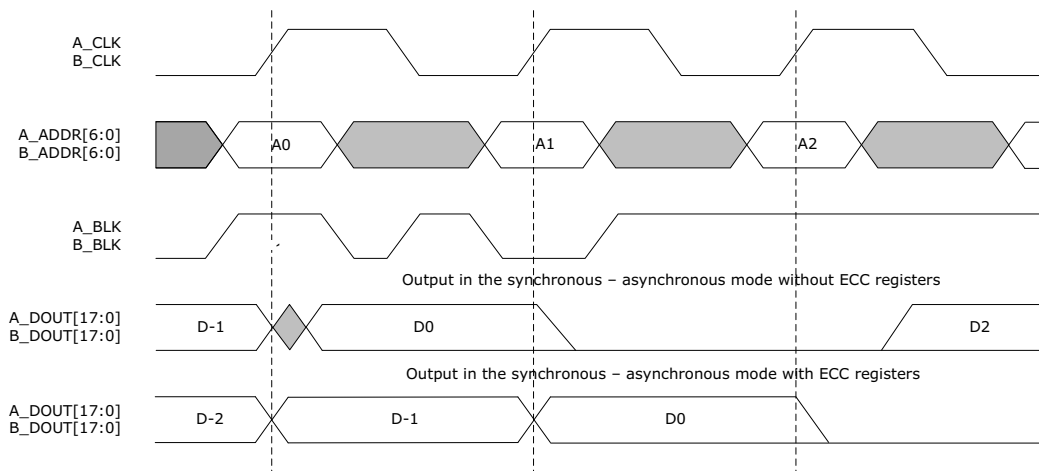
In Synchronous read mode, the address (A_ADDR or B_ADDR) and block select (A_BLK or B_BLK) inputs must satisfy the setup and hold timing with respect to the input clocks (A_CLK or B_CLK).

4.2.1.1.1 Synchronous Read Mode without Pipeline Registers (Synchronous-Asynchronous Read Mode)

- The input registers are configured in synchronous read mode.
- The output pipeline registers are configured as transparent.
- This mode is achieved by configuring the following settings:
 - A_DOUT_BYPASS = 1 or B_DOUT_BYPASS = 1
 - A_ADDR_BYPASS or B_ADDR_BYPASS = 0
 - A_DOUT_SRST_N = 1 or B_DOUT_SRST_N = 1
 - A_DOUT_EN or B_DOUT_EN = 1
 - A_BLK = 1, B_BLK = 1
- The output data is displayed immediately in the same clock cycle in which the address and block select inputs were registered.
- The μSRAM block can generate glitches on the output buses when used without the pipeline registers.

The following figure shows the timing waveforms for synchronous-asynchronous read operation without pipeline registers.

Figure 51 • Synchronous-Asynchronous Read Operation without Pipeline Registers

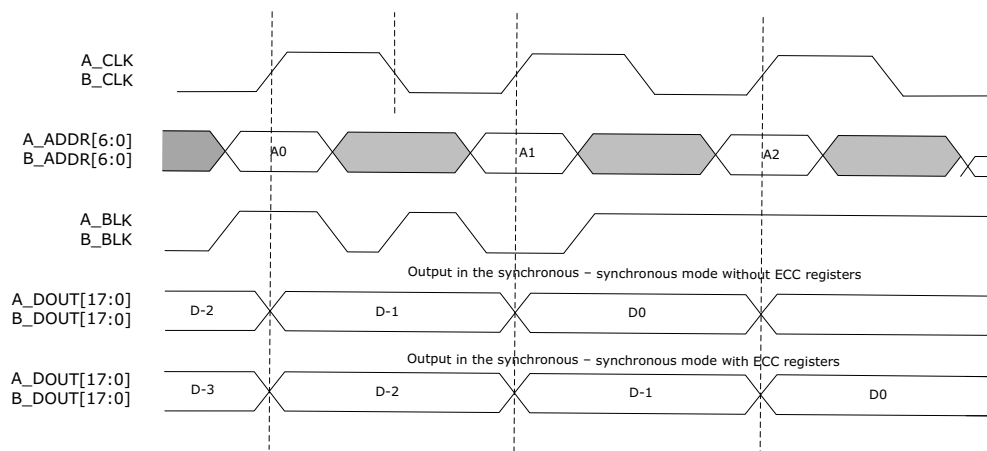


4.2.1.1.2 Synchronous Read Mode with Pipeline Registers (Synchronous-Synchronous Read Mode)

- The input registers are configured in synchronous read mode.
- The output pipeline registers are configured as edge-triggered registers (Pipelined mode).
- Pipelined mode is achieved by making the following settings:
 - A_DOUT_BYPASS or B_DOUT_BYPASS = 0
 - A_ADDR_BYPASS or B_ADDR_BYPASS = 0
 - A_DOUT_SRST_N = 1 or B_DOUT_SRST_N = 1
 - A_DOUT_EN or B_DOUT_EN = 1
 - A_BLK = 1, B_BLK = 1
- The input register clock and pipeline register clock must be synchronous to each other; hence they must be sourced from the same clock input.
- The output data appears on the output bus in the next clock cycle.

The following figure shows the timing waveforms for synchronous-synchronous read operation with pipeline registers.

Figure 52 • Synchronous-Synchronous Read Operation with Pipeline Registers



4.2.1.2 μ SRAM Asynchronous Read Operation

Asynchronous read mode requires that the input registers for the address and block-select inputs are configured in asynchronous mode by configuring the following:

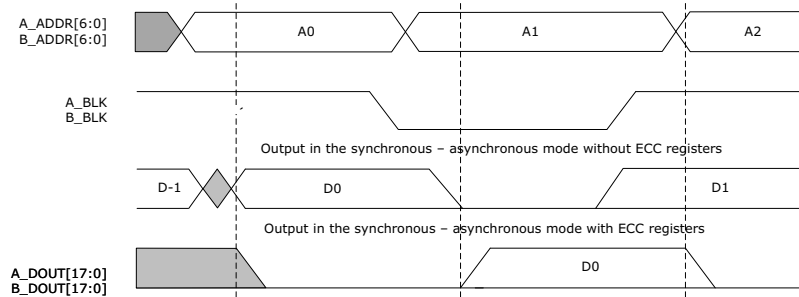
- A_ADDR_BYPASS or B_ADDR_BYPASS = 1
- A_ADDR_SRST_N or B_ADDR_SRST_N = 1
- A_BLK = 1, B_BLK = 1

4.2.1.2.1 Asynchronous Read Mode without Pipeline Registers (Asynchronous-Asynchronous Mode)

- The input registers are configured in asynchronous read mode.
- The output pipeline registers are configured as transparent (non-pipelined operation).
- The pipeline registers can be made transparent by making the following settings:
 - A_DOUT_BYPASS or B_DOUT_BYPASS = 1
 - A_ADDR_BYPASS or B_ADDR_BYPASS = 1
 - A_DOUT_SRST_N = 1 or B_DOUT_SRST_N = 1
 - A_DOUT_EN or B_DOUT_EN = 1
- The μ SRAM block can generate glitches on the data output bus when used without the pipeline register.

The following figure shows the timing diagram for asynchronous-asynchronous read mode for μ SRAM.

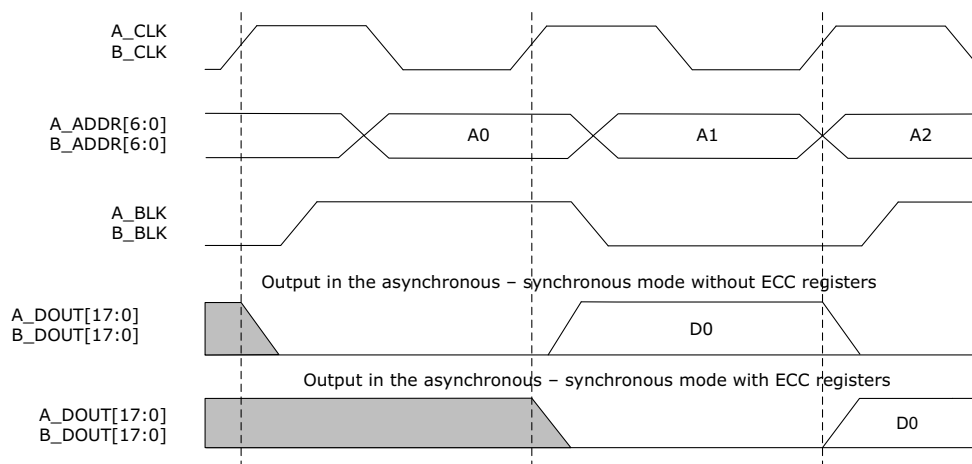
Figure 53 • Asynchronous Read Operation without Pipeline Registers Waveform



4.2.1.2.2 Asynchronous Read Mode with Pipeline Registers (Asynchronous-Synchronous Mode)

- The input registers are configured in asynchronous read mode.
- The output pipeline registers are configured as registers (Pipelined mode).
- Pipelined mode is achieved by configuring the following settings:
 - A_DOUT_BYPASS or B_DOUT_BYPASS = 0
 - A_ADDR_BYPASS or B_ADDR_BYPASS = 1
 - A_DOUT_SRST_N = 1 or B_DOUT_SRST_N = 1
 - A_DOUT_EN or B_DOUT_EN = 1
 - A_BLK = 1, B_BLK = 1
- After the input address is provided, the output data is displayed on the output data bus after the next rising edge of the pipeline register input clock.

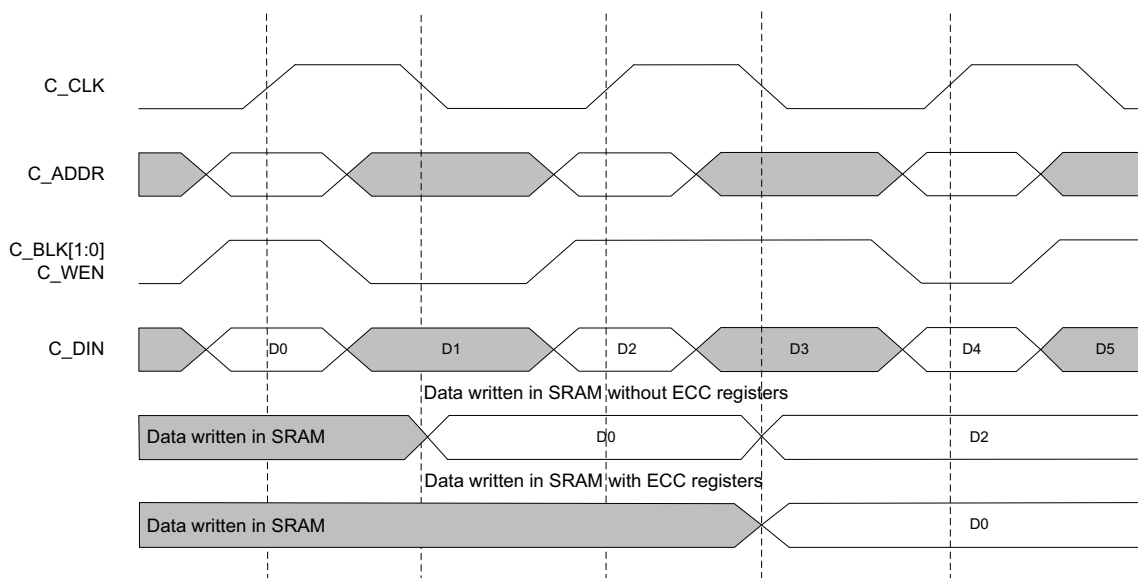
The following figure shows the timing diagram for asynchronous-synchronous read mode for μ SRAM.

Figure 54 • Asynchronous Read Operation with Pipeline Registers Waveform

4.2.2 μ SRAM Write Operation

- μ SRAM write operation can be performed through Port C only.
- The write operation is purely synchronous and all operations are synchronized to the rising edge of the port C clock input (C_CLK).
- The write inputs, C_ADDR, C_BLK, C_WEN, and C_DIN, have to satisfy the setup and hold timings with respect to the rising edge of the C_CLK input for a successful write operation.
- If all the inputs meet the required timing parameters, the input data is written into μ SRAM in one clock cycle.

The following figure shows the timing waveforms for a port C write operation.

Figure 55 • μ SRAM Write Operation

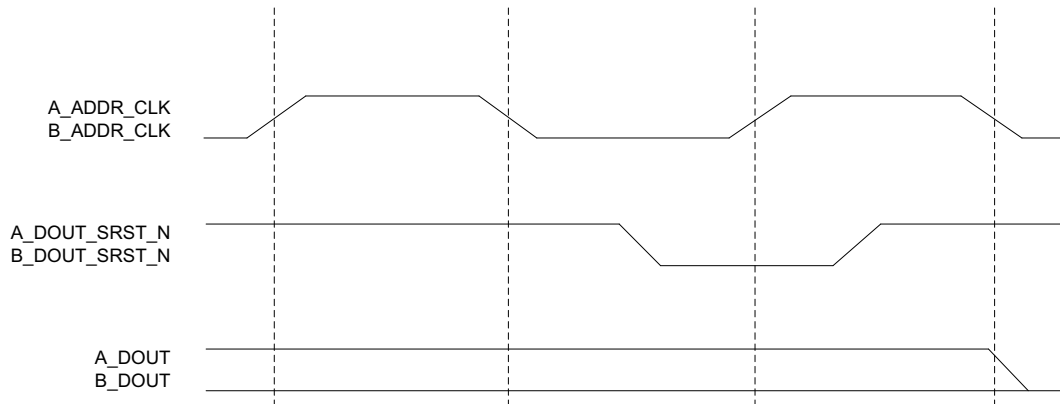
4.2.3 μ SRAM Synchronous Reset Operation

Each pipeline register has one synchronous reset. A_DOUT_SRST_N and B_DOUT_SRST_N drive the synchronous reset of the data output pipeline registers—A_DOUT and B_DOUT. If the synchronous pipeline reset is low, the pipeline data output registers are reset to zero on the next valid clock edge.

The reset signals (A_ADDR_SRST_N and B_ADDR_SRST_N) are synchronous Active Low signals for the address and block select input registers for port A and port B. The assertion of these reset signals forces the address and block select input registers to logic 0, which in turn forces the data output to logic 0.

The following figure shows the timing waveform for synchronous reset.

Figure 56 • μ SRAM Synchronous Reset Operation



4.2.4 μ SRAM Asynchronous Reset Operation

The global reset signal (ARST_N) is an asynchronous Active Low signal. For any normal operation of μ SRAM, the reset signal must be set to high. To reset the μ SRAM block, the reset signals must be set to Low.

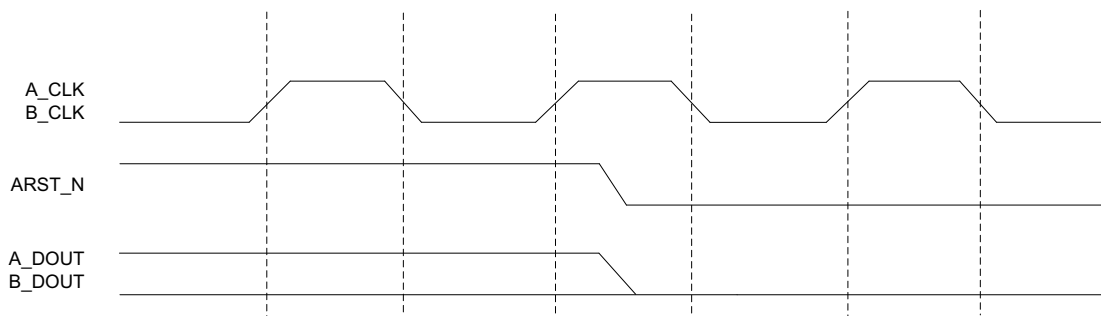
When reset is asserted (ARST_N forced Low), the μ SRAM block behaves as follows during read and write operations:

- **Read operation:** If reset is asserted when the read operation is in process, the data output port is forced low after a specified delay. If the clock is high and the reset signal is asserted and then de-asserted in the same high clock phase or low clock phase, the data output stays low until the next cycle. The data output changes its state only if a read or write operation in bypass mode is performed on the μ SRAM block. In a simple write operation, the data output stays low.
- **Write operation:** If reset is asserted during the write operation, then the corrupted data is written into the memory. It is recommended to avoid asserting the reset signal during the write operation.

All data stored in the array is lost during a global reset. The contents of the array must be considered unknown until a valid write operation.

The following figure shows the asynchronous reset operation.

Figure 57 • μ SRAM Asynchronous Reset Operation



4.2.5 μ SRAM ECC

μ SRAM has error detection and correction logic circuitry (1-bit error correction, 2-bit error detection) and it is available for the $\times 18$ only. Setting the ECC enable (ECC_EN) to high turns On the ECC circuitry and ECC pipeline stages.

The ECC encoder provides 24 bits of data for $\times 18$ mode. The ECC decoder reads 24 bits from the array and provides 18 corrected bits on the output.

If the ECC has detected an error, choose to correct the data in the μ SRAM block. The writing of the correct data is called 'Scrubbing'. Scrubbing is not available inside the μ SRAM. All scrubbing must be done in the fabric design.

Both the ECC encoder and ECC decoder contain independent pipeline registers, which add a clock cycle of latency to each of the read and write operations. These pipeline registers may be bypassed for slower operation. If pipeline modes are enabled, the ECC flags will be unknown values on subsequent invalid clock cycles until a valid data out clock cycle.

The ECC encoder generates two flags per port, an error correction flag (A_SB_CORRECT, B_SB_CORRECT) that is set to high when a single bit in a word is corrected and an error detection flag (A_DB_DETECT and B_DB_DETECT) that is set to high when two or more bit errors in a word are detected, but not corrected.

Note: The user logic must correct RAM contents if the single or double bit errors are detected.

The following table lists the error types and flag status.

Table 22 • μ SRAM Error Flag Status

Error Type	Error Flag Status
No error	A/B_SB_CORRECT = 1'b0
	A/B_DB_DETECT = 1'b0
Single-bit error	A/B_SB_CORRECT = 1'b1
	A/B_DB_DETECT = 1'b0
Double-bit error	A/B_SB_CORRECT = 1'b1
	A/B_DB_DETECT = 1'b1

4.2.6 Using μ SRAM in a Design

An μ SRAM block can be implemented in a design by the following methods:

- RTL Inference during Synthesis
- Inserting an μ SRAM Configurator component

4.2.6.1 RTL Inference during Synthesis

Synplify Pro can infer an μ SRAM and automatically set the configuration for various modes, if the RTL design contains an array of at least 12 bits. Also infers the specific RAM by using the synthesis attribute (`syn_ramstyle`). Synthesis ensures that the signals of the μ SRAM are properly connected to the rest of the design and sets the correct values for the static signals needed to configure the appropriate operational mode. The tool ties unused dynamic input signals to low.

Synplify Pro can cascade multiple μ SRAM blocks if the required memory size exceeds the limit of a single μ SRAM block. It can also absorb any registers at the μ SRAM interface if they are driven by the same clock. If the registers have different clocks, then the clock that drives the output register has priority, and all registers driven by that clock are absorbed into the μ SRAM block. If the outputs are unregistered and the inputs are registered with different clocks, the input registers with the larger input have priority and are absorbed into the μ SRAM block. For more information on μ SRAM inference by Synplify Pro, see [Inferring Microsemi RTG4 RAM Blocks Application Note](#).

4.2.6.2 Inserting an μ SRAM Configurator Component

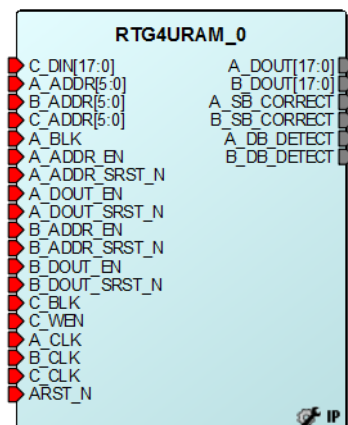
The RTG4 μ SRAM configurator is available in the Libero SoC software under Memory & Controllers. [Figure 58](#) shows μ SRAM available in the Libero SoC software. The RAM configurator automatically cascades μ SRAM blocks to create wider and deeper memories by selecting the most efficient aspect ratio. It also handles the grounding of unused bits. The core configurator supports the generation of memories that have different write and read aspect ratios. The configurator uses one or more memory blocks to generate a RAM matching the configuration. In addition, it also creates the surrounding cascading logic.

The configurator cascades RAM blocks in three different methods:

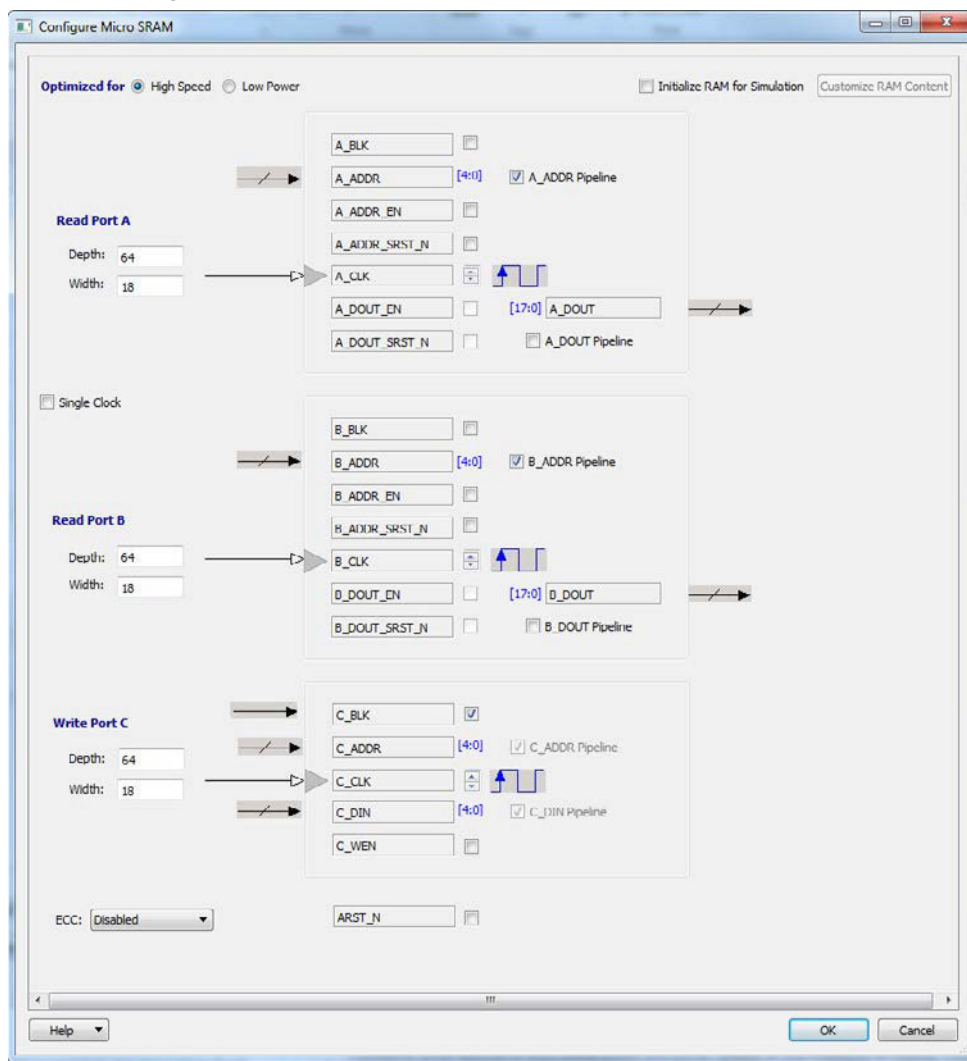
- Cascaded deep. For example, two blocks of 64×12 to create a 128×12 .
- Cascaded wide. For example, two blocks of 64×12 to create a 64×24 .
- Cascaded wide and deep. For example, four blocks of 64×12 to create a 128×24 , in two blocks width-wise by two blocks depth-wise configuration.

The core configurator only supports depth cascading up to 32 blocks. Write operations are synchronous for setting up the address, and writing the data. The memory write operations will be triggered at the rising edge of the clock.

Read operations can be either asynchronous or synchronous (for setting up the address and reading the data). An optional pipeline register is available for the read-address to improve the setup. An optional pipeline register is available at the read data to improve the clock-to-output delay. Disabling both the address and read data registers creates the asynchronous mode for read operations. For synchronous read operations, the memory read operations will be triggered at the rising edge of the clock. The RTG4 μ SRAM Smart IP is available in the Libero SoC software catalog under **Memory & Controllers** section. The following figure shows the μ SRAM IP macro available in Libero SoC. See **RTG4 Micro SRAM Configurator User Guide** for more information about software configuration for μ SRAM.

Figure 58 • μ SRAM Configurator in Libero SoC

In this section, it is described how to configure an μ SRAM instance and define how the signals are connected.

Figure 59 • μ SRAM Configurator

4.2.6.2.1 Optimization of High Speed or Low Power

The user can optimize the μ SRAM macro with one of the following options:

- **High Speed** - To optimize the μ SRAM macro for speed and area by using width cascading.
- **Low Power** - To optimize the μ SRAM macro for low power, but it uses additional logic at the input and output by using depth cascading. Performance for a low power optimized macro may be inferior to that of a macro optimized for speed.

4.2.6.2.2 Port A Depth/Width and Port B Depth/Width

The user can set depth and width of a port.

- **Depth** - To set depth range. The depth range for each port is 1 to 4096. The maximum value depends on the die.
- **Width** - To set width range. The width range for each port is 1 to 3780.

Note: The three ports can be configured independently for any depth and width. Port A depth \times port A width must be equal to port B depth \times port B width must be equal to port C depth \times port C width. The width range varies between devices.

4.2.6.2.3 Single Clock (CLK) or Independent Write and Read Clocks (A_CLK, B_CLK, and C_CLK)

The user can set the clock signals:

- Check **Single Clock** to drive both A, B, and C ports with the same clock. This is the default configuration for dual-port μ SRAM. Uncheck **Single Clock** to enable independent clock for each port—A_CLK, B_CLK, and C_CLK.
- Click the waveform next to any of the clock signals to toggle its active edge.

4.2.6.2.4 Block Select for Ports A and B (A_BLK and B_BLK)

De-asserting A_BLK forces A_DOUT to zero. De-asserting B_BLK forces B_DOUT to zero.

- Asserting A_BLK reads the RAM at the address given by the output of the A_ADDR register onto the input of the A_DOUT register.
- Asserting B_BLK reads the RAM at the address given by the output of the B_ADDR register onto the input of the B_DOUT register.

The default configuration for A_BLK and B_BLK is unchecked, which ties the signal to the active state and removes it from the generated macro. Click the respective checkbox to insert that signal on the generated macro. Click the signal arrow (when available) to toggle its polarity.

4.2.6.2.5 Block Select for Port C (C_BLK) and Write Enable (C_WEN)

Asserting C_BLK when C_WEN is high writes the data C_DIN into the RAM at the address C_ADDR on the next rising edge of C_CLK.

Unchecking the C_BLK option ties the signal to the active state and removes it from the generated macro. Click the signal arrow (when available) to toggle its polarity.

The default configuration for C_WEN is unchecked, which ties the signal to the active state and removes it from the generated macro. Click the C_WEN checkbox to insert that signal on the generated macro.

Click the signal arrow (when available) to toggle its polarity.

4.2.6.2.6 Pipeline for Read Address for Ports A and B

The default configuration for μ SRAM is to enable the Pipeline of Read address (A_ADDR or B_ADDR). Uncheck the Pipeline option to turn off pipelining. This is a static selection and cannot be changed dynamically by driving it with a signal.

Turning off pipelining of Read address of a port also disables the configuration options of the respective ADDR_EN and ADDR_SRST_N signals.

4.2.6.2.7 Pipeline for Read Data Output for Ports A and B

Check the **A_DOUT Pipeline** or **B_DOUT Pipeline** checkbox to enable pipelining of Read data (A_DOUT or B_DOUT). If the checkbox is not checked, the user cannot configure the A_DOUT_EN/B_DOUT_EN, A_DOUT_SRST_N/B_DOUT_SRST_N, or A_DOUT_ARST_N/B_DOUT_ARST_N signals. This is a static selection and cannot be changed dynamically by driving it with a signal.

4.2.6.2.8 Register Enable (A_ADDR_EN, A_DOUT_EN, B_ADDR_EN and B_DOUT_EN)

The address and pipeline registers for ports A and B have active high, enable inputs. The default configuration is to tie these signals to the active state and remove them from the generated macro. Use the signal arrow (when available) to toggle its polarity.

4.2.6.2.9 Synchronous Reset (A_ADDR_SRST_N, A_DOUT_SRST_N, B_ADDR_SRST_N and B_DOUT_SRST_N)

The address and pipeline registers for ports A and B have active low, synchronous reset inputs. The default configuration is to tie these signals to the inactive state and remove them from the generated macro. Use the signal arrow (when available) to toggle its polarity.

4.2.6.2.10 Asynchronous Reset (ARST_N)

The address and pipeline registers for ports A and B have an active low, asynchronous reset input. The default configuration is to tie this signal to the inactive state and remove it from the generated macro. Use the signal arrow (when available) to toggle its polarity.

Note: ARST_N does not reset the memory contents. It resets only the pipeline registers for Read Data.

4.2.6.2.11 Error Correction Code (ECC)

The following three error correction code (ECC) options are available:

- Disabled
- Pipelined
- Non-Pipelined

Note: When ECC is enabled (Pipelined or Non-Pipelined), both ports have data widths equal to 18 bits. The SB_CORRECT and DB_DETECT output ports are exposed when ECC is enabled. When ECC is disabled, each port can be configured to either 18 bits or 9 bits width. Alternatively, all three ports can be configured to 12 bits width.

4.2.6.2.12 Initialize RAM for Simulation

The user can initialize RAM for simulation by setting the following:

- **Initialize RAM for Simulation** - To load the RAM content during simulation.
- **RAM Configuration** - Both write and read depths and widths are displayed as specified in the Port setting tab.
- **Initialize RAM Contents From File** - The RAM Content can be initialized by importing the memory file. It avoids the simulation cycles required for initializing the memory and reduces the simulation runtime. The configurator partitions the memory file appropriately so that the right content goes to the right block RAM when multiple blocks are cascaded.
- **Import File** - To select and import a memory content file (Intel-Hex) from the Import Memory Content dialog box. File extensions are set to *.hex for Intel-Hex files during import. See Appendix: Supported Memory File Formats. The imported memory content is displayed in the RAM Content Editor.
- **Reset All Values** - Resets all the data values.

4.2.6.2.13 RAM Configuration

The RAM Content Manager enables the user to specify the contents of RAM memory manually for both port A and port B. It avoids the simulation cycles required for initializing the memory and reduces the simulation runtime. It also allows the user to modify the imported data.

Port A View/Port B View

- **Go To Address** - Enables to go to a specific address in the editor. User can select the number display format (HEX, BIN, DEC) from the drop-down menu.
- **Default Value Data** - User can change the default data value by setting this with new data. When the data value is changed, all default values in the manager are updated to match the new value. User can select the number display format (HEX, BIN, DEC) from the drop-down menu.
- **Address** - The Address column lists the address of a memory location. The drop-down menu specifies the number format of the address list (hexadecimal, binary, or decimal).
- **Data** - To control the data format and data value in the manager.

Note: The dialogs show all data with the MSB down to LSB. For example, if the row showed 0xAABB for a 16-bit word size, the AA is MSB and BB is LSB.

- Click **OK** to close the manager and save all the changes made to the memory and its contents.
- Click **Cancel** to close the manager by canceling all the changes.

4.2.7 Collision Behavior

Collision between ports occurs when the read and write operations are requested from two or all three ports at the same time at the same address location. [Table 23](#), page 67 lists the different scenarios for collision.

Table 23 • Collision Scenarios

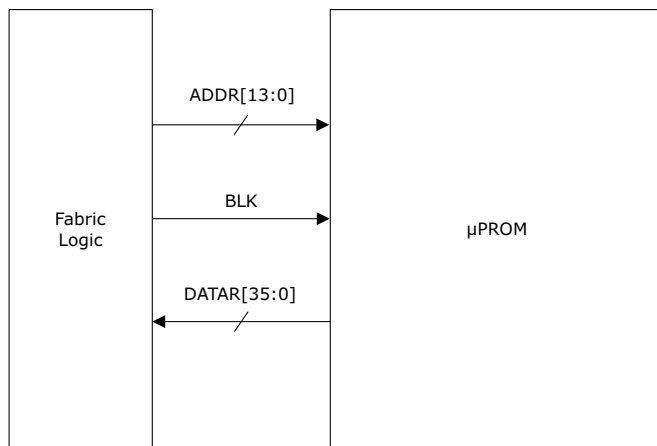
Operation	Comments
Simultaneous read from Port A and read from Port B to the same address location	Allowed since the read ports are independent of each other. Both read ports deliver correct read data.
Simultaneous read from Port A and write to Port C to the same address location	Collision occurs. The write operation works correctly but the read operation from Port A generates ambiguous data output unless the clock cycle is long enough to allow the newly written data to be read.
Simultaneous read from Port B and write to Port C to the same address location	Collision occurs. The write operation works correctly but the read operation from Port B generates ambiguous data output unless the clock cycle is long enough to allow the newly written data to be read.
Simultaneous read from Port A, read from Port B, and write to Port C to the same address location	Collision occurs. The write operation works correctly but the read operation from both the ports generates ambiguous data output unless the clock cycle is long enough to allow the newly written data to be read.

The user must take measures to avoid the last three scenarios because μ SRAM architecture does not support collision prevention or detection.

4.3 μ PROM

RTG4 devices have a single μ PROM row located at the bottom of the fabric, providing up to 374,400 Bits of non-volatile, read-only memory. The address bus is 14 bits wide, and the read data bus is 36-bit wide. Fabric logic has access to the entire μ PROM data. The following figure shows a simplified block diagram of μ PROM.

Figure 60 • Functional Block Diagram of μ PROM



The following table lists μ PROM ports.

Table 24 • Port List for the μ PROM Configurator

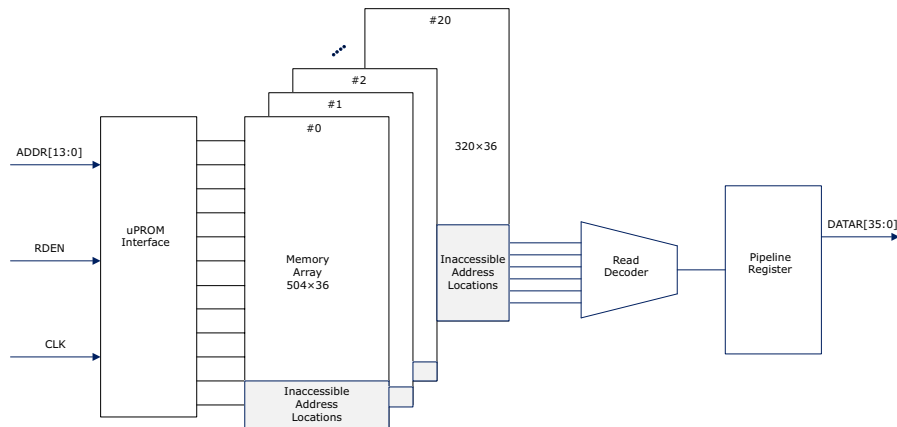
Port Name	Direction	Descriptions	Polarity
ADDR[13:0]	Input	Address input	
CLK	Input	Clock input	Rising edge
RDEN	Input	Read Enable	Active high
DATAR[35:0]	Output	Data output	

4.3.1 μ PROM Architecture and Address Space

Architecturally, μ PROM is structured in 21 different memory arrays with 14-bit addressing. Each array is 512×36 bit words. In the first 20 memory arrays, the last eight words are not user accessible. Therefore, for the first 20 memory arrays (#0 - #19), the size of each memory array is 504×36 . In the last memory array (#20), there are 192 words that are not user accessible. Therefore, the size of memory array #20 is 320×36 . Because there are user inaccessible addresses in the array, the addressing scheme for the μ PROM is not contiguous.

The following figure shows a simplified block diagram of the μ PROM memory.

Figure 61 • μ PROM Memory Blocks



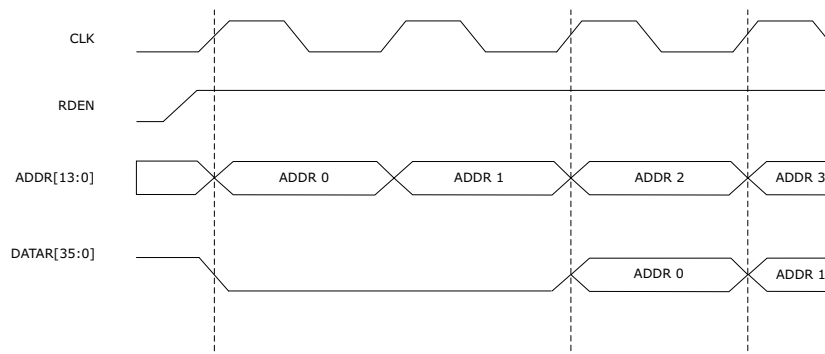
To make μ PROM addressing easy for the user, the μ PROM configurator takes the user-specified contiguous address and automatically translates that address into the μ PROM addressing scheme. Inaccessible addresses are skipped. The address translation is transparent to the user and takes up about 80 4-LUTs from the fabric resources.

4.3.2 μ PROM Operation

In μ PROM, the write operation (program/erase) is performed during FPGA configuration. To configure the μ PROM, the Libero SoC μ PROM configurator writes the memory file (*.mem) to the configuration bitstream. The memory file can be a plain text or cipher text/encrypted bit file. The device programmer (FlashPro5 or above) writes this memory file to μ PROM during FPGA programming. Read operations are performed only through the fabric interface. There is a TMR register at both address input and read data output.

The following figure shows the read timing diagram for the μ PROM.

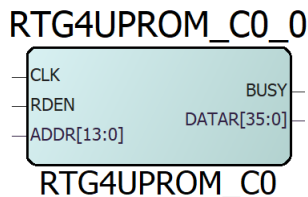
Figure 62 • μ PROM Read Operation



4.3.3 μ PROM Configurator

The RTG4 μ PROM Smart IP is available in the Libero SoC software catalog under Memory & Controllers. The following figure shows the μ PROM IP macro block. See [RTG4 \$\mu\$ PROM Configuration User Guide](#) for more information about software configuration for μ PROM.

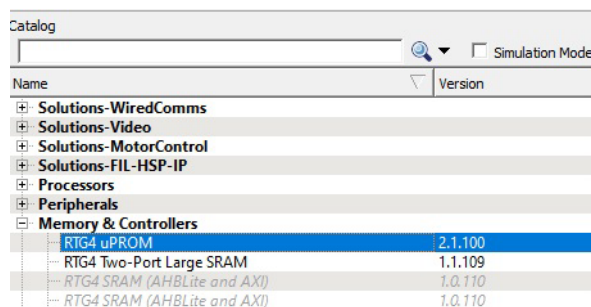
Figure 63 • μ PROM Configurator in Libero SoC



To invoke the configurator:

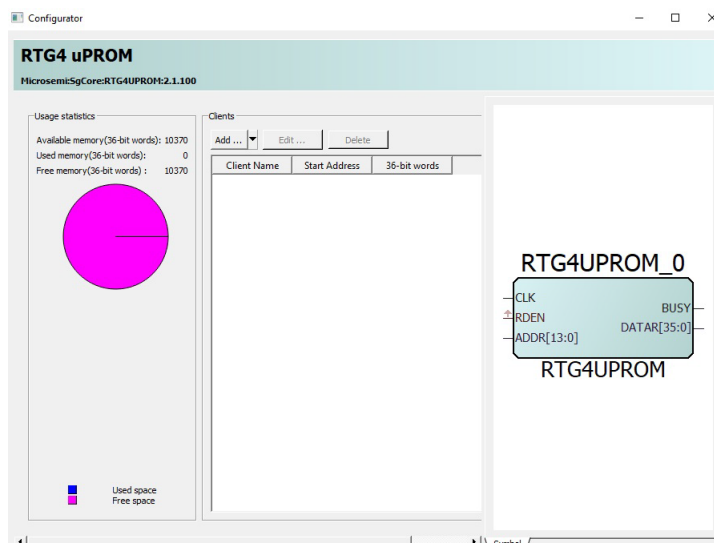
1. Expand **Memory & Controllers** in the Catalog.

Figure 64 • RTG4 μ PROM Core in Catalog



2. Do one of the following to invoke the μ PROM Configurator:
 - Double-click or right-click RTG4 μ PROM and select **Instantiate in <design_name>** to instantiate the μ PROM in the SmartDesign canvas.
 - Double-click or right-click RTG4 μ PROM and choose **Configure Core**. Enter a component name for the μ PROM when prompted.

Figure 65 • μ PROM Configurator



3. In the μ PROM Configurator, click **Add Clients to System** to add a Client to the μ PROM.

4.3.3.1 Usage Statistics

Usage statistics display the total memory size of the μ PROM, the size of used memory and available free memory. All memory sizes are expressed in terms of the number of 36-bit words.

4.3.3.2 Available Memory

The μ PROM can hold 10,400 36-bit words (total 374,400 bits).

4.3.3.3 Used Memory

When the user adds memory clients, the used memory displays the total amount of memory (number of 36-bit words) used by all clients. This is indicated in blue in the pie chart.

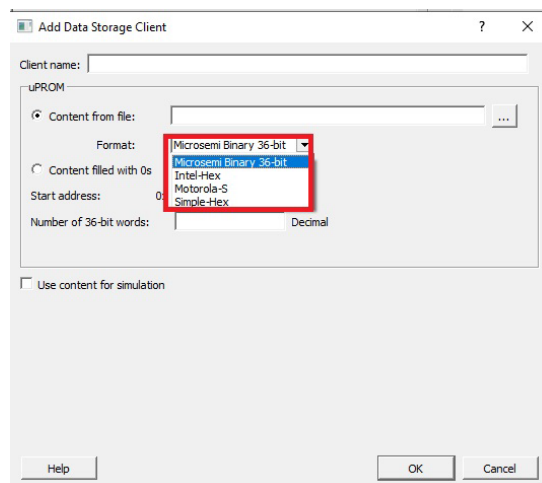
4.3.3.4 Free Memory

Free memory (number of 36-bit words) is displayed in magenta in the pie chart.

4.3.3.5 Add Clients to System

1. Click **Add Clients to System** to open the **Add Data Storage Client** dialog box, see the following figure.
2. Specify the start address, client size, content of the client, and whether or not to use the memory content for simulation.

Figure 66 • Add Data Storage Client Dialog Box



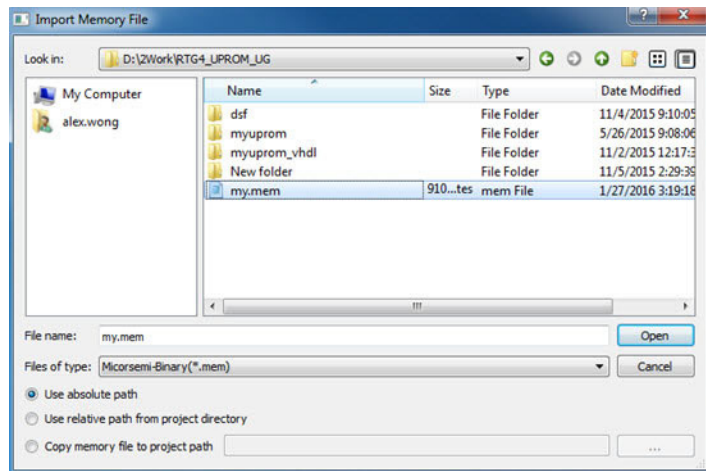
4.3.3.5.1 Client Name

Enter a name of the memory client.

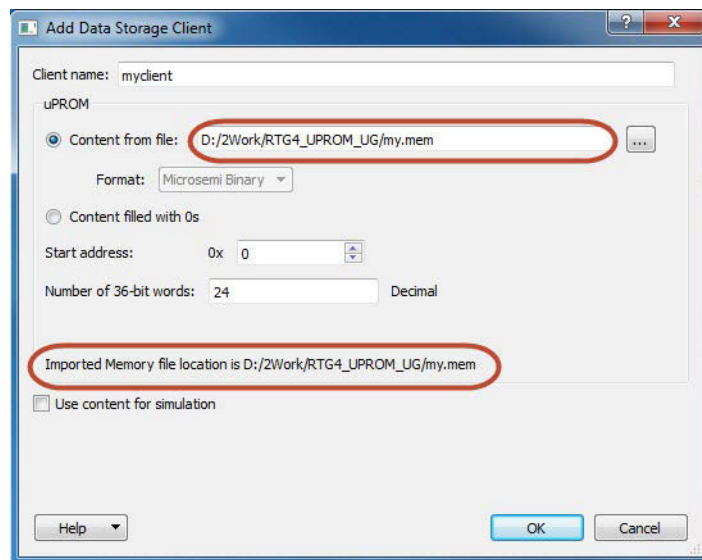
4.3.3.5.2 Content from File

Import the memory client from a memory file with this option. Click **Browse** to navigate to the location of the memory file to import. Select the memory file and click **Open**.

Note: The memory file must have the *.mem file extension.

Figure 67 • Import Memory File Dialog Box**Use Absolute Path**

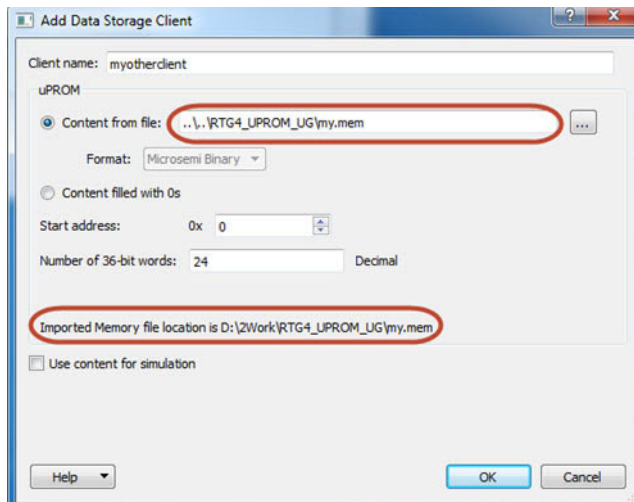
When selected, the Absolute Path of the Memory File appears in the Content from File field.

Figure 68 • Absolute Path of Memory File**Use Relative Path from Project Directory**

When selected, the relative path of the memory file (relative to the Project location) imported appears in the **Content from file** field.

Note: On the Windows systems, if the memory file and the Project location are on different drives, the Absolute Path is used even if the Relative Path is selected.

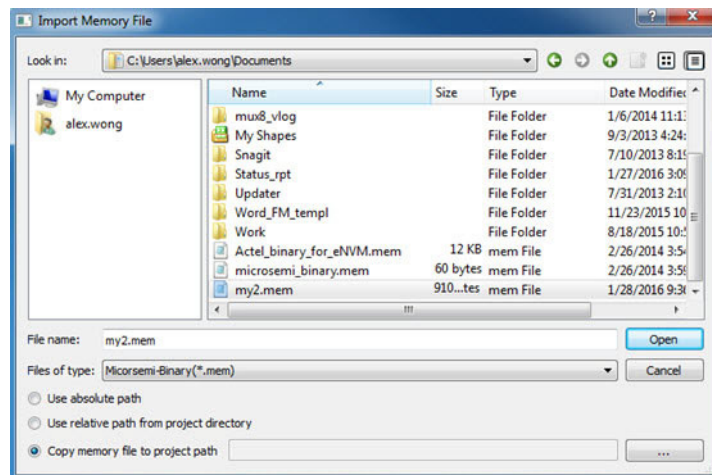
Figure 69 • Relative Path of Memory File



Copy Memory File to Project Path

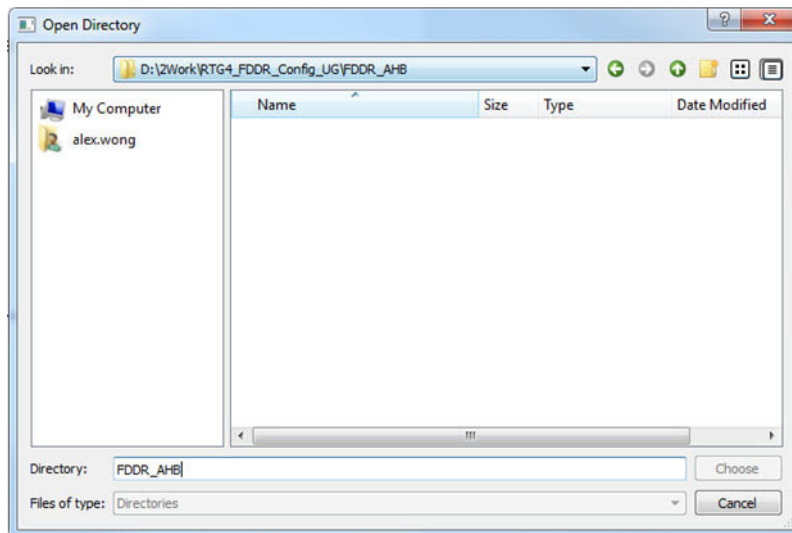
Select this option and click the **Browse** to navigate to the location of the memory file to copy from. The memory file is copied to the project location.

Figure 70 • Location of Memory File to Copy From



Note: The memory file cannot be copied to and stored in the project's sub-folders: component, smartgen, synthesis, designer, simulation, stimulus, tooldata, and constraint. To prevent users from inadvertently copying the memory file into these sub-folders, these project sub-folders are hidden from view when you select the project folder.

Figure 71 • Project Sub-Folders Hidden from View



Note: The copied memory file path is internally stored as relative path.

Note: If the memory file is copied to the project, the user must update the content of the Memory File.

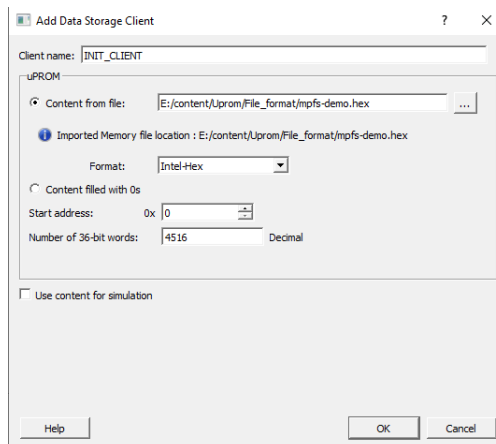
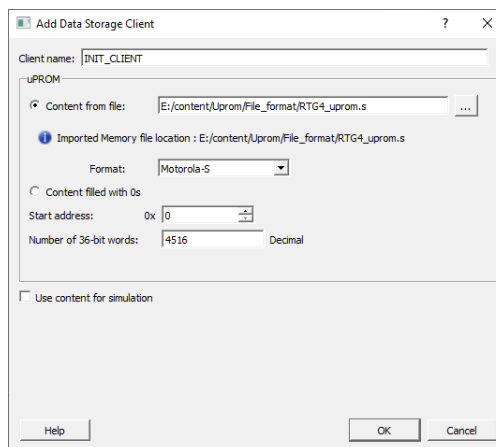
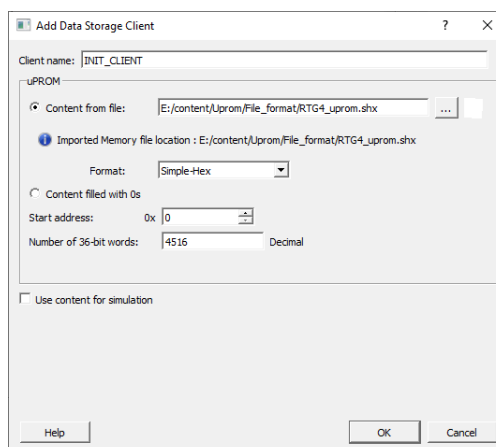
μPROM supports only the Microsemi binary format (* .mem) for the memory content. The * .mem file must meet the following requirements:

- Each row is one 36-bit binary word (only 0s and 1s).
- Only 0s and 1s are allowed.
- The number of rows in the file (word count) must be less than or equal to the memory space of the μPROM (up to 10,400 words).
- The memory file must have the * .mem file extension.

The following figure shows a sample Microsemi Binary file. Intel-Hex, Motorola-Hex, and simple-Hex files can also be imported as shown in [Figure 73](#), [Figure 74](#), and [Figure 75](#).

Figure 72 • Microsemi Binary File (*.mem) Example

```
110000111110000111110000111110000111
110000111110000111110000111110000111
110000111110000111110000111110000111
110000111110000111110000111110000111
110000111110000111110000111110000111
110000111110000111110000111110000111
110000111110000111110000111110000111
110000111110000111110000111110000111
110000111110000111110000111110000000
110000111110000111110000111110001110
110000111110000111110000111110001110
110000111110000111110000111110001110
110000111110000111110000111110001110
110000111110000111110000111110000000
110000111110000111110000111110001111
110000111110000111110000111110001111
110000111110000111110000111110001111
110000111110000111110000111110001111
110000111110000111110000111110001111
110000111110000111110000111110001111
110000111110000111110000111110001111
110000111110000111110000111110001111
110000111110000111110000111110001111
110000111110000111110000111110001111
110000111110000111110000111110001111
110000111110000111110000111110001111
```

Figure 73 • Intel-Hex File Selection**Figure 74 • Motorola-S File Selection****Figure 75 • Simple-Hex File Selection**

4.3.3.5.3 Content Filled with 0s

Fill the content of the memory client with 0s as a place holder. User can update the memory client after Place and Route and before programming. There is no need to rerun Place and Route after you update the μ PROM Memory Content. See [Update \$\mu\$ PROM Memory Content](#), page 78 for details.

4.3.3.5.4 Start Address

Enter the Start Address (14-bit) of client in HEX. Valid values are from 0x0 to 0x289F (HEX).

4.3.3.6 Number of 36-bit Words

Enter the size of client (expressed as the number of 36-bit words) in decimal.

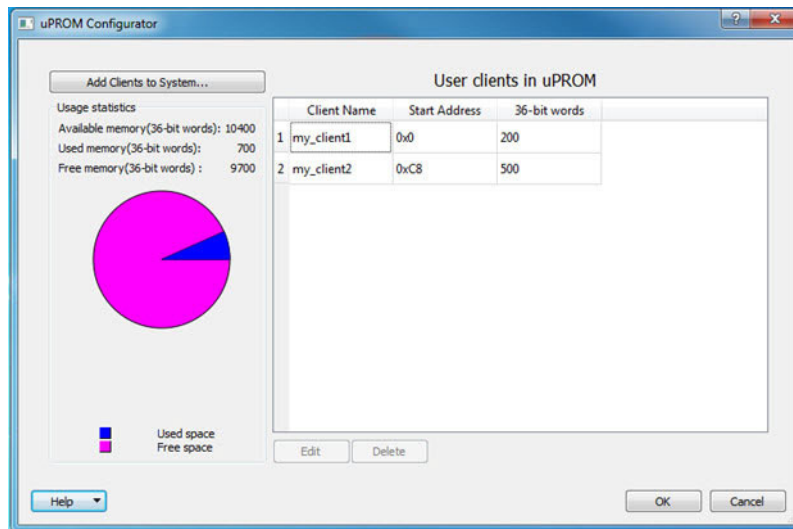
Note: When multiple clients are added, ensure that the address range of each client does not overlap with the other clients. Overlapping of address range is not allowed and will be flagged as an error when it occurs.

4.3.3.6.1 Use Content for Simulation

Select to include the memory content for simulation. When selected, a `μPROM.mem` file is automatically created in the `<prj_location>/simulation` folder when simulation is invoked in the Design Flow window. The `μPROM.mem` file is read by the `μPROM` simulation model to initialize the `μPROM` content when the simulation starts. The clients with the **Use Client for Simulation** check box checked have the contents added to the `μPROM.mem` file for simulation.

The following figure shows the added clients under User clients in `μPROM`.

Figure 76 • User Clients Added



4.3.3.7 DRC Rules and Error Messages

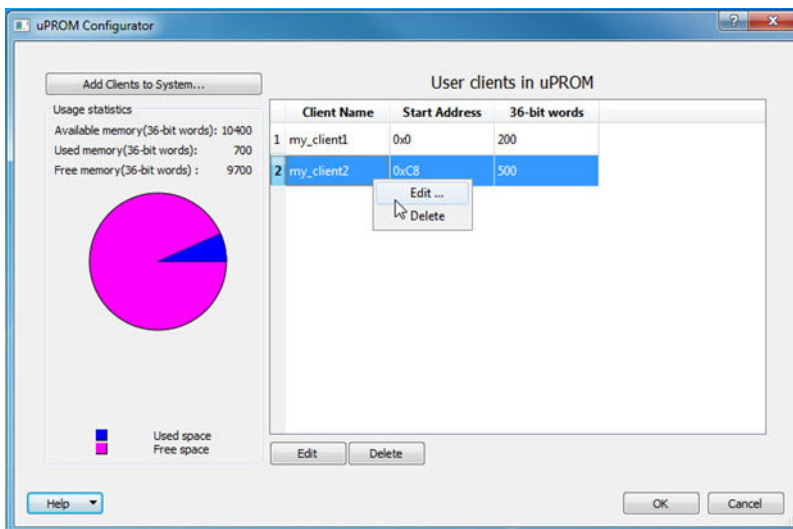
To prevent out-of-bound memory addressing and overlapping of address space, DRC rules are enforced and error messages are given when:

- An invalid start address (outside of the `μPROM` memory space) is entered. The `μPROM` address range is 0x0000 through 0x289F (HEX).
 - DRC Error: The specified start address is invalid; legal addresses range from 0x0 to 0x289F.
- The start address and the number of words the user has entered put the user client beyond the memory space of the `μPROM`.
 - DRC Error: For the specified start address the number of words cannot exceed the total number of words of 10,400.
- The number of 36-bit words the user has entered is less than the number of words in the memory file used to fill the content of the client.
 - DRC Error: The number of words cannot be less than the number of words `<mem_file_word_count>` specified in the memory file `<mem_file_name>`.
- There is more than one user client and the address range of one client overlaps with that of another.
 - DRC Error: This client overlaps with: `<client name>`.
- The memory file (`*.mem`) size exceeds the total `μPROM` memory space.
 - DRC Error: The memory file `<memoryFileName>` size exceeds the total `μPROM` space.

4.3.3.8 Editing a Client

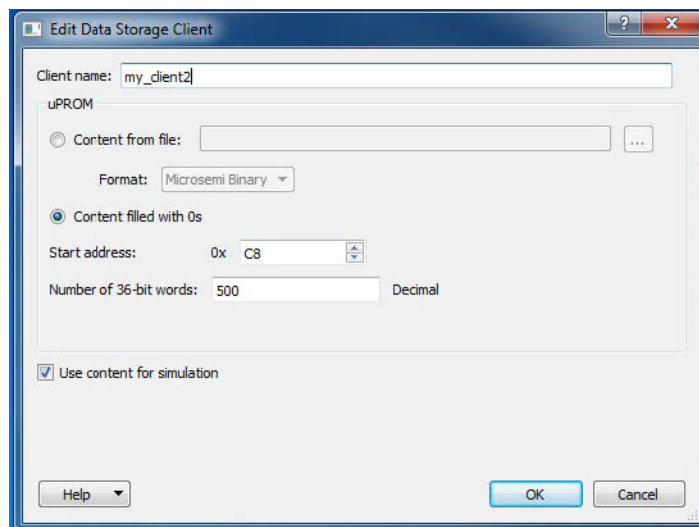
1. To edit a client, right-click the client and select **Edit** to open the **Edit Data Storage Client** dialog box.

Figure 77 • Editing User Clients



2. Make changes in the Edit Data Storage Client dialog box and click **OK** to save edits.

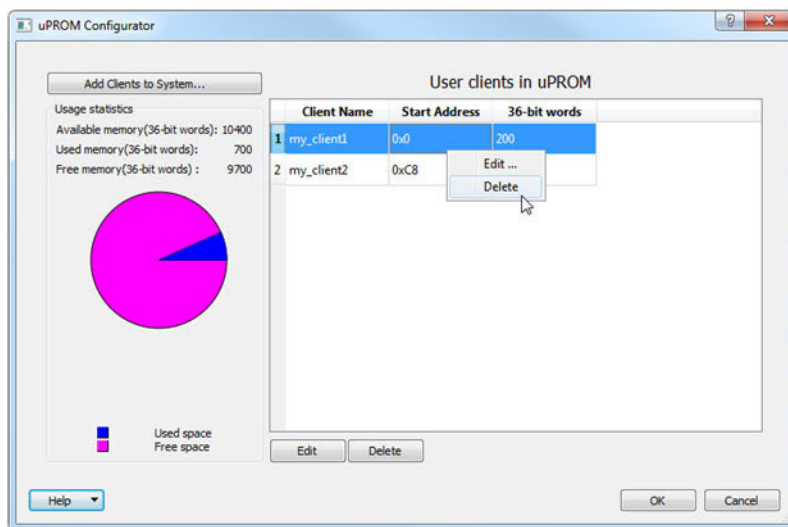
Figure 78 • Edit Data Storage Client Dialog Box



4.3.3.9 Deleting a Client

Right-click the client and select **Delete**.

Figure 79 • Deleting a Client



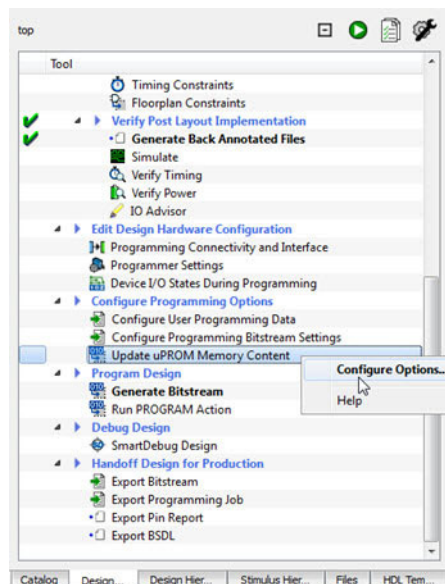
4.3.3.10 Update μ PROM Memory Content

The Update μ PROM Memory Content tool is useful if the user is reserved space in the μ PROM Configurator and want to make changes to the μ PROM client after Place and Route. After updating the μ PROM memory content, there is no need to rerun Place and Route.

To update the μ PROM Memory Content from the Design Flow window:

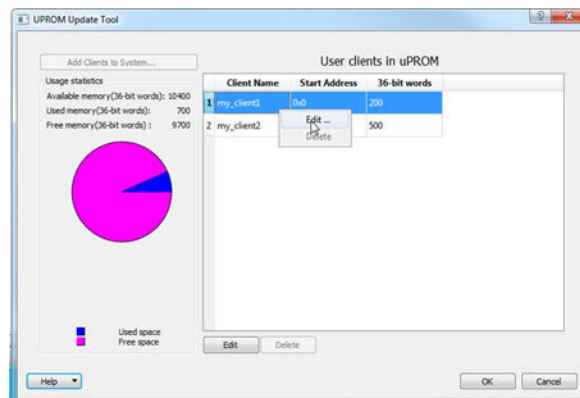
1. Right-click **Update μ PROM Memory Content** in the Design Flow window and select **Configure Options**.

Figure 80 • Update μ PROM Memory Content



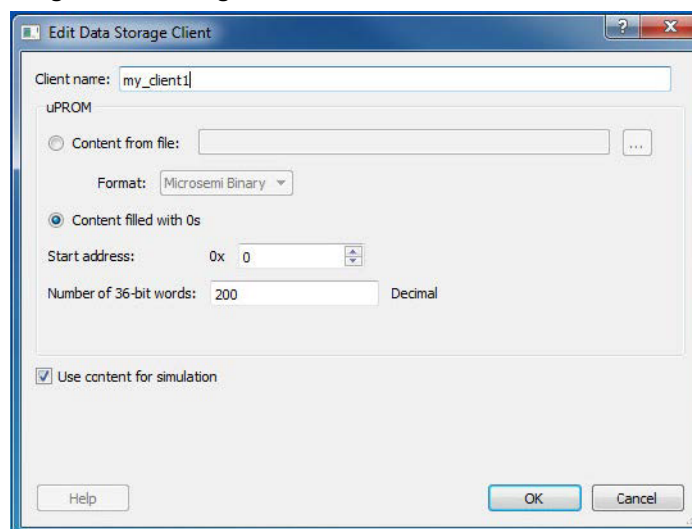
2. When the μ PROM Update Tool is displayed, right-click the **Memory Client** to update and click **Edit**.

Figure 81 • μ PROM Update Tool



The Edit Data Storage Client dialog box is displayed.

Figure 82 • Edit Data Storage Client Dialog Box



Make the following changes to the μ PROM client:

- Rename a client
- Change the memory content, memory size, and start address of the client
- Reverse the decision on whether or not to use content for simulation

Note: User cannot use the μ PROM Update Tool to add or delete a client. To add or delete a client, use the **μ PROM Configurator** to reconfigure the clients and regenerate the μ PROM component.

5 Math Blocks

5.1 Introduction

The RTG4 device implements a custom 18×18 multiply and accumulate block (18×18 multiply-accumulate (MACC)) for efficient implementation of complex digital signal processing (DSP) algorithms such as finite impulse response (FIR) filters, infinite impulse response (IIR) filters, and fast fourier transform (FFT) for filtering and image processing applications, and so on.

The RTG4 math block has a built-in multiplier and adder, which minimize the fabric logic required to implement multiplication, multiply-add, and multiply-accumulate (MACC) functions. Implementation of these arithmetic functions results in efficient resource usage and improved performance for DSP applications. In addition to the basic MACC functions, DSP algorithms require small amounts of RAM for coefficients and larger RAMs for data storage. RTG4 μ SRAMs are ideal to serve the coefficient storage requirements while LSRAMS are used for data storage. The number of available math blocks varies depending on the size of the device, as shown in the following figure.

5.2 Features

Each math block has the following features:

- High-performance and power optimized multiplications operations.
- Support for 18×18 signed multiplication.
- Support for 17×17 unsigned multiplications.
- Support for dot product: the multiplier computes: $(A[8:0] \times B[17:9] + A[17:9] \times B[8:0]) \times 29$.
- Built-in addition, subtraction, and accumulation units to combine multiplication results efficiently.
- Independent third input C with data width 44 bits completely registered.
- Single-bit input, CARRYIN, from fabric routing.
- Support for both registered and unregistered inputs and outputs.
- All the inputs and outputs registers are STMR-D flip-flops.
- Support for signed and unsigned operations.
- Internal cascade signals (44-bit CDIN and CDOOUT) enable cascading of the math blocks to support larger accumulator, adder, and subtractor without extra logic.
- Support for loopback capability.
- Adder support: $(A \times B) + C$ or $(A \times B) + D$ or $(A \times B) + C + D$.
- Clock-gated input and output registers for power optimizations.
- Extension of adder and accumulator width by implementing extra adders in the FPGA fabric.
- Operating up to 300 MHz with SET mitigation disable and up to 250 MHz with SET mitigation enable.
- Support for transparent mode.
- Asynchronous load - limited to reset. Math block registers are same as fabric STMR-D flip-flops with single asynchronous reset signal sharing among the fabric flip-flops and RAMs registers.
- Global reset can be ignored, if required.
- Math block flip-flops always reset during power-up.

5.3 Math Block Resource Table

The following table lists the number of math blocks available for RTG4 devices.

Table 25 • Resources for RTG4 Devices

Blocks	RT4G150
Math blocks (18-bit \times 18-bit)	462

Note: All numbers given above are applicable per device.

5.4 Architecture Description

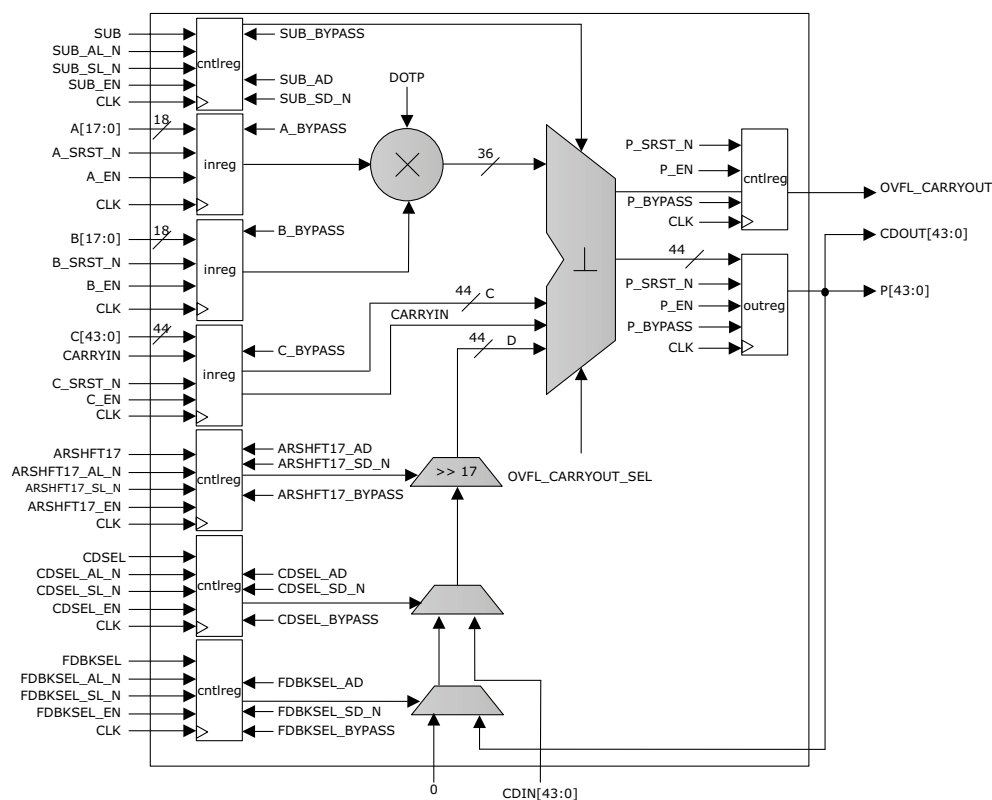
RTG4 devices can have one to three rows of math blocks in the fabric, as shown in [Table 25](#), page 80. Math blocks are cascaded in a chain, starting from the left-most block to the right-most block. These can be accessed through the fabric routing through interface logic clusters. These clusters are composed of 12 flip-flops and 12 4-input LUTs. When math blocks are used, these flip-flops and LUTs act as an interface to the fabric routing. When math blocks are not used, these flip-flops and LUTs can be utilized as normal flip-flops and LUTs. The interface logic clusters do not support carry chains.

Each math block consists of:

- Multiplier
- Adder or subtractor
- I/O and Control Registers

The following figure shows the functional block diagram of the math block.

Figure 83 • Functional Block Diagram of Math Block



For more information about port list, see [Table 40](#), page 110.

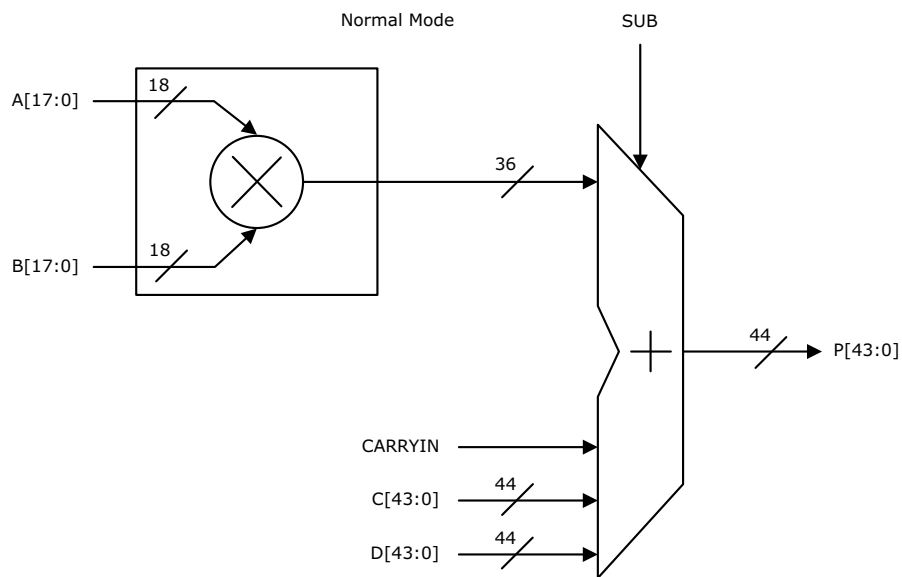
5.4.1 Multiplier

The RTG4 math block can be used as a multiplier, which accepts two 18-bit inputs (A and B), and generates a 36-bit output. The math block multiplier can be configured in two different operating modes:

- Normal mode
- DOTP mode

5.4.1.1 Normal Mode

In normal mode, the math block implements a single 18×18 signed multiplier. The math block accepts the inputs, A [17:0] and B [17:0], and generates product of A and B with a 36-bit wide result. The following figure shows the functional block diagram of the math block in normal mode.

Figure 84 • Functional Block Diagram of Math Block in Normal Mode

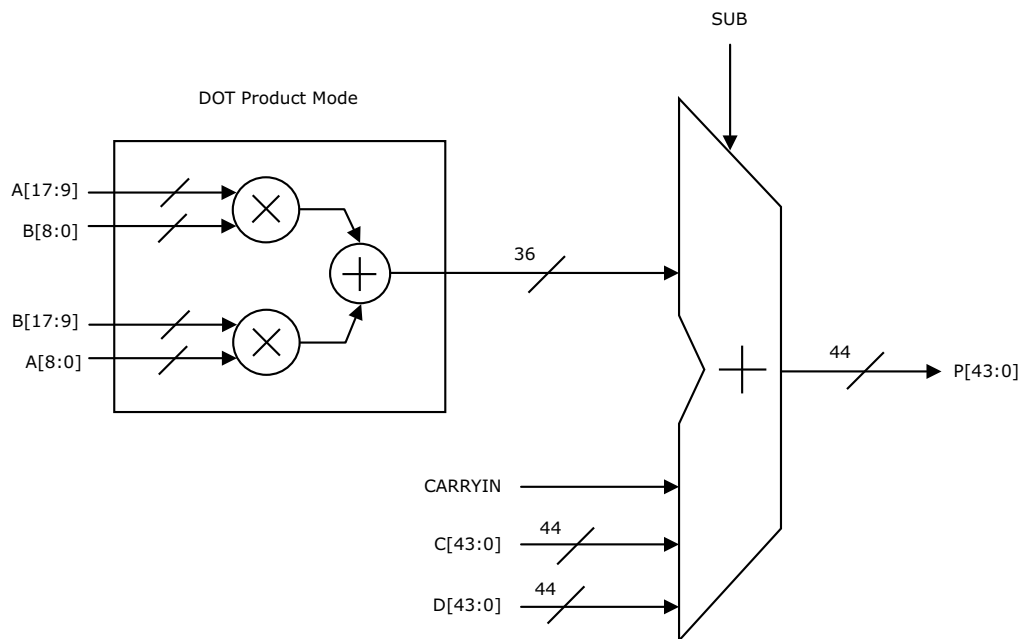
5.4.1.2 DOTP Mode

Dot product (DOTP) mode has two independent 9×9 multipliers with adder and the product sum is stored in the upper 36 bits of the 44-bit register. In DOTP mode, the math block implements the following equation:

$$(A[8:0] \times B[17:9] + A[17:9] \times B[8:0]) \times 29$$

DOTP mode can be used to implement 9×9 complex multiplications.

The following figure shows the functional block diagram of the math block in DOTP mode.

Figure 85 • Functional Block Diagram of Math Block in DOTP Mode

5.4.2 Adder or Subtractor

The adder sums the output from the multiplier, C input, CARRYIN, or D input. The final output (P) of the adder is $((A[17:0] \times B[17:0]) + C[43:0] + D[43:0] + \text{CARRYIN})$.

The math block can be configured as a 2-input or 3-input adder.

- 2-input adder, computes $A \times B + C$ or $A \times B + D$.
- 3-Input adder, computes $A \times B + C + D$.

If the adder is configured as a subtractor, the adder output is $((C[43:0] + D[43:0] + \text{CARRYIN}) - (A[17:0] \times B[17:0]))$.

Note: If the user design deploys the math block(s) to perform accumulation in RTG4, any error caused by a radiation-induced event (SEU/SET), will stay in the accumulator until it is reset or purged.

5.4.3 I/O and Control Registers

Math blocks have built-in registers on data inputs (A, B, and C), data output (P), and control signals. If required, these registers can be bypassed. All these registers have clock gating capability to reduce the power consumption. These register flip-flops are STMR-D flip-flops.

Math blocks do not have a pipeline register at the cascade input (CDIN), thus pipeline registers can be added from the fabric when multiple math blocks are cascaded to implement higher bit-width multiplications.

5.4.3.1 C Input

The C input port allows the formation of many 3-input mathematical functions, such as 3-input addition or 2-input multiplication with an addition. The CARRYIN signal is the carry input of the adder or accumulator. The C input can also be used as a dynamic input for achieving the following functionalities:

- Wrapping-around the cascade chain of math blocks from one row to the next row through the fabric.
- Rounding of multiplication outputs.
- Trimming of lower order bits of the final sum, partial sum, or the product.

5.4.3.2 Cascaded Input, Output, and Selection

Higher level DSP functions are supported by cascading individual math blocks in a row. The two data signals, CDIN [43:0] and CDOUT [43:0], provide the cascading capability with a cascade select input (CDSEL). Table 26, page 84 shows the selection of CDSEL for propagating CDIN to the D input of the adder. To cascade math blocks, the CDOUT of one block must feed the CDIN of another block. CDOUT to CDIN is a hardwired connection between the blocks within a row.

Two different rows can be cascaded using the fabric routing between the two rows. Extra pipeline registers might be required to compensate for the extra delays added due to the fabric routing, which in turn increases the latency of the chain.

The ability to cascade math blocks is useful in filter designs. For example, an FIR filter design can use cascading inputs to arrange a series of input data samples and cascading outputs to arrange a series of partial output results. The ability to cascade provides a high-performance and low-power implementation of DSP filter functions as the general routing in the fabric is not used.

5.4.3.3 Overflow Output

Each math block has an overflow signal, OVFL_CARRYOUT. This signal indicates any overflow from the additional operation performed by the adder. This signal is used to extend the adder data widths from the existing 44 bits using the fabric. It is also used for the implementation of saturation capabilities.

Saturation refers to catching an overflow condition and replacing the output with either the maximum (most positive) value or minimum (most negative) value that can be represented. In RTG4 math blocks, this capability is implemented using the adder's output sign bit (MSB [43] bit of the P output) and the overflow signal.

5.4.3.4 Shift Input

For multi-precision arithmetic, math blocks provide a right-wire-shift by 17 which is controlled by the ARSFT17 input. Thus, a partial product from one math block can be shifted to the right and added to

the next partial product computed in an adjacent math block. Using this technique, math blocks can be used to build larger multipliers.

5.4.3.5 Feedback Select Input

For accumulation operations, the math block output must loopback to the D input of the adder block. Selection of the D input is controlled by the Feedback Select (FDBKSEL) input. The following table shows the selection of FDBKSEL for loopback.

Table 26 • Truth Table for Propagating Operand D of the Adder or Accumulator

CDSEL	FDBKSEL	ARSHFT17	Operand D
0	0	0	0
0	0	1	0
1	X	0	CDIN[43:0]
1	X	1	{{17{CDIN[43]}}, CDIN[43:18]}
0	1	0	P[43:0]
0	1	1	{{17{P[43]}}, P[43:18]}

5.5 Math Blocks Functional Examples

The following sections describe how to use math block in an application:

- Designing with Math Blocks
- Use Models
- Coding Style Examples

5.5.1 Designing with Math Blocks

Math blocks can be used in two methods—through inference and through the math block primitive. Inference is done during the Synthesis stage of an RTL design. Alternately, the math block primitive is available in the Libero SoC IP catalog as a component that can be used directly in the HDL file or instantiated in SmartDesign.

5.5.1.1 Through RTL Inference

Synplify Pro can infer math blocks and can configure them into appropriate modes automatically, if the RTL contains one of the following functions:

- Multiplication
- Multiply-accumulate
- Multiply-add
- Multiply-subtract

In this case, the synthesis tool takes care of all the signal connections of the math block to the rest of the design and provides the correct values for the static signals to configure the appropriate operational mode. The tool ties unused dynamic input signals to the ground and provides default values to unused static signals.

The synthesis tool maps any multiplication function with input widths of three or greater to math blocks. However, the mapping of multiplication functions with input widths less than three, which are implemented in the fabric logic by default, can be controlled by the Synthesis attribute - `syn_multstyle`. The tool can cascade multiple math blocks, if the function exceeds the limits of a single math block. For example, if an RTL function has a 35×35 multiplication, the synthesis tool implements this using four math blocks cascaded in a chain. It can also place the input and output registers inside the math block boundary, if they are driven by same clock. If the registers have different clocks, the clock that drives the output register has priority, and all registers driven by that clock are placed into the math block. If the outputs are unregistered and the inputs are registered with different clocks, the input registers with the larger input have priority and are placed into the math block.

The synthesis tool supports inference of math block components across hierarchical boundaries, which means even if the multipliers, input registers, output registers, and subtractor/adders are present in different hierarchies, they can be placed into the same math block.

For more information about math block inference by Synplify Pro, see [Inferring Microsemi SmartFusion2 and RTG4 MACC Blocks Application Note](#).

5.5.2 Use Models

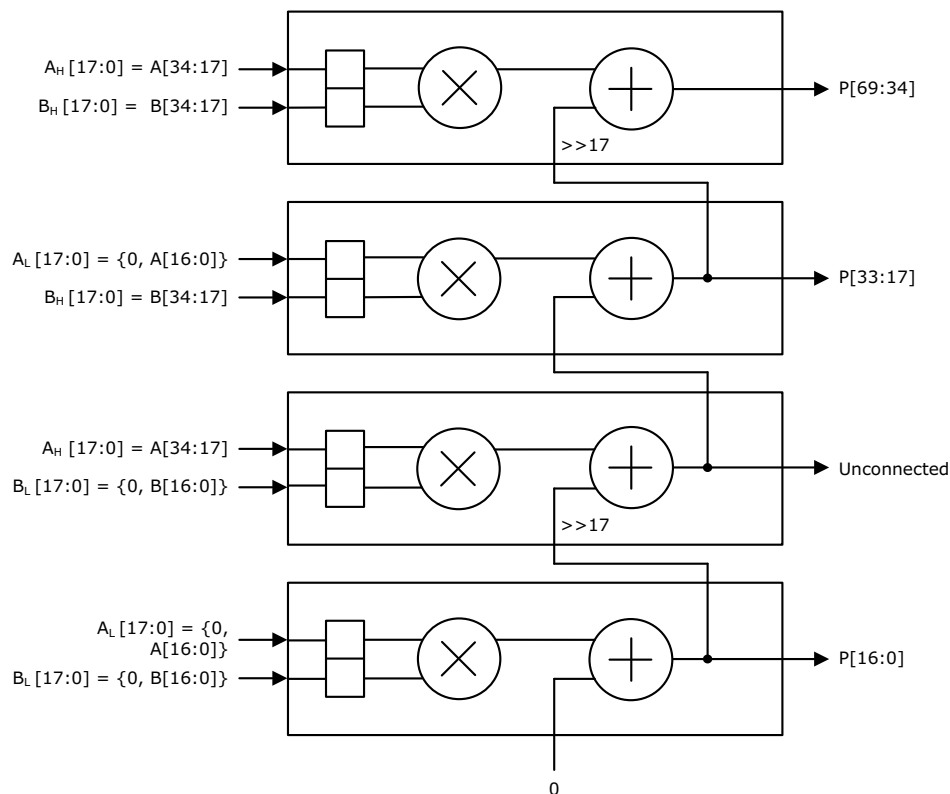
This section describes use models for RTG4 math block.

5.5.2.1 Non-Pipelined Implementation of 35×35 Multiplier

35×35 multipliers are useful for applications, which require more than 18-bit precision. Non-pipelined implementation is typically used for low-speed applications. A 35×35 multiplier can be constructed using four math blocks in a single row, connected in a cascade. The following figure shows the implementation of a non-pipelined 35×35 multiplier.

The inputs are assumed to be A [34:0] and B [34:0] with a product of P [69:0].

Figure 86 • Non-Pipelined 35×35 Multiplier

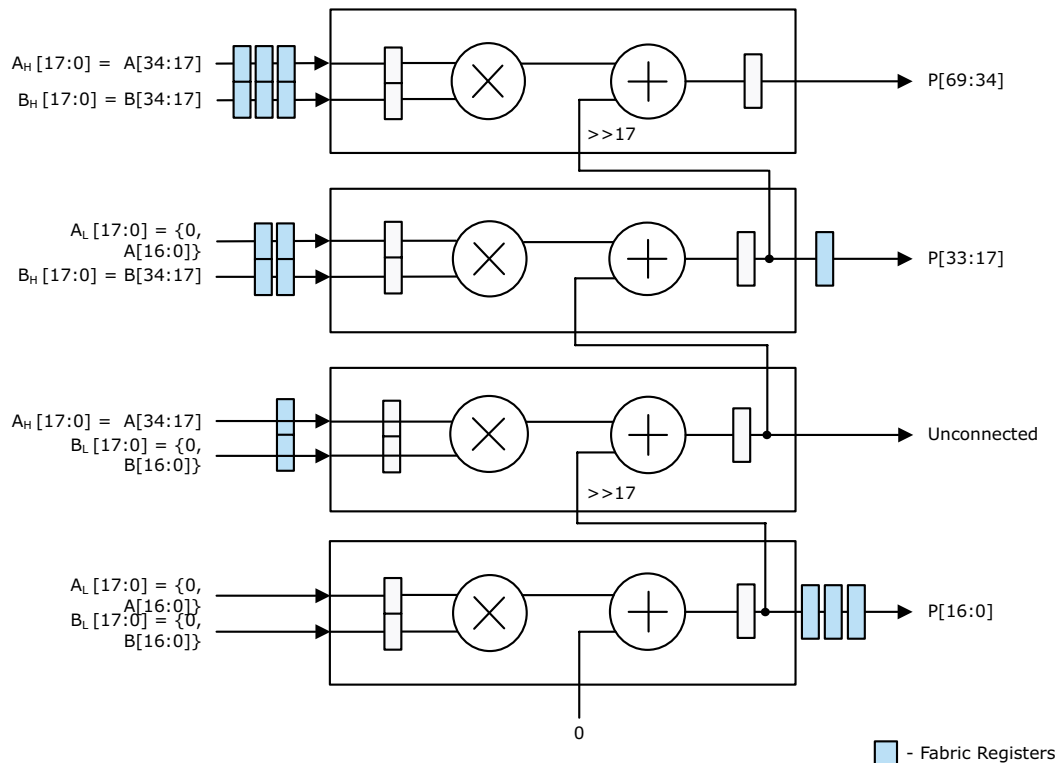


5.5.2.2 Pipelined Implementation of 35×35 Multiplier

Math blocks have built-in registers on all input and output ports. To implement the high-speed multipliers, extra registers are added to the input or output side of the math blocks to balance the pipeline latency. These extra registers are implemented in the fabric.

The following figure shows a typical 35×35 multiplier implementation with fabric pipeline registers.

Figure 87 • Pipeline 35×35 Multiplier



5.5.2.3 Implementation of 9-Bit Complex Multiplication

Implementation of complex multiplication using a math block in DOTP mode requires additional 2's complement logic in the fabric for negating the Q input. The DOTP implementation in the following figure shows the optimized way of implementing the 2's complement with minimal logic in the fabric.

For two complex numbers $X + jY$, $P + jQ$, the complex multiplication is shown in the following equation:

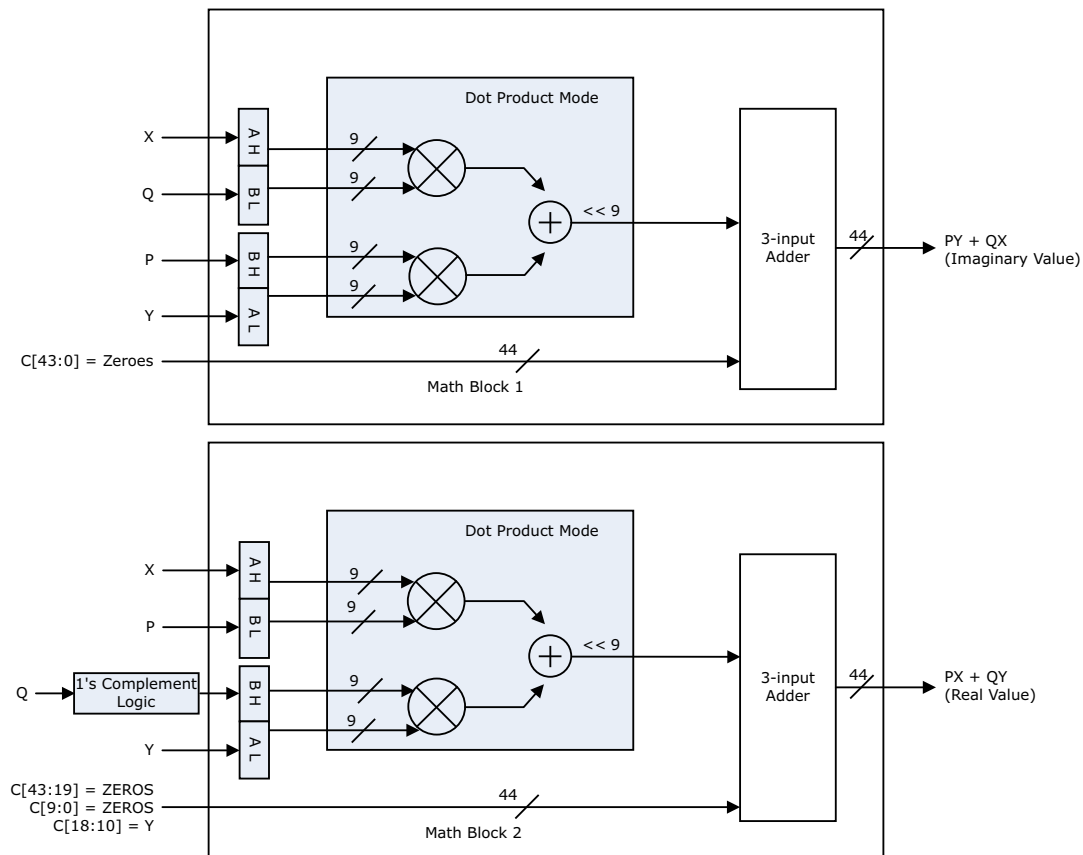
$$\text{Multiplication Result} = \text{Real part} + \text{Imaginary Part} = (PX - QY) + j(PY + QX)$$

In the preceding equation, real part $(PX - QY)$ requires $-Q$ for the multiplication result. This can be computed using the one's complement of Q and add the Y using the C input (since $-Q = \sim Q + 1$).

$$\text{Imaginary part} = P \times Y + Q \times X$$

$$\text{Real part} = P \times X + (\sim Q) \times Y + Y$$

The following figure shows the implementation of 9×9 multiplication using a math block configured in DOTP mode.

Figure 88 • 9-Bit Complex Multiplication Using DOTP Mode

5.5.2.4 Multi-Threading and Multi-Channeling

Math blocks support multi-threading where the same math block can be used for performing more than one computation by time multiplexing. Time multiplexing can be done easily for designs with low sample rates.

The multi-threading capability, if implemented for a chain of math blocks, is called multi-channeling.

Multi-channeling can be used to implement multi-channel FIR filters where the same math block chain can be used to process multiple input channels by time multiplexing the math block chain. Multi-channel filtering is used in applications such as wireless communications, image processing, and multimedia applications. The math block uses its C input for multi-threading and multi-channeling, but fabric registers are also required for implementation.

5.5.2.5 Rounding and Trimming

5.5.2.5.1 Rounding

Rounding can be computed by adding a fixed term and a variable term to the input value to be rounded, and then truncating. The fixed term can be fed using the C-input of the math block and the value is depending on the number of decimal points required after rounding. The variable term is always a single bit in the least-significant position whose value may be determined from the input value based on the type of rounding.

The following are the types of rounding:

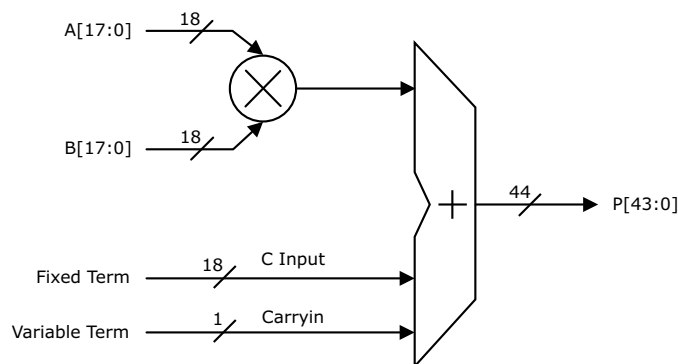
- Round to the adjacent even integer: The variable term is determined from the 20-bit of the input value.
- Round towards zero: The variable term is determined from the sign bit of the input value. For example, 1.5 rounds to 1 and -1.5 rounds to -1.

The following table shows examples for 6-bit values including three fraction bits.

Table 27 • Rounding Examples

Input Value		Fixed Term	Round To Even			Round Toward Zero				
Decimal	Binary		Variable Term	Sum	Truncated Sum	Decimal	Variable Term	Sum	Truncated Sum	Decimal
2.5	010.100	0.011	000.000	010.111	010	2	000.000	010.111	010	2
1.5	001.100	0.011	000.001	010.000	010	2	000.000	001.111	001	1
-1.5	110.100	0.011	000.000	110.111	110	-2	000.001	111.000	111	-1
-2.5	101.100	0.011	000.001	110.000	110	-2	000.001	110.000	110	-2

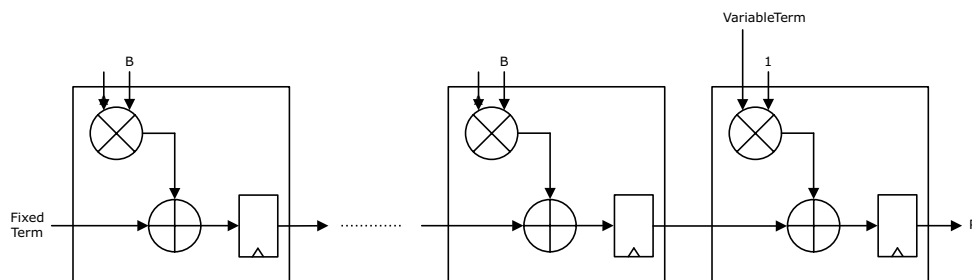
Figure 89 • Rounding Using C-Input and CARRYIN



5.5.2.5.2 Trimming

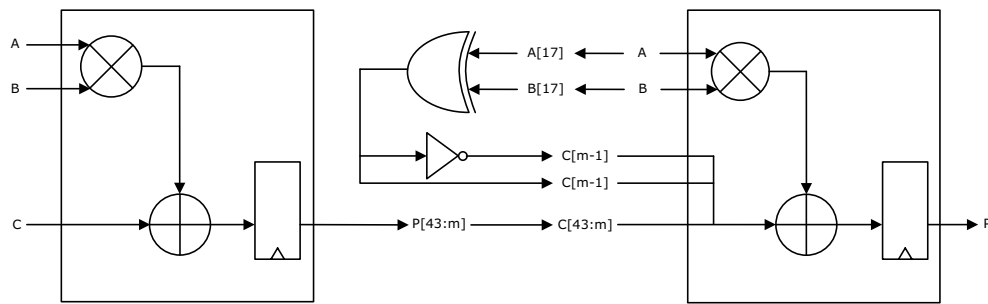
Trimming of the Final Sum: Applications such as IIR and FFT often require the rounding and trimming of the final result. For example, last output of a cascade chain or the final value read from an accumulator. The addition of the rounding terms can be done as shown in the following figure. The final result can be trimmed in the fabric.

Figure 90 • Rounding and Trimming of the Final Sum



Trimming of Grouped Sums: When computing very large DOTPs (for example, a large, fully-enumerated FIR), it is good to avoid overflow by breaking the sum into a few groups, trimming the sum for each group, and only then combining the sums of the groups into a final result. The rounding of each group's sum can be done as shown in the preceding figure. The trimming of each group's sum and summation of the final result can be done in the fabric. Trimming can be done between the output of each cascade and the final fabric adder.

Trimming of Products: The following figure shows the implementation of rounding all products towards zero and then trimming the least significant M bits of the product. As long as there are no additive terms other than the products, it is possible to equivalently trim the partial sums instead of the products. Round towards zero can be done using sign bit of the product ($A \times B$) from the sign bits of the incoming factors A and B using an XOR.

Figure 91 • Rounding and Trimming of the Final Sum

5.5.3 Coding Style Examples

The following code examples illustrate coding styles from which the synthesis tool can infer and implement RTG4 math blocks.

Note: Examples provided are only in VHDL. Verilog examples will be provided on request.

5.5.3.1 Example 1: 18 × 18 Signed Multiplication – Non-Registered

The following code is for an 18 × 18 signed multiplier. The input and output registers are configured in transparent mode. The synthesis tool maps the code into one math block.

```
library IEEE;
use IEEE.std_logic_1164.all;
use IEEE.numeric_std.all;

entity sign18x18_mult is
port(   in1      : in signed(17 downto 0);
        in2      : in signed(17 downto 0);
        out1     : out signed(35 downto 0)
);
end sign18x18_mult;

architecture behav of sign18x18_mult is
begin
    out1 <= in1 * in2;
end behav;
```

5.5.3.2 Example 2: 18 × 18 Signed Multiplication – Registered

The following code is for an 18 × 18 signed multiplier. The inputs and outputs are registered, with a Synchronous active low reset signal. The synthesis tool maps the code into one math block.

```
library IEEE;
use IEEE.std_logic_1164.all;
use IEEE.numeric_std.all;
entity sign18x18_mult_reg is
port(
    clk      : in std_logic;
    rstn     : in std_logic;

    in1      : in signed(17 downto 0);
    in2      : in signed(17 downto 0);
    out1     : out signed(35 downto 0)
);
end sign18x18_mult_reg;
architecture behav of sign18x18_mult_reg is
    signal in1_reg : signed(17 downto 0);
    signal in2_reg : signed(17 downto 0);
begin
    process(clk, rstn)
    begin
        if(rstn = '0')then
            in1_reg <= (others => '0');
            in2_reg <= (others => '0');
            out1    <= (others => '0');
        else
            if(rising_edge(clk))then
                in1_reg <= in1;
                in2_reg <= in2;
            end if;
            out1 <= in1_reg * in2_reg;
        end if;
    end process;
end behav;
```

5.5.3.3 Example 3: 17×17 Unsigned Multiplier with Different Resets

The following code is for a 17×17 unsigned multiplier, which has input and output registers with different asynchronous resets. The synthesis tool maps the code into one RTG4 math block.

```
library IEEE;
use IEEE.std_logic_1164.all;
use IEEE.std_logic_unsigned.all;
entity mult_17x17unsign is
port(
    clk      : in std_logic;
    rstn1    : in std_logic;
    rstn2    : in std_logic;
    in1      : in std_logic_vector(16 downto 0);
    in2      : in std_logic_vector(16 downto 0);
    out1     : out std_logic_vector(33 downto 0)
);
end mult_17x17unsign;
architecture behav of mult_17x17unsign is
    signal in1_reg :std_logic_vector(16 downto 0);
    signal in2_reg :std_logic_vector(16 downto 0);
begin
    process(clk,rstn1)
    begin
        if(rstn1 = '0')then
            in1_reg <= (others => '0');
            in2_reg <= (others => '0');
        else
            if(rising_edge(clk)) then
                in1_reg <= in1;
                in2_reg <= in2;
            end if;
        end if;
    end process;
    process(clk,rstn2)
    begin
        if(rstn2 = '0')then
            out1 <= (others => '0');
        else
            if(rising_edge(clk)) then
```

```

        out1 <= in1_reg * in2_reg;
    end if;
end if;
end process;
end behav;

```

5.5.3.4 Example 4: 17 × 17 Unsigned Multiplier with Different Clocks

This example shows an unsigned multiplier with inputs and outputs that are registered with different clocks—clock1 and clock2. In this case, the synthesis tool places the output registers and the multiplier only into the RTG4 math block. The input registers are implemented in the fabric logic outside the math block.

```

library IEEE;
use IEEE.std_logic_1164.all;
use IEEE.std_logic_unsigned.all;
entity mult_17x17unsign is
port(
    clk1      : in std_logic;
    clk2      : in std_logic;
    in1       : in std_logic_vector(16 downto 0);
    in2       : in std_logic_vector(16 downto 0);
    out1      : out std_logic_vector(33 downto 0)
);
end mult_17x17unsign;
architecture behav of mult_17x17unsign is
    signal in1_reg :std_logic_vector(16 downto 0);
    signal in2_reg :std_logic_vector(16 downto 0);
begin
    process(clk1)
    begin
        if(rising_edge(clk1))then
            in1_reg <= in1;
            in2_reg <= in2;
        end if;
    end process;
    process(clk2)
    begin
        if(rising_edge(clk2))then
            out1 <= in1_reg * in2_reg;
        end if;
    end process;
end mult_17x17unsign;

```

```
end behav;
```

5.5.3.5 Example 5: Multiplier-Adder

In the code below, the output of a multiplier is added with another input. Inputs and outputs are registered and have enables and synchronous resets. The synthesis tool maps the code into one RTG4 math block.

```
library IEEE;
use IEEE.std_logic_1164.all;
use IEEE.std_logic_unsigned.all;
entity mult_add is port (
    clk : in std_logic;
    rst : in std_logic;
    en   : in std_logic;
    in1  : in std_logic_vector (16 downto 0);
    in2  : in std_logic_vector (16 downto 0);
    in3  : in std_logic_vector (33 downto 0);
    out1 : out std_logic_vector (34 downto 0)
);
end mult_add;
architecture behav of mult_add is
    signal in1_reg, in2_reg : std_logic_vector (16 downto 0 );
    signal mult_out : std_logic_vector ( 33 downto 0 );
begin
    process(clk)
    begin
        if(rising_edge(clk))then
            if(rst = '0') then
                in1_reg <= ( others => '0');
                in2_reg <= ( others => '0');
                out1 <= ( others => '0');
            elsif(en = '1')then
                in1_reg <= in1;
                in2_reg <= in2;
                out1 <= ( '0' & mult_out ) + ( '0' & in3 );
            end if;
        end if;
    end process;
    mult_out <= in1_reg * in2_reg;
end behav;
```


5.5.3.6 Example 6: Multiplier-Subtractor

User can implement multiplier and subtract logic in three methods. The synthesis tool places the logic differently, depending on how it is implemented.

- Subtract the result of multiplier from an input value ($P = \text{Cin} - \text{mult_out}$). The synthesis tool places all logics in the math block.
- Subtract a value from the result of the multiplier ($P = \text{mult_out} - \text{Cin}$). The synthesis tool places only the multiplier in the math block. The subtractor is implemented in the fabric logic outside the math block.
 - Unsigned MultSub Example ($P = \text{Cin} - \text{Mult_out}$) - Implemented in a single math block.
 - Unsigned MultSub Example ($P = \text{Cin} - \text{Mult_out}$) - Implemented in a single math block

```
library IEEE;
use IEEE.std_logic_1164.all;
use IEEE.std_logic_unsigned.all;
entity mult_sub is port (
    clk : in std_logic;
    rst : in std_logic;
    in1 : in std_logic_vector(16 downto 0);
    in2 : in std_logic_vector(16 downto 0);
    in3 : in std_logic_vector(33 downto 0);
    out1 : out std_logic_vector(33 downto 0)
);
end mult_sub;
architecture behav of mult_sub is
    signal in1_reg, in2_reg : std_logic_vector(16 downto 0);
begin
    process(clk)
    begin
        if(rising_edge(clk))then
            if(rst = '0') then
                in1_reg <= ( others => '0');
                in2_reg <= ( others => '0');
                out1    <= ( others => '0');
            else
                if(rising_edge(clk))then
                    in1_reg <= in1;
                    in2_reg <= in2;
                    out1 <= in3 - (in1_reg * in2_reg);
                end if;
            end if;
        end if;
    end process;
end mult_sub;
```

```
end behav;
```

– Unsigned MultSub Example ($P = \text{Mult} - \text{Cin}$) -

Multiplier is implemented in the math block and subtractor in the fabric logic

```
library IEEE;
use IEEE.std_logic_1164.all;
use IEEE.std_logic_unsigned.all;
entity mult_sub is port (
    clk : in std_logic;
    rst : in std_logic;
    in1 : in std_logic_vector(16 downto 0);
    in2 : in std_logic_vector(16 downto 0);
    in3 : in std_logic_vector(33 downto 0);
    out1 : out std_logic_vector(33 downto 0)
);
end mult_sub;
architecture behav of mult_sub is
    signal in1_reg, in2_reg : std_logic_vector(16 downto 0);
begin
    process(clk)
    begin
        if(rising_edge(clk)) then
            if(rst = '0') then
                in1_reg <= (others => '0');
                in2_reg <= (others => '0');
                out1    <= (others => '0');
            else
                if(rising_edge(clk)) then
                    in1_reg <= in1;
                    in2_reg <= in2;
                    out1 <= (in1_reg * in2_reg)-in3;
                end if;
            end if;
        end if;
    end process;
end behav;
```

5.5.3.7 Example 7: Signed 35×35 Multiplication

The following code implements a signed 35×35 multiplication function. The synthesis tool uses four cascaded math blocks to implement this multiplication function.

```
library IEEE;
use IEEE.std_logic_1164.all;
use IEEE.numeric_std.all;
entity sign35x35_mult is port (
    in1 : in signed(34 downto 0);
    in2 : in signed(34 downto 0);
    out1 : out signed(69 downto 0)
);
end sign35x35_mult;
architecture behav of sign35x35_mult is
begin
    out1 <= in1*in2;
end behav;
```

5.5.3.8 Example 8: Signed 35×35 Multiplication with Two Pipelined Register Stages

The following code implements a signed 35×35 multiplication function with two pipelined register stages. The synthesis tool uses four cascaded math blocks to implement this multiplication function. The synthesis tool first infers pipeline registers at the input and output of the RTG4 math block and controls pipeline latency by balancing the number of register stages. To balance the stages, the tool adds additional registers at the input or output of the math block as required, implemented in the fabric logic.

```
library IEEE;
use IEEE.std_logic_1164.all;
use IEEE.numeric_std.all;
entity sign35x35_mult is
port (
    clk      : in std_logic;
    rstn     : in std_logic;
    in1      : in signed(34 downto 0);
    in2      : in signed(34 downto 0);
    out1     : out signed(69 downto 0)
);
end sign35x35_mult;
architecture behav of sign35x35_mult is
    signal in1_reg : signed(34 downto 0);
    signal in2_reg : signed(34 downto 0);
begin
    process(rstn,clk)
    begin
```

```
if(rstn ='0')then
    in1_reg <= (others => '0');
    in2_reg <= (others => '0');
    out1    <= (others => '0');
else
    if(rising_edge(clk))then
        in1_reg <= in1;
        in2_reg <= in2;
    out1    <= in1_reg*in2_reg;
    end if;
end if;
end process;
end behav;
```

6 Appendix: Supported Memory File Formats

Intel-Hex and Motorola-S file formats are supported. Implementation of these formats interprets data sets in bytes. If the memory width is 7 bits, every 8th bit in the data set is ignored. If the data width is 9 bits, two bytes are assigned to each memory address and the upper 7 bits of each 2-byte pair are ignored.

The following examples illustrate how the data is interpreted for various word sizes:

FF 11 EE 22 DD 33 CC 44 BB 55 (where, 55 is the MSB and FF is the LSB) for 32-bit word size:56

0x22EE11FF (address 0)

0x44CC33DD (address 1)

0x000055BB (address 2)

For 16-bit word size:

0x11FF (address 0)

0x22EE (address 1)

0x33DD (address 2)

0x44CC (address 3)

0x55BB (address 4)

For 8-bit word size:

0xFF (address 0)

0x11 (address 1)

0xEE (address 2)

0x22 (address 3)

0xDD (address 4)

0x33 (address 5)

0xCC (address 6)

0x44 (address 7)

0xBB (address 8)

0x55 (address 9)

For 9-bit word size:

0x11FF -> 0x01FF (address 0)

0x22EE -> 0x00EE (address 1)

0x33DD -> 0x01DD (address 2)

0x44CC -> 0x00CC (address 3)

0x55BB -> 0x01BB (address 4)

Note: For 9-bit, the upper 7-bits of the 2-bytes are ignored.

INTEL-HEX

Intel Hex is an industry standard file format created by Intel. File extensions for these files are `.hex` and `.ihx`.

Memory contents are stored in ASCII files using hexadecimal characters. Each file contains a series of records (lines of text) delimited by new line, '\n', characters and each record starts with a ':' character. For more information about this format, see the Intel-Hex Record Format Specification.

The Intel Hex record is composed of five fields and is arranged as:

```
:11aaaaatt[dd...]cc
```

Where:

- `:` - Start code of every Intel Hex record
- `11` - Byte count of the data field
- `aaaa` - 16-bit address of the beginning of the memory position for the data. Address is big endian.
- `tt` - Record type, defines the data field:
- `00` - Data record
- `01` - End of file record
- `02` - Extended segment address record
- `03` - Start segment address record (ignored by Microsemi SoC tools)
- `04` - Extended linear address record
- `05` - Start linear address record (ignored by Microsemi SoC tools)
- `[dd...]` - Sequence of n bytes of the data. n is equivalent to what was specified in the `11` field
- `cc` - Checksum of count, address, and data

Example Intel Hex record:

```
:0300300002337A1E
```

MOTOROLA S-Record

Motorola S-Record is an industry standard file format created by Motorola. The file extension for these files is `.s`.

This format uses ASCII files, hex characters, and records to specify memory content similar to the Intel-Hex format. See the Motorola S-record description document for more information about this format. The RAM Content Manager uses only the S1 through S3 record types. The other record types are ignored.

The major difference between Intel-Hex and Motorola S is the record formats and extra error checking features that are incorporated into the Motorola S-record.

In both formats, memory content is specified by providing a starting address and a data set. The upper bits of the data set are loaded into the starting address and leftovers overflow into the adjacent addresses until the entire data set has been used.

The Motorola S-record is composed of six fields and arranged as follows:

```
S111aaaa[dd...]cc
```

Where:

- `S` - Start code of every Motorola S-record
- `t` - Record type, defines the data field
- `11` - Byte count of the data field
- `aaaa` - 16-bit address of the beginning of the memory position for the data. Address is big endian.
- `[dd...]` - Sequence of n bytes of the data; n is equivalent to what was specified in the `11` field
- `cc` - Checksum of count, address, and data

Example Motorola S-record:

```
S10a0000112233445566778899FFFA
```

MEMFILE (RAM Content Manager output file)

Transfer of RAM data (from the RAM Content Manager) to test equipment is accomplished via MEM files.

The contents of RAM is first organized into the logical layer and then reorganized to fit the hardware layer. Then it is stored in MEM files that are read by other systems and used for testing. The MEM files are named according to the logical structure of RAM elements created by the configurator. In this scheme, the highest order RAM blocks are named `CORE_R0C0.mem`, where R stands for row and C stands for column. For multiple RAM blocks, the naming continues with `CORE_R0C1`, `CORE_R0C2`, `CORE_R1C0`, and so on.

The data intended for the RAM is stored as ASCII 1s and 0s within the file. Each memory address occupies one line. Words from logical layer blocks are concatenated or split in order to make them fit efficiently within the hardware blocks. If the logical layer width is less than the hardware layer, two or more logical layer words are concatenated to form one hardware layer word. In this case, the lowest bits of the hardware word are made up of the lower address data bits from the logical layer. If the logical layer width is more than the hardware layer, the words are split, placing the lower bits in lower addresses.

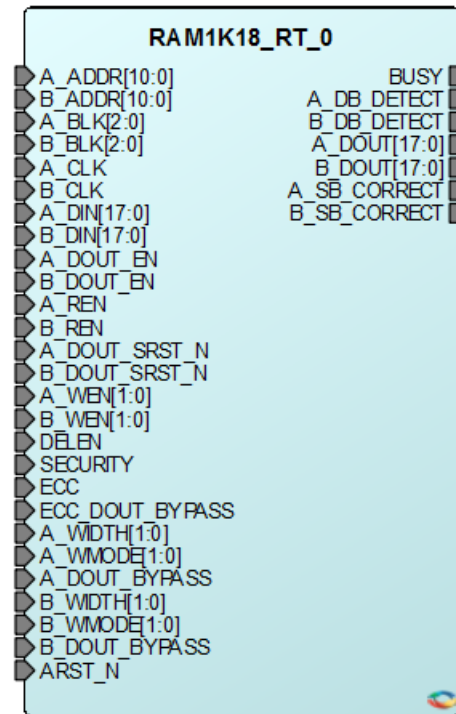
If the logical layer words do not fit cleanly into the hardware layer words, the most significant bit of the hardware layer words is not used and defaulted to zero. This is also done when the logical layer width is 1 in order to avoid having leftover memory at the end of the hardware block.

7 Appendix: Macro

7.1 LSRAM Macro

The LSRAM macro (RAM1K18_RT) in the Libero SoC IP macro library can be used directly to instantiate the LSRAM block in the design. The LSRAM block must be configured with appropriate values of the static signals. The following figure shows the LSRAM macro (RAM1K18_RT).

Figure 92 • LSRAM Configurator



Note: Static inputs are defined at design time and need to be tied to 0 or 1.

7.1.1 A_WIDTH and B_WIDTH

The following table lists the width/depth mode selections for each port. Two-port mode is in effect when the width of at least one port is 36, and A_WIDTH indicates the read width while B_WIDTH indicates the write width.

Table 28 • Depth × Width Mode Selection

Depth x Width	A_WIDTH/B_WIDTH
2Kx9, 2Kx12	00
1Kx18	01
512x36 (Two-port)	10

7.1.2 A_WEN and B_WEN

The following table lists the write/read control signals for each port. Two-port mode is in effect when the width of at least one port is 36, and read operation is always enabled.

Table 29 • Write/Read Operation Select

Depth x Width	A_WEN/B_WEN ¹	Result
2Kx9, 2Kx12	00	Perform a read operation
2Kx9, 2Kx12	11	Perform a write operation
1Kx18	01	Write [8:0]
	10	Write [17:9]
	11	Write [17:0]
512x36 (Two-port)	B_WEN[0] = 1	Write B_DIN[8:0]
	B_WEN[1] = 1	Write B_DIN[17:9]
	A_WEN[0] = 1	Write A_DIN[8:0]
	A_WEN[1] = 1	Write A_DIN[17:9]

1. A_WEN/B_WEN = 1 if ECC mode is used.

7.1.3 A_ADDR and B_ADDR

The following table lists the address buses for the two ports. 11 bits are needed to address the 2K independent locations in x9 mode. In wider modes, fewer address bits are used. The required bits are MSB justified and unused LSB bits must be tied to 0. A_ADDR is synchronized to A_CLK while B_ADDR is synchronized to B_CLK. A_ADDR provides the read-address while B_ADDR provides the write address.

Table 30 • Address Bus Used and Unused Bits

Depth x Width	A_ADDR/B_ADDR	
	Used Bits	Unused Bits (must be tied to 0)
2Kx9, 2Kx12	[10:0]	None
1Kx18	[10:1]	[0]
512x36 (Two-port)	[10:2]	[1:0]

7.1.4 A_DIN and B_DIN

The following table lists the data input buses for the two ports. The required bits are LSB justified and unused MSB bits must be tied to 0. For two-port mode when the write data width is more than 18-bits, A_DIN provides the MSB of the write data while B_DIN provides the LSB of the write-data.

Table 31 • Data Input Buses Used and Unused Bits

Depth x Width	A_DIN/B_DIN	
	Used Bits	Unused Bits (must be tied to 0)
2Kx9	[8:0]	[17:9]
2Kx12	[11:0]	[17:12]
1Kx18	[17:0]	None

Table 31 • Data Input Buses Used and Unused Bits (continued)

A_DIN/B_DIN		
Depth x Width	Used Bits	Unused Bits (must be tied to 0)
512x36 (Two-port)	A_DIN[17:0] is [35:18] B_DIN[17:0] is [17:0]	None

7.1.5 A_DOUT and B_DOUT

The following table lists the data output buses for the two ports. The required bits are LSB justified. A_DOUT provides the MSB of the read-data while B_DOUT provides the LSB of the read-data.

Table 32 • Data Output Buses Used and Unused Bits

A_DOUT/B_DOUT		
Depth x Width	Used Bits	Unused Bits
2Kx9	[8:0]	[17:9]
2Kx12	[11:0]	[17:12]
1Kx18	[17:0]	None
512x36 (Two-port)	A_DOUT[17:0] is [35:18] B_DOUT[17:0] is [17:0]	None

7.1.6 A_BLK and B_BLK

The following table lists the block-port select control signals for the two ports. A_BLK is synchronized by A_CLK while B_BLK is synchronized to B_CLK. Two-port mode is in effect when the width of at least one port is 36, and A_BLK controls the read operation while B_BLK controls the write operation.

Table 33 • Block-Port Select

Block-port Select Signal	Value	Result
A_BLK[2:0]	111	Perform read or write operation on Port A. In 36 width mode, perform a read operation from both ports A and B.
A_BLK[2:0]	Any one bit is 0	No operation in memory from Port A. Port A read-data will be forced to 0. In 36 width mode, the read-data from both ports A and B will be forced to 0.
B_BLK[2:0]	111	Perform read or write operation on Port B. In 36 width mode, perform a write operation to both ports A and B.
B_BLK[2:0]	Any one bit is 0	No operation in memory from Port B. Port B read-data will be forced to 0, unless it is a 36 width mode and write operation to both ports A and B is gated.

7.1.7 A_WMODE and B_WMODE

In true dual-port write mode:

- Logic 00 = Read-data port holds the previous value.
- All other values are reserved and must not be used.

7.1.8 A_CLK and B_CLK

All signals in ports A and B are synchronous to the corresponding port clock. All address, data, block-port select, write-enable and read-enable inputs must be set up before the rising edge of the clock. The read

or write operation begins with the rising edge. Two-port mode is in effect when the width of at least one port is 36, and A_CLK provides the read clock while B_CLK provides the write clock.

7.1.9 A_REN and B_REN

Enables read operation from the memory on the corresponding port.

Read-data Pipeline Register Control signals

A_DOUT_BYPASS and B_DOUT_BYPASS

A_DOUT_EN and B_DOUT_EN

A_DOUT_SRST_N and B_DOUT_SRST_N

Two-port mode is in effect when the width of at least one port is 36, and the A_DOUT register signals control the MSB of the read-data while the B_DOUT register signals control the LSB of the read-data.

7.1.10 ARST_N

Connects the Read-data pipeline registers to the global Asynchronous-reset signal.

7.1.11 ECC and ECC_DOUT_BYPASS

Controls ECC operation.

- ECC = 0: Disable ECC.
- ECC = 1, ECC_DOUT_BYPASS = 0: Enable ECC Pipelined.
 - During writes, ECC Pipelined mode inserts an additional clock cycle to encode the write data before it is actually written into the memory array.
 - During reads, ECC Pipelined mode inserts an additional clock cycle to decode the data read from memory before it is presented on DOUT.
- ECC = 1, ECC_DOUT_BYPASS = 1: Enable ECC Non-pipelined.

7.1.12 A_SB_CORRECT and B_SB_CORRECT

Output flag indicates single-bit correction was performed on the corresponding port.

7.1.13 A_DB_DETECT and B_DB_DETECT

Output flag indicates double-bit detection was performed on the corresponding port.

7.1.13.1 DELEN

Enable Single-event Transient mitigation.

7.1.13.2 SECURITY

Control signal, when 1 locks the entire RAM1K18_RT memory from being accessed by the SII.

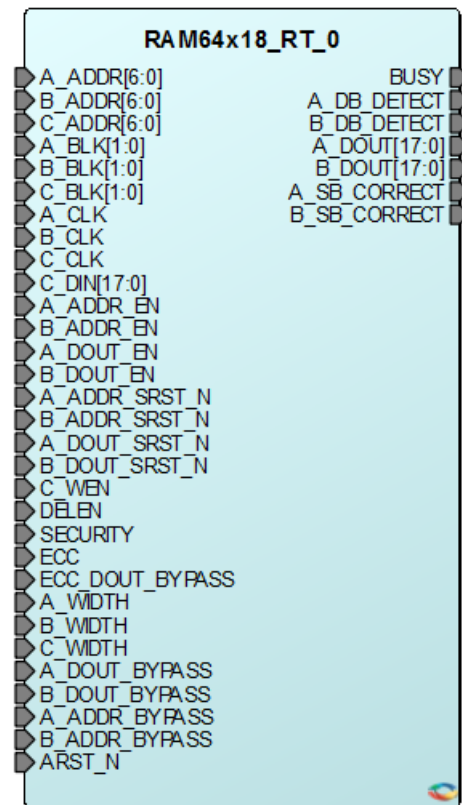
7.1.13.3 BUSY

This output indicates that the RAM1K18_RT memory is being accessed by the SII.

7.2 μ SRAM Macro

The μ SRAM macro (RAM64 \times 12) in Libero SoC can be used directly to instantiate μ SRAM in the design. μ SRAM must be configured correctly with appropriate values provided to the static signals before instantiating in the design. Instantiating μ SRAM primitives in a design is not recommended. See Inserting an μ SRAM Memory Macro for the recommended methods of instantiating memory into a user design. The following figure shows the μ SRAM macro (RAM64 \times 12) available in the Libero SoC macro library.

Figure 93 • μSRAM Configurator



7.2.1 A_WIDTH, B_WIDTH, and C_WIDTH

The following table lists the width/depth mode selections for each port.

Table 34 • Width/Depth Mode Selection

Depth x Width	A_WIDTH/B_WIDTH/C_WIDTH
128x9, 128x12	0
64x16, 64x18	1

7.2.2 C_WEN

This is the write-enable signal for port C.

7.2.3 A_ADDR, B_ADDR, and C_ADDR

The following table lists the address buses for each port. 7 bits are required to address 128 independent locations in x9 mode. In wider modes, fewer address bits are used. The required bits are MSB justified and unused LSB bits must be tied to 0.

Table 35 • Address Buses Used and Unused Bits

A_ADDR/B_ADDR/C_ADDR		
Depth x Width	Used Bits	Unused Bits (must be tied to 0)
128x9	[6:0]	None
64x18	[6:1]	[0]

7.2.4 C_DIN

The following table lists the write-data input for port C. The required bits are LSB justified and unused MSB bits must be tied to 0.

Table 36 • Data Input Bus Used and Unused Bits

C_DIN		
Depth x Width	Used Bits	Unused Bits (must be tied to 0)
128x9	[8:0]	[17:9]
128x12	[11:0]	[17:12]
64x18	[17:0]	None

7.2.5 A_DOUT and B_DOUT

The following table lists the read-data output buses for ports A and B. The required bits are LSB justified.

Table 37 • Data Output Used and Unused Bits

A_DOUT/B_DOUT		
Depth x Width	Used Bits	Unused Bits
128x9	[8:0]	[17:9]
128x12	[11:0]	[17:12]
64x18	[17:0]	None

7.2.6 A_BLK, B_BLK, and C_BLK

The following table lists the block-port select control signals for the ports.

Table 38 • Block-Port Select

Block-port Select Signal	Value	Result
A_BLK[1:0]	Any one bit is 0	Port A is not selected and its read-data will be forced to zero.
	11	Perform read operation from port A.
B_BLK[1:0]	Any one bit is 0	Port B is not selected and its read-data will be forced to zero.
	11	Perform read operation from port B.
C_BLK[1:0]	Any one bit is 0	Port C is not selected.
	11	Perform write operation to port C.

7.2.7 C_CLK

All signals on port C are synchronous to this clock signal. All write-address, write-data, C block-port select and write enable inputs must be set up before the rising edge of the clock. The write operation begins with the rising edge.

Read-address and Read-data Pipeline Register Control signals

A_DOUT_BYPASS, A_ADDR_BYPASS, B_DOUT_BYPASS and B_ADDR_BYPASS

A_DOUT_EN, A_ADDR_EN, B_DOUT_EN and B_ADDR_EN

A_DOUT_SRST_N, A_ADDR_SRST_N, B_DOUT_SRST_N and B_ADDR_SRST_N

The following table lists the functionality of the control signals on the A_ADDR, B_ADDR, A_DOUT and B_DOUT registers.

Table 39 • Truth Table for A_ADDR, B_ADDR, A_DOUT, and B_DOUT Registers

ARST_N	_BYPASS	_CLK	_EN	_SRST_N	D	Q _{n+1}
0	X	X	X	X	X	0
1	0	Not rising	X	X	X	Q _n
1	0	↑	0	X	X	Q _n
1	0	↑	1	0	X	0
1	0	↑	1	1	D	D
1	1	X	X	X	D	D

7.2.8 ARST_N

Connects the read-address and read-data pipeline registers to the global Asynchronous-reset signal.

7.2.9 ECC and ECC_DOUT_BYPASS

Controls ECC operation.

- ECC = 0: Disable ECC.
- ECC = 1, ECC_DOUT_BYPASS = 0: Enable ECC Pipelined.
 - ECC Pipelined mode inserts an additional clock cycle to Read-data.
- ECC = 1, ECC_DOUT_BYPASS = 1: Enable ECC Non-pipelined.

7.2.10 A_SB_CORRECT and B_SB_CORRECT

Output flag indicates single-bit correction was performed on the corresponding port.

7.2.11 A_DB_DETECT and B_DB_DETECT

Output flag indicates double-bit detection was performed on the corresponding port.

7.2.11.1 DELEN

Enable Single-event Transient mitigation.

7.2.11.2 SECURITY

Control signal, when 1 locks the entire RAM64x18_RT memory from being accessed by the SII.

7.2.11.3 BUSY

This output indicates that the RAM64x18_RT memory is being accessed by the SII.

7.3 Math Block Macro

18 bit x 18 bit multiply-accumulate MACC block. The math block can accumulate the current multiplication product with a previous result, a constant, a dynamic value, or a result from another math block. Each math block can also be configured to perform a Dot-product operation. All the signals of the math block (except CDIN and CDOU) have optional registers.

Figure 94 • Math Block Configurator



Table 40 • Ports List of Math Block Configurator

Pin Name	Pin Direction	Type	Polarity	Description
DOTP	Input	Static	Active high	Dot-product mode. When DOTP = 1, MACC block performs Dotproduct of two pairs of 9-bit operands. When DOTP = 0, it is called the normal mode.
SIMD	Input	Static		Reserved. Must be 0.
CLK[1:0]	Input	Dynamic	Rising edge	Input clocks. CLK[1] is the clock for A[17:9], B[17:9], C[43:18], P[43:18], OVFL_CARRYOUT, ARSHFT17, CDSEL, FDBKSEL and SUB registers. CLK[0] is the clock for A[8:0], B[8:0], C[17:0], CARRYIN and P[17:0]. In normal mode, ensure CLK[1] = CLK[0].
A[17:0]	Input	Dynamic	Active high	Input data A.
A_BYPASS[1:0]	Input	Static	Active high	Bypass data A registers. A_BYPASS[1] is for A[17:9]. Connect to 1, if not registered. A_BYPASS[0] is for A[8:0]. Connect to 1, if not registered. In normal mode, ensure A_BYPASS[0] = A_BYPASS[1].
A_ARST_N[1:0]	Input	Dynamic	Active low	Asynchronous reset for data A registers. Connect both A_ARST_N[1] and = A_ARST_N[0] to 1 or to the global Asynchronous reset of the design
A_SRST_N[1:0]	Input	Dynamic	Active low	Synchronous reset for data A registers. A_SRST_N[1] is for A[17:9]. Connect to 1, if not registered. A_SRST_N[0] is for A[8:0]. Connect to 1, if not registered. In normal mode, ensure A_SRST_N[1] = A_SRST_N[0].
A_EN[1:0]	Input	Dynamic	Active high	Enable for data A registers. A_EN[1] is for A[17:9]. Connect to 1, if not registered. A_EN[0] is for A[8:0]. Connect to 1, if not registered. In normal mode, ensure A_EN[1] = A_EN[0].
B[17:0]	Input	Dynamic	Active high	Input data B.
B_BYPASS[1:0]	Input	Static	Active high	Bypass data B registers. B_BYPASS[1] is for B[17:9]. Connect to 1, if not registered. B_BYPASS[0] is for B[8:0]. Connect to 1, if not registered. In normal mode, ensure B_BYPASS[0] = B_BYPASS[1].
B_ARST_N[1:0]	Input	Dynamic	Active low	Asynchronous reset for data B registers. In normal mode, ensure to connect both B_ARST_N[1] and B_ARST_N[0] to 1 or to the global Asynchronous reset of the design.

Table 40 • Ports List of Math Block Configurator (continued)

Pin Name	Pin Direction	Type	Polarity	Description
B_SRST_N[1:0]	Input	Dynamic	Active low	Synchronous reset for data B registers. B_SRST_N[1] is for B[17:9]. Connect to 1, if not registered. B_SRST_N[0] is for B[8:0]. Connect to 1, if not registered. In normal mode, ensure B_SRST_N[1] = B_SRST_N[0].
B_EN[1:0]	Input	Dynamic	Active high	Enable for data B registers. B_EN[1] is for B[17:9]. Connect to 1, if not registered. B_EN[0] is for B[8:0]. Connect to 1, if not registered. In normal mode, ensure B_EN[1] = B_EN[0].
P[43:0]	Output		Active high	Result data. Normal mode $P = D + (\text{CARRYIN} + C) + (A * B)$, when SUB = 0 $P = D + (\text{CARRYIN} + C) - (A * B)$, when SUB = 1 Dot-product mode $P = D + (\text{CARRYIN} + C) + 512 * ((AL * BH) + (AH * BL))$, when SUB = 0 $P = D + (\text{CARRYIN} + C) - 512 * ((AL * BH) + (AH * BL))$, when SUB = 1 Notation: AL = A[8:0], AH = A[17:9] BL = B[8:0], BH = B[17:9] See Table 43, page 115 to see how operand D is obtained from P, CDIN or 0.
OVFL_CARRYOUT	Output		Active high	Overflow or CarryOut Overflow when OVFL_CARRYOUT_SEL = 0 $\text{OVFL_CARRYOUT} = (\text{SUM}[45] \wedge \text{SUM}[44]) \mid (\text{SUM}[44] \wedge \text{SUM}[43])$ CarryOut when OVFL_CARRYOUT_SEL = 1 $\text{OVFL_CARRYOUT} = C[43] \wedge D[43] \wedge \text{SUM}[44]$
P_BYPASS[1:0]	Input	Static	Active high	Bypass result P registers. P_BYPASS[1] is for P[43:18] and OVFL_CARRYOUT. Connect to 1, if not registered. P_BYPASS[0] is for P[17:0]. Connect to 1, if not registered. In normal mode, ensure P_BYPASS[0] = P_BYPASS[1].
P_ARST_N[1:0]	Input	Dynamic	Active low	Asynchronous reset for result P registers. Connect both P_ARST_N[1] and P_ARST_N[0] to 1 or to the global Asynchronous reset of the design

Table 40 • Ports List of Math Block Configurator (continued)

Pin Name	Pin Direction	Type	Polarity	Description
P_SRST_N[1:0]	Input	Dynamic	Active low	Synchronous reset for result P registers. P_SRST_N[1] is for P[43:18] and OVFL_CARRYOUT. Connect to 1, if not registered. P_SRST_N[0] is for P[17:0]. Connect to 1, if not registered. In normal mode, ensure P_SRST_N[1] = P_SRST_N[0].
P_EN[1:0]	Input	Dynamic	Active high	Enable for result P registers. P_EN[1] is for P[43:18] and OVFL_CARRYOUT. Connect to 1, if not registered. P_EN[0] is for P[17:0]. Connect to 1, if not registered. In normal mode, ensure P_EN[1] = P_EN[0].
CDOUT[43:0]	Output	Cascade	Active high	Cascade output of result P. CDOUT is the same as P. The entire bus must either be dangling or drive an entire CDIN of another MACC block in cascaded mode.
CARRYIN	Input	Dynamic	Active high	CarryIn for operand C.
C[43:0]	Input	Dynamic	Active high	Routed input for operand C. In Dot-product mode, connect C[8:0] to the CARRYIN.
C_BYPASS[1:0]	Input	Static	Active high	Bypass data C registers. C_BYPASS[1] is for C[43:18]. Connect to 1, if not registered. C_BYPASS[0] is for C[17:0] and CARRYIN. Connect to 1, if not registered. In normal mode, ensure C_BYPASS[0] = C_BYPASS[1].
C_ARST_N[1:0]	Input	Dynamic	Active low	Asynchronous reset for data C registers. Connect both C_ARST_N[1] and C_ARST_N[0] to 1 or to the global Asynchronous reset of the design.
C_SRST_N[1:0]	Input	Dynamic	Active low	Synchronous reset for data C registers. C_SRST_N[1] is for C[43:18]. Connect to 1, if not registered. C_SRST_N[0] is for C[17:0] and CARRYIN. Connect to 1, if not registered. In normal mode, ensure C_SRST_N[1] = C_SRST_N[0].
C_EN[1:0]	Input	Dynamic	Active high	Enable for data C registers. C_EN[1] is for C[43:18]. Connect to 1, if not registered. C_EN[0] is for C[17:0] and CARRYIN. Connect to 1, if not registered. In normal mode, ensure C_EN[1] = C_EN[0].

Table 40 • Ports List of Math Block Configurator (continued)

Pin Name	Pin Direction	Type	Polarity	Description
CDIN[43:0]	Input	Cascade	Active high	Cascaded input for operand D. The entire bus must be driven by an entire CDOUT of another MACC block. In Dotproduct mode the CDOUT must also be generated by a MACC block in Dot-product mode. See Table 43 , page 115 to see how CDIN is propagated to operand D.
ARSHFT17	Input	Dynamic	Active high	Arithmetic right-shift for operand D. When asserted, a 17-bit arithmetic right-shift is performed on operand D going into the accumulator. See Table 43 , page 115 to see how operand D is obtained from P, CDIN or 0.
ARSHFT17_BYPASS	Input	Static	Active high	Bypass ARSHFT17 register. Connect to 1, if not registered.
ARSHFT17_AL_N	Input	Dynamic	Active low	Asynchronous load for ARSHFT17 register. Connect to 1 or to the global Asynchronous reset of the design. When asserted, ARSHFT17 register is loaded with ARSHFT17_AD.
ARSHFT17_AD	Input	Static	Active high	Asynchronous load data for ARSHFT17 register.
ARSHFT17_SL_N	Input	Dynamic	Active low	Synchronous load for ARSHFT17 register. Connect to 1, if not registered. See Table 41 , page 115.
ARSHFT17_SD_N	Input	Static	Active low	Synchronous load data for ARSHFT17 register. See Table 41 , page 115.
ARSHFT17_EN	Input	Dynamic	Active high	Enable for ARSHFT17 register. Connect to 1, if not registered. See Table 41 , page 115.
CDSEL	Input	Dynamic	Active high	Select CDIN for operand D. When CDSEL = 1, propagate CDIN. When CDSEL = 0, propagate 0 or P depending on FDBKSEL. See Table 41 , page 115 to see how operand D is obtained from P, CDIN or 0.
CDSEL_BYPASS	Input	Static	Active high	Bypass CDSEL register. Connect to 1, if not registered.
CDSEL_AL_N	Input	Dynamic	Active low	Asynchronous load for CDSEL register. Connect to 1 or to the global Asynchronous reset of the design. When asserted, CDSEL register is loaded with CDSEL_AD.
CDSEL_AD	Input	Static	Active high	Asynchronous load data for CDSEL register.
CDSEL_SL_N	Input	Dynamic	Active low	Synchronous load for CDSEL register. Connect to 1, if not registered. See Table 41 , page 115.
CDSEL_SD_N	Input	Static	Active low	Synchronous load data for CDSEL register. See Table 41 , page 115.
CDSEL_EN	Input	Dynamic	Active high	Enable for CDSEL register. Connect to 1, if not registered. See Table 41 , page 115.

Table 40 • Ports List of Math Block Configurator (continued)

Pin Name	Pin Direction	Type	Polarity	Description
FDBKSEL	Input	Dynamic	Active high	Select the feedback from P for operand D. When FDBKSEL = 1, propagate the current value of result P register. Ensure P_BYPASS[1] = 0 and CDSEL = 0. When FDBKSEL = 0, propagate 0. Ensure CDSEL = 0. See Table 43 , page 115 to see how operand D is obtained from P, CDIN or 0.
FDBKSEL_BYPASS	Input	Static	Active high	Bypass FDBKSEL register. Connect to 1, if not registered.
FDBKSEL_AL_N	Input	Dynamic	Active low	Asynchronous load for FDBKSEL register. Connect to 1 or to the global Asynchronous reset of the design. When asserted, FDBKSEL register is loaded with FDBKSEL_AD.
FDBKSEL_AD	Input	Static	Active high	Asynchronous load data for FDBKSEL register.
FDBKSEL_SL_N	Input	Dynamic	Active low	Synchronous load for FDBKSEL register. Connect to 1, if not registered. See Table 41 , page 115.
FDBKSEL_SD_N	Input	Static	Active low	Synchronous load data for FDBKSEL register. See Table 41 , page 115.
FDBKSEL_EN	Input	Dynamic	Active high	Enable for FDBKSEL register. Connect to 1, if not registered. See Table 41 , page 115.
SUB	Input	Dynamic	Active high	Subtract operation.
SUB_BYPASS	Input	Static	Active high	Bypass SUB register. Connect to 1, if not registered.
SUB_AL_N	Input	Dynamic	Active low	Asynchronous load for SUB register. Connect to 1 or to the global Asynchronous reset of the design. When asserted, SUB register is loaded with SUB_AD.
SUB_AD	Input	Static	Active high	Asynchronous load data for SUB register.
SUB_SL_N	Input	Dynamic	Active low	Synchronous load for SUB register. Connect to 1, if not registered. See Table 41 , page 115.
SUB_SD_N	Input	Static	Active low	Synchronous load data for SUB register. See Table 41 , page 115.
SUB_EN	Input	Dynamic	Active high	Enable for SUB register. Connect to 1, if not registered. See Table 41 , page 115.

Table 41 • Truth Table for Control Registers ARSHFT17, CDSEL, FDBKSEL, and SUB

_AL_N	_AD	_BYPASS	_CLK	_EN	_SL_N	_SD_N	D	Q _{n+1}
0	AD	X	X	X	X	X	X	AD
1	X	0	Not rising	X	X	X	X	Q _n
1	X	0	↑	0	X	X	X	Q _n
1	X	0	↑	1	0	SD _n	X	!SD _n
1	X	0	↑	1	1	X	D	D
1	X	1	X	0	X	X	X	Q _n
1	X	1	X	1	0	SD _n	X	!SD _n
1	X	1	X	1	1	X	D	D

Table 42 • Truth Table - Data Registers A, B, C, CARRYIN, P, and OVFL_CARRYOUT

_ARST_N	_BYPASS	_CLK	_EN	_SRST_N	D	Q _{n+1}
0	X	X	X	X	X	0
1	0	Not rising	X	X	X	Q _n
1	0	↑	0	X	X	Q _n
1	0	↑	1	0	X	0
1	0	↑	1	1	D	D
1	1	X	0	X	X	Q _n
1	1	X	1	0	X	0
1	1	X	1	1	D	D

Table 43 • Truth Table - Propagating Data to Operand D

FDBKSEL	CDSEL	ARSHFT17	Operand D
0	0	X	44'b0
X	1	0	CDIN[43:0]
X	1	1	{{17{CDIN[43]}},CDIN[43:17]}
1	0	0	P[43:0]
1	0	1	{{17{P[43]}},P[43:17]}

8 Glossary

8.1 Acronyms

CCC

Clock conditioning circuits

DDRIO

Double data rate input output

ECC

Error correction code

ESD

Electrostatic discharge protection

FDDR

Controller for external DDR memory

HSTL

High-speed transceiver logic

IOA

Input output analog

IOD

Input output digital

LPDDR

Low power double data rate memory

LPE

Low power exit

LSB

Least significant bit

LSRAM

Large static random access memory

LVDS

Bus LVDS

LVPECL

Low-voltage positive emitter coupled logic

LVTTL

Low voltage transistor transistor logic

MLVDS

Multipoint LVDS

MSB

Most significant bit

MSIO

Multi-standard I/O

MVN

MultiView Navigator

ODT

On-die termination

RSDS

Reduced swing differential signaling

SerDes

Serializer/deserializer

SSTL

Stub series terminated logic

STMR

Self-corrected triple module redundancy

μSRAM

Micro static random access memory

8.2 Terminology

Bus Keeper

Holds the signal on an I/O pin at its last driven state.

Clusters

Clusters are formed by grouping a certain number of logic elements and interconnecting them. This is related to the clustered routing architecture of the RTG4 FPGA fabric.

Dual-Port Mode

SRAM with two independent ports through which both read and write operation can be done.

Flow-Through Read

A read operation performed with the output not being registered by the output pipeline registers.

Hot Insertion

Capability to connect I/O to external circuitry even after power-up.

I/O Cluster

I/O cluster is formed by grouping either three or four I/O modules.

I/O Module

The logic element consists of flip-flops and routing multiplexers. This logic element interfaces the user I/Os to fabric routing.

Inference

Using RTL to infer mathblocks

Inter-Cluster Routing

Inter-cluster routing refers to routing resources between various types of clusters.

Interface Cluster

An interface cluster is formed by grouping 12 interface logic elements.

Interface Logic

The logic element consists of a 4-input LUT and a STMR-flip-flop. This logic element interfaces the hard macros (LSRAMs, uSRAMs, and mathblocks) to fabric routing.

Intra-Cluster Routing

Intra-cluster routing refers to routing resources existing inside a specific cluster.

Logic Cluster

A logic cluster is formed by grouping 12 logic elements.

Logic Element

The basic logic element in the RTG4 FPGA fabric, consisting of a 4-input LUT, a D-flip-flop, and a dedicated carry chain.

Low Power Exit

Logic for the chip to come out from low power state.

Multi-Channeling

Multi-threading done for a chain of mathblocks

Multi-Threading

Using a math block for performing more than one computation by time multiplexing it.

Pipelined Operation

The mode of operation where the mathblock output is registered at the pipeline registers.

Pipelined Read

A read operation performed with the output being registered by the output pipeline registers.

Simple Write

A write operation in which the data written does not appear on the SRAM output ports.

STMR

Self-corrected triple module redundancy

Transparent Mode

Non-registered/Non-pipelined mode

Two-Port Mode

SRAM with two ports, one dedicated to read operations and the other dedicated to write operations.